"Hardware Implementation of Discrete Cosine Transform "

Report of the project carried out at Raman Research Institute (RRI), Bangalore, submitted in partial fulfillment of the requirements for the award of degree of

Bachelor of Engineering

in

Electronics & Communication

of

Visveswaraiah Technological University, Belgaum.

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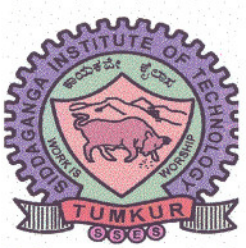

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(Affiliated to Visveswaraiah Technological University)

Department of Electronics & Communication

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is a bona fide work of

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Carried out under my guidance at the

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This project is in partial fulfillment of the requirement for the award of Bachelor's Degree in Electronics & Communication Engineering by the Visveswaraiah Technological University during the academic year 2001-2002.

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ABSTRACT

This project aims at implementing Discrete Cosine Transform in Hardware. DCT stands for Discrete Cosine Transform. DCT transforms the spatial information of picture to frequency domain where it can be variably quantised to obtain compression. DCT is chosen as it is one of the optimum transforms for image compression and DCT is the heart of many Image compression standards such as JPEG, ISO-MPEG-1 and MPEG-2.

The implementation is carried out using bit serial architecture & distributed arithmetic, which eliminates the direct use of multiplication in the algorithm. Further the algorithm chosen satisfies the scanning rate of NTSC standard television and thus can be used for video applications as well.

ACKNOWLEDGEMENTS

ACKNOWLEDGEMENTS

With respectful pranams to His Holiness **Dr. Sree Sree Sivakumara Swamigalu**, revered President of Sree Siddaganga Education Society, Sree Siddaganga Math, we express our gratitude at his lotus feet for his blessings and giving us the opportunity to have a sound base in Engineering there by helping us to fulfill our cherished desire of becoming Electronics Engineers.

The satisfaction and euphoria that accompany the successful completion of any task would be incomplete without the mention of the people who made it possible, whose constant guidance, help and encouragement crowned our efforts with success. We consider it our privilege to express our gratitude and respect to all those who guided and inspired us in the successful completion of the project.

It gives us immense pleasure to express our deep sense of gratitude to our beloved Principal **Dr. M. N. Channabasappa**, M.A, Ph.D., whose words of advice has always been a constant source of inspiration for us.

We would like to express our heartfelt thanks to the Head of the Department of Electronics and Communication Engineering, **Prof. G. K. Suresh**, M.Sc. (Engg.), MISTE, for his valuable advice & encouragement.

We are grateful to the Staff at Raman Research Institute, Bangalore for giving us an opportunity to carry out our project work at their esteemed organization and providing us the most conducive environment. Our special thanks to Dr. G. S. Ranganath who directed us to Dr. T. N. Ruckmongathan who was kind enough to give us this project.

We are indeed indebted to **Dr T. N. Ruckmongathan**, our guide at RRI for his invaluable advice and suggestions. We are very grateful for the technical advice and the practical suggestions provided by him, which helped us to complete the project successfully.

We would like to thank **Mr. K. G. Pani Kumar**, Research student and **A.R.Shashidhara,** Technical Assistant of RRI for giving us the right directions and guidance during the course of the project.

We were fortunate enough to have **Mr. R. KumarSwamy**, M.E, Lecturer, Department of E & C, as our guide who has helped us at each and every moment of the project by providing valuable suggestions & advice. We express our utmost thanks to him.

We would also wish to thank the members of the teaching staff for providing us the right technical foundation, which came handy to carry out our project work successfully.

Finally we want to express our sincere thanks to all those who were directly or indirectly helpful in carrying out the project.

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INTRODUCTION

Chapter 1

INTRODUCTION

"A Picture is worth a Thousand Words"

Images convey more information than written words. An image is described as a two-dimensional function f (x, y) of the intensity of reflected (or transmitted) light from its surface. Since light is a form of energy, f (x, y) must be non-zero & finite i.e.

$$0 < f(x, y) < \infty.$$

In order to be in a form suitable for computer processing, this image function f(x, y) must be sampled in two-dimensions (x, y) and its intensity value is also quantized (say using 8 bits). Digitization of spatial co-ordinates (x, y) is referred to as image sampling, while amplitude digitization is called gray level quantization. The image so obtained may be considered as a matrix whose row and column indices identify a point in the image and the corresponding matrix element value identifies the gray level at that point .The elements of such a array are called image elements, picture elements, pixels or pels.

The digital image obtained from the quantization of a real image is fed into a digital computer for processing .The term Digital Image Processing generally refers to processing of two-dimensional picture by a digital computer. A block diagram of a general image processing system is as shown in fig.1.1.

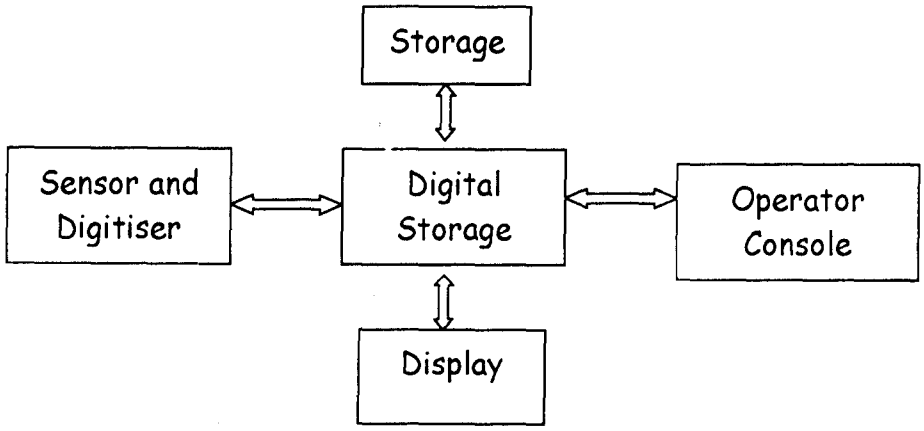


Fig 1.1 *General purpose Image Processing System*

Digital Image Processing has a broad spectrum of applications such as remote sensing via satellite, image transmission and storage application, medical imaging, acoustic image processing, robotics and many more. Apart from the above mentioned applications, image processing encounters certain classes of problems such as image representation, image enhancement, image restoration, image analysis, image reconstruction, image data compression. Image data compression is considered in this project.

The size of the image is very large and hence its storage would require enormous amount of memory. Storage and/or transmission of data generated by typical television and other image sources require large capacity and/or bandwidth, which could be very expensive. Data compression techniques are used to reduce the number of bits required to store or transmit images without any appreciable loss of information. Image transmission is useful in application like TV, remote sensing, teleconferencing, etc. while image storage is required mostly for educational purposes, medical images used in patient monitoring system etc.

Because of their wide spread applications compression of image data is of great importance.

A typical block diagram of an Image Compression system is as shown in Fig.1.2

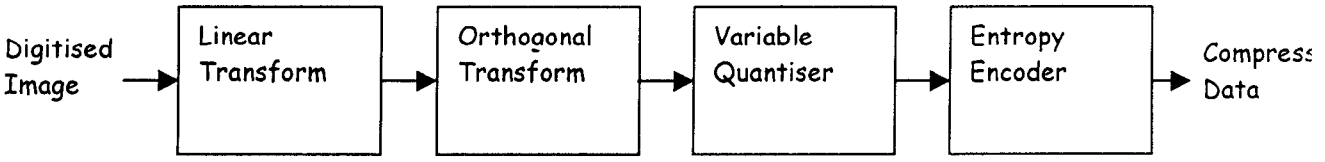


Fig.1.2 *Block diagram of general image compression system*

The Linear Transform involves conversion of the color space (the RGB representation of the input image) to a luminance and chrominance space (such as the YCbCr representation) .Y represents the luminance while Cb and Cr are the chrominance components. The orthogonal transform is the one which converts the information into frequency domain and the co-efficients obtained from the transform are quantized and encoded using an entropy encoder which may use Run length encoding (RLE), Huffman coding or any other encoding scheme that is efficient. The first block is used in the case of color images and is not necessary for a monochrome image.

The Orthogonal Transform is one of the important steps in compression of images. Discrete Cosine Transform (DCT) is widely used and accepted orthogonal transform for image compression. This is because DCT forms the best approximation to Karhunen-Loeve transform (KLT).

Further KLT is considered as the optimum transform for image compression for the following reasons:

1. It packs most of theenergy in the least number of elements in the transform.
2. It minimizes the total entropy of the sequence.
3. It completely decorrelates the elements in the original signal.

KLT is not used for implementation purposes, because the computation time required for the calculation of co-efficients is large and further there is no fast approximation for KLT. Thus DCT based image coding is the basis for most of the image and video compression standards. The basic computation in a DCT based system is the transformation of an N x N image block from spatial domain to DCT domain. For image compression standards, N=8. This is because from hardware or software implementation viewpoint, an 8 x 8 blocksize doesn't impose significant memory requirements; furthermore, the computational complexity of an 8 x 8 DCT is manageable on most computing platforms.

The DCT is a discrete version of Fourier cosine series. The DCT of a signal can be derived, by applying the Fourier transform to a discrete signal that is symmetrically extended about the origin. The symmetric extension of the discrete signal can be done in several ways. Each symmetric extension gives rise to different type of transform.

In total, there are four types of transform and they are as follows

Type-I DCT: This type involves symmetric extension of the signal. The defining equation for Type I DCT is as shown below

$$X^{C1}[k] = \{2/(N-1)\}\ 1/2\ \Sigma\ a[k]\ a[n]\ x[n]\ \text{Cos}\{\Pi\ n\ k/\ (N-1)\}$$

where n=0,1,2,...N-1,k=0,1,2,....7 for 8 point DCT

$$a[n]=\sqrt{1/2} \text{ for } 0\leq n\leq N-1$$

$$=1 \text{ otherwise}$$

Type-II DCT: The Type II DCT is based on non-minimal symmetrization of signal.The defining equation for Type I DCT is as shown below.

$$X^{C2}[k]= (2/N)1/2\ \Sigma\ b[k]\ x[n]\ \text{Cos}\{\ \Pi\ k\ (n+0.5)\ /N)\ \}$$

where n=0,1,2,...N-1,k=0,1,2,....7 for 8 point DCT

Type-III DCT: Type-III DCT is defined by the equation

$$X^{C3}[k]= 1/2\ \Sigma\ x[n]\ Cos\{\ \Pi\ k\ (2n+1)\ /2N)\ \}$$

where n=0,1,2,...N-1,k=0,1,2,....7 for 8 point DCT

Type-IV DCT: The Type IV DCT is like DCT-I symmetric. Its construction is similar to that of DCT-II. It is defined by the following equation

$$X^{C4}[k]=(2/N)1/2\ \Sigma\ x[n]\ Cos\ \{\ \Pi\ (k+0.5)\ (n+0.5)\ /N)\ \}$$

where n=0,1,2,...N-1,k=0,1,2,....7 for 8 point DCT

Of the four types of DCTs, DCT-II is more commonly used than the others, since it is even symmetric. The odd symmetric DCT involves computing an odd length, which is not very convenient while using fast algorithms and during implementation.

DCT fares better over DFT, which is one of the most frequently and widely used.The basis functions for DFT and DCT are as shown in fig 1.3 and fig 1.4 respectively. DCT is used in several signal-processing applications for the following reasons

1. An N-point DFT produces 2N co-efficients at the output (N real and N imaginary) while an N-point DCT produces N co-efficients (all the N co-efficients are real).

2. The DFT co-efficients are both real and complex in nature, which make them occupy more space, while the DCT co-efficients are real only.

3. The basis functions in DFT algorithms are sine and cosine resulting in complex co-efficients, while the basis functions in DCT algorithms are only cosines resulting in real co-efficients

Thus DCT proves to be a better approach for frequency analysis of images without the need to handle complex numbers.

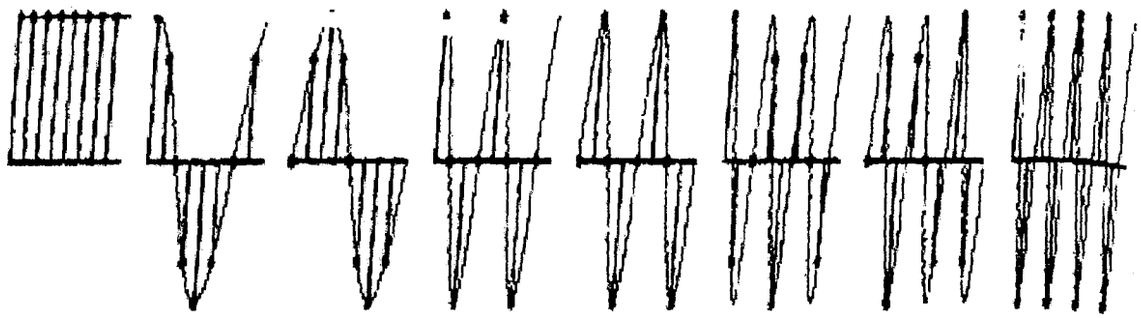


Fig.1.3.*Basis functions for the Discrete Fourier Transform*

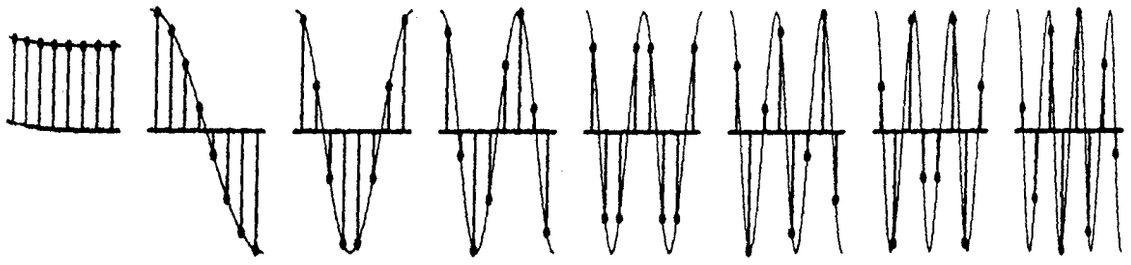


Fig.1.4.*Basis functions for the Discrete Cosine Transform*

The main point of comparison between the DFT with DCT is the amount of computation necessary. The multiplications involved in DFT computations are simpler compared to that of DCT i.e. DCT is harder to compute. Inspite of this there is good reason for using it. The number of DCT co-efficients required to get a good approximation of a typical signal is far less than that required by DFT co-efficients. The primary reason for performing the transform is to crudely quantize the high frequency components, which are small in magnitude than the low frequency components. Fig1.5 shows the reconstruction of an original ramp signal after performing DFT or DCT, then truncating the co-efficients, taking the inverse transform of the truncated co-efficients.

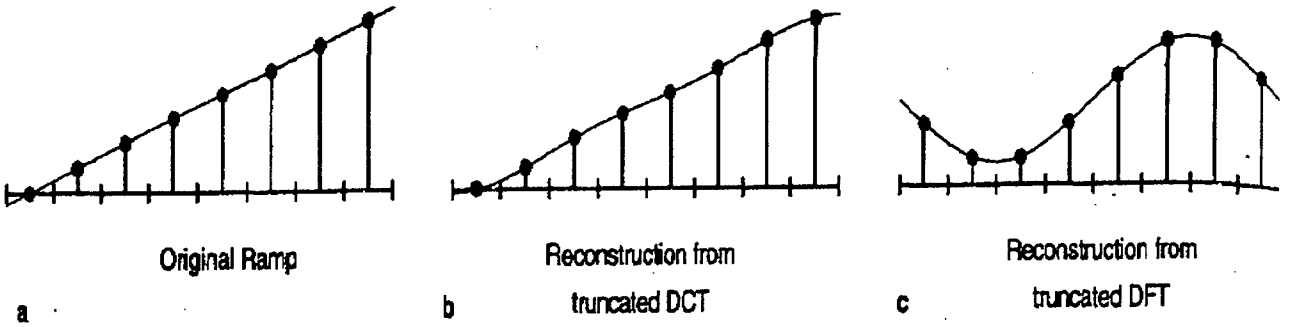


Fig.1.5. *A comparison of the accuracy of the truncated & reconstructed DCT and DFT for the ramp signal*

S_x	DCT	DFT	Truncated DCT	IDCT	Truncated DFT	IDFT
0	356.38	356.38	356.38	2.19	356.38	90.00
36	-213.92	-72.00	-213.92	31.95	-72.00	39.39
72	0.00	-173.82	0.00	73.46	-173.82	39.09
108	-24.24	-72.00	-24.24	110.11	0.00	90.00
144	0.00	-72.00	0.00	141.089	0.00	162.00
180	-7.23	-72.00	0.00	178.54	0.00	212.91
216	0.00	-29.82	0.00	220.05	0.00	212.91
252	-1.83	-50.91	0.00	249.81	0.00	162.00

Table.1.1. *Signal, transform, truncated, reconstructed values for the ramp signal*

It is evident from figure.1.5 and table 1.1 that on choosing DCT the high frequency components can be ignored without much error being introduced. This is more evident from fig.1.6

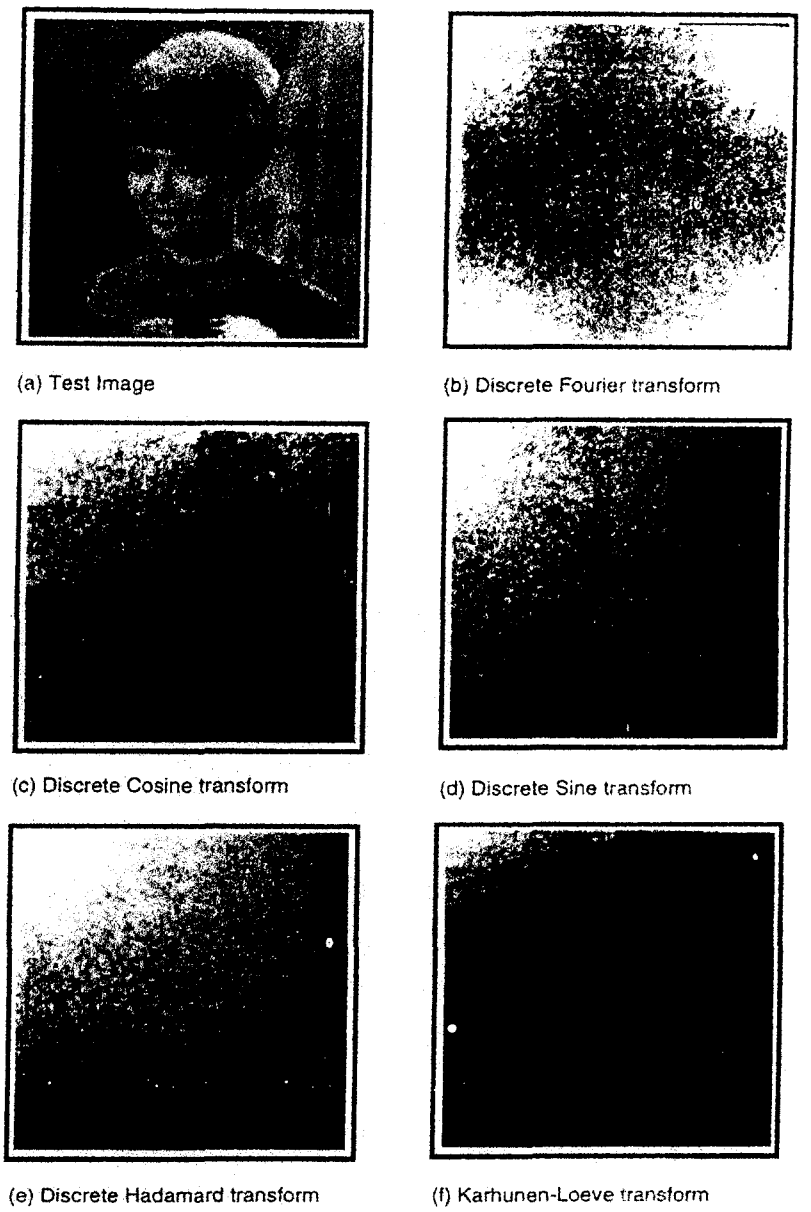


Fig1.6.Comparison of energy compaction of different transforms for a picture

The Discrete Cosine Transform is one of many transforms that take input and transforms it into a linear combination of weighted basis functions. These basis functions are commonly signals, like sine waves.

The 2-D Discrete Cosine Transform is just a 1-D DCT applied twice, once in the X direction, and again in the Y direction. One can imagine the computational complexity of doing so for a large image. Let us consider the number of operations involved in the computation of an N-point 1-D DCT. It requires (NxN) multiplications and Nx(N-1) additions. Moreover, implementation of multiplication in hardware is very costly in terms of the computation time required. So, many fast algorithms that reduce or avoid multiplications have been proposed. First let's see the how DCT is defined. By knowing the basic definition of the Discrete Cosine Transform, one can make suitable changes/approximations such that the desired equation can be realized without much compromise on the error and in a lesser time than that is necessary for the original equation. This is the most common way in which fast algorithms are proposed.

N point 1-D DCT is defined by the equation

$$X(k) = \sum_{n=0}^{N-1} x(n) \cos[k\pi(2n+1)/2N]; \quad 0 \le k \le N-1$$

x(n) represents the input sample values of the signal whose transform is to be taken.
X(k) represents the corresponding co-efficients of the input signal x (n).

The cosine values under the summation on the right hand side are the cosines of different angles depending the number of points of DCT.

When we observe the defining equation of 1-D DCT more closely, we find that the summation and the product of the terms under the summation can be viewed as matrix multiplication of input signal samples and the cosine matrix resulting in the output co-efficients. The matrix multiplication can be better visualized as shown in figure.1.7. In the above equation

$$\begin{bmatrix} X0 \\ X1 \\ X2 \\ X3 \\ X4 \\ X5 \\ X6 \\ X7 \end{bmatrix} = \begin{bmatrix} C4 & C4 & C4 & C4 & C4 & C4 & C4 & C4 \\ C1 & C3 & C5 & C7 & -C7 & -C5 & -C3 & -C1 \\ C2 & C6 & -C6 & -C2 & -C2 & -C6 & C6 & C2 \\ C3 & -C7 & -C1 & -C5 & C5 & C1 & C7 & -C3 \\ C4 & -C4 & -C4 & C4 & C4 & -C4 & -C4 & C4 \\ C5 & -C1 & C7 & C3 & -C3 & -C7 & C1 & -C5 \\ C6 & -C2 & C2 & C6 & -C6 & C2 & -C2 & C6 \\ C7 & -C5 & C3 & -C1 & C1 & -C3 & C5 & -C7 \end{bmatrix} \begin{bmatrix} x0 \\ x1 \\ x2 \\ x3 \\ x4 \\ x5 \\ x6 \\ x7 \end{bmatrix}$$

where $C_j = \text{Cos}\ (j\ \Pi/16)$

Fig.1.7. *Representation of N point 1-D DCT in matrix form*

	Angle in radians	Angle in degrees	Precise value	Numeric value
C_0	0	0	1	1
C_1	$\Pi/16$	11.25	$\frac{1}{2}\sqrt{2+\sqrt{2}+\sqrt{2}}$	0.9807853
C_2	$2\Pi/16$	22.5	$\frac{1}{2}\sqrt{2+\sqrt{2}}$	0.9238794
C_3	$3\Pi/16$	33.75	Complicated	0.8314695
C_4	$4\Pi/16$	45	$\frac{1}{2}\sqrt{2}$	0.7071065
C_5	$5\Pi/16$	56.25	Complicated	0.5555699
C_6	$6\Pi/16$	67.5	$\frac{1}{2}\sqrt{2-\sqrt{2}}$	0.3826829
C_7	$7\Pi/16$	78.75	$\frac{1}{2}\sqrt{2-\sqrt{2}+\sqrt{2}}$	0.1950897

Table.1.2. *Different cosine values [C_j] participating in 8 point DCT*

Table 1.2 gives the different cosine values [C_j] participating in 8-point 1-D DCT.

One of the important aims of this project is to obtain the output (i.e. the DCT co-efficients) faster than the Scanning Rate of a television.

CHAPTER II
DCT ALGORITHMS

Chapter 2

DCT Algorithms

Fast Algorithms

Fast computation of DCT co-efficients becomes necessary as these computations are used in several image processing (still and motion pictures) algorithms. Thus many fast algorithms have been proposed. Some of the fast algorithms that we have come across in our literature survey have been discussed briefly in the following sections. In almost all algorithms, an attempt has been made to reduce the direct multiplication operation that is involved in the DCT co-efficient computation, but realized in different ways rather than using the multiplier itself, which tends to consume more space and time.

2.1 Algorithm based on encoding algebraic integers

This algorithm is one among the many algorithms that has been extensively worked upon in our survey for a fast algorithm. The paper that has been referred to for this algorithm is ***"DHT algorithm based on encoding algebraic integers".***

The proposed algorithm is based on the algebraic integers encoding scheme. Using the first non-zero angle the other needed angles are represented in the polynomial form with the first non-zero angle as the basic root. An exact representation of the other angles can be done using the algebraic integers as shown in table 2.1and the implementation is found to be error free. The main advantage of this algorithm is that it can be implemented using systolic arrays, which enjoys the advantages of simplicity, regularity and modularity.

1-D DHT of an N-point sequence is defined as

$$X(k) = \sum x(n) \cas(2\Pi kn./N);\ 0 \leq k \leq N-1;\ n=0,1,2,\ldots N-1$$

	a_0	a_1	a_2	a_3	Error
2cas(0Π/16)	2	0	0	0	0
2cas(2Π/16)	0	-2	0	1	0
2cas(4Π/16)	-4	0	2	0	0
2cas(6Π/16)	0	-2	0	1	0

Table.2.1. *Representation of the cas (cosine+sine) function for 16 point DHT*

The same concept can be extended for the computation of DCT co-efficients. In case of DCT also the co-efficients can be represented with zero or minimal error. The paper ***"A new DCT algorithm based on encoding algebraic integers*** " proposes the representation of co-efficients using algebraic integers. An improvement can be made over this algorithm if the co-efficients of the first non-zero angle is represented using powers of 2 only. By doing so only shift operations need to be incorporated during implementation and further it saves one addition operation that should have been performed if the latter algorithm is implemented. This is because the algebraic integer, that is not a power of 2, has to be realized not only using shift but also requires an extra addition operation.

The different cosine values in the 8point DCT can be represented in polynomial form as shown below

$$f(z) = \sum a_i.z^i \qquad i= 0,1,\ldots\ldots 7$$

In the above equation 'z' is the cosine of the first non-zero angle and the remaining cosines are represented using this root while a_i are the corresponding co-efficients of z^i. Table.2.2 shows the representation of several cosines participating in the 8 point DCT based on encoding algebraic integers.

	a0	a1	a2	a3	a4	a5	a6	a7	Exact value	Represented value	Error in %
2cos(1∏/16)	0	1	0	0	0	0	0	0	1.9615706	1.9615706	0%
2cos(2∏/16)	-2	0	1	0	0	0	0	0	1.8477588	1.84775921	0.0000221%
2cos(3∏/16)	0	-3	0	1	0	0	0	0	1.662939	1.66293955	0.000033%
2cos(4∏/16)	2	0	-4	0	1	0	0	0	1.414213	1.41421416	0.000082%
2cos(5∏/16)	0	5	0	-5	0	1	0	0	1.1111139	1.48504715	33.653%
2cos(6∏/16)	-2	0	9	0	-6	0	1	0	0.7653658	0.76536793	0.000278%
2cos(7∏/16)	0	-7	0	14	0	-7	0	1	0.3901794	-2.22715874	--

Table. 2. 2.Representation of cosines participating in 8-point DCT using algebraic integers

This DCT algorithm based on encoding of algebraic integers has further been worked upon by replacing the 'integers' by 'integers which are powers of 2'.By doing so the extra addition operation required for normal integer multiplication can be eliminated thus reducing space (for adder) and time (clock cycles).

The representation of the cosines participating in the 8 point DCT using the basic root is as shown in table2.3. Calculating the error in percent makes a comparison between the exact and the represented value. Extending the co-efficients (a_i) further can reduce this error.

	a_0	a_1	a_2	a_3	a_4	a_5	Exact value	Represented value	Error in %
$2\cos(1\Pi/16) \Rightarrow 2[C1]$	0	1	0	0	0	0	1.9615706	1.9615706	0%
$2\cos(2\Pi/16) \Rightarrow 2[C2]$	-2	0	1	0	0	0	1.8477588	1.84775921	0.0000221%
$2\cos(3\Pi/16) \Rightarrow 2[C3]$	0	0	8	2	-1	-1	1.662939	1.65667448	0.000082%
$2\cos(4\Pi/16) \Rightarrow 2[C4]$	2	0	-4	0	1	0	1.414213	1.41421416	0.37%
$2\cos(5\Pi/16) \Rightarrow 2[C5]$	1	-2	1	0	2	-1	1.1111139	1.11966911	0.76%
$2\cos(6\Pi/16) \Rightarrow 2[C6]$	0	0	-4	8	-1	-1	0.7653658	0.76595131	0.5%
$2\cos(7\Pi/16) \Rightarrow 2[C7]$	0	0	0	0	4	-2	0.3901794	0.3901022	0.019%

Table.2.3. *Representation of cosines participating in 8-point DCT in powers of 2.*

2.2 A multiplierless implementation scheme for the JPEG Image coding

This paper ***"A multiplierless implementation scheme for the JPEG Image coding algorithm"*** reports an efficient implementation scheme for a JPEG encoder. The baseline JPEG algorithm is executed without involving any multiplication .All the arithmetic operations are reduced to simple additions and subtractions and very short shifts which is as shown in fig.2.4. This translates into a hardware implementation of reduced complexity. The multiplication involves the multiplication of a fixed co-efficient with the signal sample value

Original co-efficients	Multiplierless approximation	Binary representation	Number of add/shift	Maximum single shift	Relative error
0.7071	0.70312500	0.10110100	4	4	0.56%
0.2706	0.26953125	0.01000101	3	4	0.39%
0.6533	0.65625000	0.10101000	3	2	0.45%
0.3827	0.38281250	0.01100010	3	4	0.03%

Table.2.4. *Approximation of the co-efficients for the DCT computation*

2.3 BinDCT: Fast Multiplierless Approximation of the DCT

This paper presents a family of fast biorthogonal block transforms called BinDCT that can be implemented using only shift and adds operations. The transform is based on a VLSI-friendly lattice structure that robustly enforces both linear phase and perfect reconstruction properties. Application of the BinDCT in both lossy and lossless image coding yield very competitive results compared to the performance of the original floating-point DCT.

Compared to the DCT, the novel block transform offers numerous advantages.

1.The BinDCT has a fast, elegant implementation utilizing only shift and add operations. No multiplication is needed.

2. Eight transform co-efficients can be computed using as low as 13 bit shifts and 30 additions.

3. The BinDCT can map integers to integers with exact reconstruction.

4. In software implementation, the BinDCT is found to be three times faster than the floating point DCT. Much higher speed is expected in hardware implementation.

5. The multiplierless property of the BinDCT allows efficient VLSI implementations in terms of both chip area and power consumption.

6. The BinDCT approximates the DCT very closely.

7. The BinDCT has reasonably high coding performances.

Bin DCT has the following properties

1. Both forward and inverse transforms can be implemented using only binary shifts and additions operations.
2. The idea of scaled DCT is used to reduce complexity.
3. Bin DCT inherits all desirable DCT characteristics such as high coding gain, no DC leakage, symmetric basis functions and recursive construction.
4. Bin DCT inherits all lifting properties such as fast implementations, invertible integer to integer mapping ,in place computation and low dynamic range

2.4 Fast DCT algorithm with Even/Odd decomposition:

This algorithm reduces computational complexity. Even /odd decompositions is one of the obvious ways of reducing the number of multiplications and additions. This is done by using symmetry and anti-symmetry property in cosine scalars. The matrix can be rewritten as shown in fig.2.1

$$\begin{bmatrix} X(0) \\ X(1) \\ X(2) \\ X(3) \\ X(4) \\ X(5) \\ X(6) \\ X(7) \end{bmatrix} = \begin{bmatrix} C_4 & C_4 & C_4 & C_4 & 0 & 0 & 0 & 0 \\ C_2 & C_6 & -C_6 & -C_2 & 0 & 0 & 0 & 0 \\ C_4 & -C_4 & -C_4 & C_4 & 0 & 0 & 0 & 0 \\ C_6 & -C_2 & C_2 & -C_6 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & C_1 & C_3 & C_5 & C_7 \\ 0 & 0 & 0 & 0 & C_3 & -C_7 & -C_1 & -C_5 \\ 0 & 0 & 0 & 0 & C_5 & -C_1 & C_7 & C_3 \\ 0 & 0 & 0 & 0 & C_7 & -C_5 & C_3 & -C_1 \end{bmatrix} \begin{bmatrix} 1 & 0 & 0 & 0 & 0 & 0 & 0 & 1 \\ 0 & 1 & 0 & 0 & 0 & 0 & 1 & 0 \\ 0 & 0 & 1 & 0 & 0 & 1 & 0 & 0 \\ 0 & 0 & 0 & 1 & 1 & 0 & 0 & 0 \\ 1 & 0 & 0 & 0 & 0 & 0 & 0 & -1 \\ 0 & 1 & 0 & 0 & 0 & 0 & -1 & 0 \\ 0 & 0 & 1 & 0 & 0 & -1 & 0 & 0 \\ 0 & 0 & 0 & 1 & -1 & 0 & 0 & 0 \end{bmatrix} \begin{bmatrix} x(0) \\ x(1) \\ x(2) \\ x(3) \\ x(4) \\ x(5) \\ x(6) \\ x(7) \end{bmatrix}$$

Fig. 2.1. One level Even/Odd decomposition

One level even/odd decomposition requires 32 multiplications and 32 additions as against 64 multiplications and 56 additions required by direct computation. By decomposing further, we get all level even/odd decomposition, which is as shown in fig.2.2.

$$\begin{bmatrix} X(0) \\ X(1) \\ X(2 \\ X(3) \\ X(4) \\ X(5) \\ X(6) \\ X(7) \end{bmatrix} = \begin{bmatrix} 1 & 1 & 0 & 0 & 0 & 0 & 0 & 1 \\ 1 & -1 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 1 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 1 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 1 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 1 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 1 & 0 \\ 0 & 0 & 0 & 1 & -1 & 0 & 0 & 1 \end{bmatrix} \bullet \begin{bmatrix} C_4 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & C_4 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & C_2 & C_6 & 0 & 0 & 0 & 0 \\ 0 & 0 & C_6 & -C_2 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & C_1 & C_3 & C_5 & C_7 \\ 0 & 0 & 0 & 0 & C_3 & -C_7 & -C_1 & -C_5 \\ 0 & 0 & 0 & 0 & C_5 & -C_1 & C_7 & C_3 \\ 0 & 0 & 0 & 0 & C_7 & -C_5 & C_3 & -C_1 \end{bmatrix}$$

$$\begin{bmatrix} 1 & 0 & 0 & 1 & 0 & 0 & 0 & 0 \\ 0 & 1 & 1 & 0 & 0 & 0 & 0 & 0 \\ 1 & 0 & 0 & -1 & 0 & 0 & 0 & 0 \\ 0 & 1 & -1 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 1 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 1 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 1 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 1 \end{bmatrix} \bullet \begin{bmatrix} 1 & 0 & 0 & 0 & 0 & 0 & 0 & 1 \\ 0 & 1 & 0 & 0 & 0 & 0 & 1 & 0 \\ 0 & 0 & 1 & 0 & 0 & 1 & 0 & 0 \\ 0 & 0 & 0 & 1 & 1 & 0 & 0 & 0 \\ 1 & 0 & 0 & 0 & 0 & 0 & 0 & -1 \\ 0 & 1 & 0 & 0 & 0 & 0 & -1 & 0 \\ 0 & 0 & 1 & 0 & 0 & -1 & 0 & 0 \\ 0 & 0 & 0 & 1 & -1 & 0 & 0 & 0 \end{bmatrix} \bullet \begin{bmatrix} x(0) \\ x(1) \\ x(2) \\ x(3) \\ x(4) \\ x(5) \\ x(6) \\ x(7) \end{bmatrix}$$

Fig.2.2. *All level even/odd decomposition*

The number of multiplications and additions required for all level even/odd decomposition are 22 and 28 respectively. The signal flow graph so obtained will not be as regular as that for original DCT formula. Compared to other fast algorithms scaled even/odd decomposition algorithm is not the fastest, yet it has numerical and latency advantages over the faster algorithms as all multilications can be performed concurrently (in parallel / pipelined). A comparison of all-level even/odd decomposition & original DCT formula is shown in table.2.5.

	Multiplication	Addition	1000 frames per sec.
Original DCT formula	64	56	103 sec.
All level Even/Odd Decomposition	22	28	43 sec.

Table. 2.5. Comparison of all level Even/odd decomposition & original DCT formula

CHAPTER III
IMPLEMENTATION

Chapter 3

IMPLEMENTATION

3.1 The Role of Distributed Arithmetic in FPGA-based Signal Processing

3.1.1 Introduction

Distributed Arithmetic (DA) plays a key role in embedding DSP functions in FPGA devices. In this chapter the DA algorithm is derived and examples are offered that illustrate its effectiveness in producing gate-efficient designs.

3.1.2 Distributed Arithmetic Revisited

Distributed Arithmetic, along with Modulo Arithmetic, are computation algorithms that perform multiplication with look-up table based schemes. Both stirred some interest over two decades ago but have languished ever since. Indeed, DA specifically targets the sum of products (sometimes referred to as the vector dot product) computation that covers many of the important DSP filtering and frequency transforming functions. Ironically, many DSP designers have never heard of this algorithm. Inspired by the potential of the Xilinx FPGA look-up table architecture, the DA algorithm was resurrected in the early 90's. The derivation of the DA algorithm is extremely simple but its applications are extremely broad. The mathematics includes a mix of Boolean and ordinary algebra and require no prior preparation - even for the logic designer.

3.1.3 Distributed Arithmetic at a Glance

The arithmetic sum of products that defines the response of linear, time-invariant networks can be expressed as:

$$y(n) = \sum_{k=1}^{K} A_k x_k(n) \text{----------(1)}$$

where:

$y(n)$ = response of network at time n.

$x_k(n)$ = k^{th} input variable at time n.

A_k = weighting factor of k^{th} input variable that is constant for all n, and so it remains time-invariant.

In frequency transforming –whether the Discrete Fourier or the Discrete Cosine Transform - the constants are the sine/cosine basis functions and the variables are a block of samples from a single data source. Examples of multiple data sources may be found in image processing.

The multiply intensive nature of eqn(1) can be appreciated by observing that a single output response requires the accumulation of K product terms. In DA the task of summing product terms is replaced by table look-up procedures that are easily implemented in configurable logic block (CLB) look-up table architecture. We start by defining the number format of the variable to be 2's complement, fractional - a standard practice for fixed-point microprocessors in order to bound number growth under multiplication. The constant factors, A_k, need not be so restricted, nor are they required to match the data word length, as is the case for the microprocessor. The constants may have a mixed integer and fractional format; they need not be defined at this time. The variable, x_k, may be written in the fractional format as shown in eqn(2)

$$x_k = - x_{k0} + \sum_{b=1}^{B-1} x_{kb}\, 2^{-b} \quad \text{----------(2)}$$

where x_{kb} is a binary variable and can assume only values of 0 and 1. A sign bit of value -1 is indicated by x_{k0}. Note that the time index, n, has been dropped since it is not needed to continue the derivation. The

final result is obtained by first substituting equ.2 into equ.1 –

$$y = \sum_{k=1}^{K} A_k \left[-x_{k0} + \sum_{b=1}^{B-1} x_{kb}\, 2^{-b} \right]$$

$$= \sum_{k=1}^{K} x_{k0} \cdot A_k + \sum_{k=1}^{K} \sum_{b=1}^{B-1} x_{kb} \cdot A_k\, 2^{-b}$$

and then explicitly expressing all the product terms under the summation symbols:

$$y = - [x_{10} .A_1 + x_{20} .A_2 + x_{30} .A_3 + \ldots + x_{K0} .A_K] \quad \text{----------(4)}$$
$$+ [x_{11} .A_1 + x_{21} .A_2 + x_{31} .A_3 + \ldots + x_{K1} .A_K]\, 2^{-1}$$
$$+ [x_{12} A_1 + x_{22} .A_2 + x_{32} .A_3 + \ldots + x_{K2} .A_K]\, 2^{-2}$$
$$\square$$
$$\square$$
$$\square$$
$$+ [x_{1(B-2)} .A_1 + x_{2(B-2)} .A_2 + x_{3(B-2)} \cdot A_3 + \ldots + x_{K(B-2)} .A_K] 2^{-(B-2)}$$
$$+ [x_{1(B-1)} .A_1 + x_{2(B-1)} .A_2 + x_{3(B-1)} .A_3 + \ldots + x_{K(B-1)} .A_K] 2^{-(B-1)}$$

Each term within the brackets denotes a binary AND operation involving a bit of the input variable and all the bits of the constant. The plus signs denote arithmetic sum operations. The exponential factors denote the scaled contributions of the bracketed pairs to the total sum. One can now construct a look-up table that can be addressed by the same-scaled bit of all the input variables and can access the sum of the terms within each pair of

brackets. Such a table is shown in fig. 3.1 and will henceforth be referred to as a Distributed Arithmetic look-up table or DALUT. The same DALUT can be time-shared in a serially organized computation or can be replicated B times for a parallel computation scheme, as described later. This ends the derivation of DA algorithm, but, before we continue with our application examples, we must note the following observations.

The arithmetic operations have now been reduced to addition, subtraction, and binary scaling. With scaling by negative powers of 2, the actual implementation entails the shifting of binary coded data words toward the least significant bit and the use of sign extension bits to maintain the sign at its normal bit position. The hardware implementation of a binary full adder (as is done in the CLBs) entails two operands, the addend and the augend to produce sum and carry output bits. The multiple bit-parallel additions of the DALUT outputs expressed in eqn.(4) can only be performed with a single parallel adder if this adder is time-shared. Alternatively, if simultaneous addition of all DALUT outputs is required, an array of parallel adders is required. These opposite goals represent the classic speed-cost tradeoff.

LUT inputs				LUT outputs
X_4	X_3	X_2	X_1	
0	0	0	0	0
0	0	0	1	C_4
0	0	1	0	C_4
0	0	1	1	$2C_4$
0	1	0	0	C_4
0	1	0	1	$2C_4$
0	1	1	0	$2C_4$
0	1	1	1	$3C_4$
1	0	0	0	C_4
1	0	0	1	$2C_4$
1	0	1	0	$2C_4$
1	0	1	1	$3C_4$
1	1	0	0	$2C_4$
1	1	0	1	$3C_4$
1	1	1	0	$3C_4$
1	1	1	1	$4C_4$

Table.3.1.Contents of a 16-word look-up table for the first row of the DCT matrix

3.1.4 The Speed Tradeoff

Any new device that can be software configured to perform DSP functions must contend with the well entrenched standard DSP chips, i.e. the programmable fixed point microprocessors that feature concurrently operating hardware multipliers and address generators, and on-chip memories. The first challenge is speed. A simple advantage may not be persuasive in all cases - an overwhelming speed advantage may be needed for FPGA

acceptance. Is it possible to reach 50 megasamples/sec data sample rates? Yes but at a high cost in gate resources. The first two examples will show the end points of the serial/parallel tradeoff continuum.

3.1.5 The Ultimate in Speed

Conceivably, with a fully parallel design the sample speed could match the system clock rate. This is the case where all the add operations of the bracketed values (the DALUT outputs) of equ. (4) are performed in parallel. We can gain implementation guidance by rephrasing equ. (4), and to facilitate this process let us abbreviate the contents within each bracket pair by the data bit position.

Thus $[x_{12}A_1 + x_{22}.A_2 + x_{32}.A_3 + \ldots + x_{K2}.A_K]$ reduces to [sum 2] and, similarly,

$[x_{1(B-1)}.A_1 + x_{2(B-1)}.A_2 + x_{3(B-1)}.A_3 + \ldots + x_{K(B-1)}.A_K]$ reduces to [sum(B-1)]

For B = 16, equ. (4) becomes:

$$y = -[\text{sum0}] + [\text{sum1}]2^{-1} + [\text{sum2}]2^{-2} + \square + \square + \square + [\text{sum14}]2^{-14} + [\text{sum15}]2^{-15} \quad \text{----------(5)}$$

The decomposition of eqn.(5) into an array of two input adders is given below:

$$y = -[\text{sum0}] + [\text{sum1}]2^{-1} + \{[\text{sum2}] + [\text{sum3}]2^{-1}\}2^{-2}$$

$$+ \{[sum4] + [sum5]2^{-1} + \{[sum6] + [sum7]2^{-1}\}2^{-2}\}2^{-4}$$
$$+ \{\{[sum8] + [sum9]2^{-1} + \{[sum10] + [sum11]2^{-1}\}2^{-2}\}$$
$$+ \{[sum12] + [sum13]2^{-1} + \{[sum14] + [sum15]2^{-1}\}2^{-2}\}2^{-4}\}2^{-8}$$
----------(6)

Equations (5) and (6) are computationally equivalent, but equ. (6) can be mapped in a straight-forward way into a binary tree-like array of summing nodes with scaling effected by signal routing. Each of the 15 nodes represents a parallel adder, and while the computation may yield responses that include both the double precision (B+C bits) of the implicit multiplication and the attendant processing gain, these adders can be truncated to produce single precision (B bits) responses. The selection of binary value levels along the data path will be discussed later. We can, nonetheless, discuss some of the hardware needed to realize this computation.

3.1.6 Number formats

Numbers are a systematic representation of the counting process. Large numbers are efficiently represented by a weighted number system wherein a few symbols are used repeatedly with different weights or radices. Thus, in our well-known decimal system there are 10 symbols or digits, 0 through 9,which define the value within each decimal (radix 10) position. The digits in a decimal number have position weightings of 1, 10, 100, 1000, etc. Western civilization was weaned on the radix 10. It, of course, is not the only radix; the ancient Egyptians knew the radix 2, the Babylonians the radix 60, the Mayans radices 18 and 20. The advent of digital computers has renewed our interest in radix 2 (binary) number systems.

The radix-2 or binary number system fits nicely with two level (expressed by symbols 0 and 1) logic circuits. Any integer, N, can be represented in binary notation as:

$$N = \sum_{j=0}^{M} b_j 2^j \qquad \text{----------(7)}$$

where the coefficients b_j denote the binary values 0,1 and the j^{th} power of 2 denotes the weight at the j^{th} position. The weighted binary representation serves as the basis for both fixed and floating point number formats. While our focus will be on fixed binary point formats it should be noted that floating point is used widely, and a standardized format (IEEE 754) has been established. Since many DSP microprocessors offer this format, a brief background description follows. The floating point number format is largely inspired by the need to represent large dynamic range numbers (10 +99) without resorting to extremely large word lengths. Similar to the logarithm, the floating-point number is represented by both an exponent and a mantissa. The standard 32-bit format has a sign bit in the most significant bit position. An eight-bit exponent and a 23-bit mantissa follow the sign bit. The exponent defines the powers of 2 prior to the binary point. The exponent covers a magnitude range of 2 255 or, equivalently, a signal range of 1530 dB (to be explained later) - an extremely large value since the upper end of the analog-to-digital converter range is 100 dB. The binary point of the mantissa denotes the most significant "1" bit of the number. In fact, it is not represented but implied in the floating-point format, with the mantissa containing the 23 lower bits. Following an arithmetic operation, the mantissa, M, is "normalized" to the range ½ < M <1. Floating point arithmetic entails complex procedures as shown in fig. 5. The additional hardware needed to execute these procedures in a manner that is transparent to the programmer adds significantly to the device cost. The fixed-point number format is a compelling choice for the FPGA.

3.1.7 Fractional 2's Complement Representation

Number values are unbounded but computer representations are not. The basic DSP equation 1 generates word growth. The multiplication of two B bit factors produces a 2B bit product; addition often produces a carry bit. Repeated additions can produce multiple carry bits. Using the fractional 2's complement number representation can bound multiplication. The DA development that was presented earlier is based on the use of this format; equation 2 defines the 2's complement fractional format. The sign bit, x0, is 1 for negative numbers. The binary point follows this and then a positive component made up of a decreasing order of B-1 binary weighted fractions. Two important features of this form are:

- The number 0 is represented unambiguously with all coefficients, x_b, equal to 0 (this is not the case for the 1's complement).
- Complementing the subtrahend bit by bit, doing a binary addition of the two operands, and then adding 1 x2 -(B-1) (i.e. 1 in the least significant bit position) to the results easily realize subtraction.

The range of values, -1 to 1-2 -(B-1) , is not symmetric about the origin. This may introduce undesirable artifacts in the output signal when full-scale limiting occurs. Clamping to symmetrical end points -1 + 2 -(B-1) and 1- 2 -(B-1) eliminates this problem.

The multiplication of two B bit fractional numbers yields a fractional, double precision product of 2B bits. If the product is subjected to further multiplications, word growth would soon exceed the size of the processing resources. Reduction to single precision through rounding or truncation is a standard procedure. The carries resulting from addition cause word growth at the high end. The result is a mixed format with integer values to the left of the binary point and fractional values to the right. The largest integer bit defines the value of the sign. If the add operation yields result that exceed the capacity of the adder circuit, overflow occurs and the value of the sum "wraps around " - a transition from maximum positive to maximum negative, or vice versa.

3.2 IMPLEMENTATION

$$\begin{bmatrix} X0 \\ X1 \\ X2 \\ X3 \\ X4 \\ X5 \\ X6 \\ X7 \end{bmatrix} = \begin{bmatrix} C4 & C4 & C4 & C4 & C4 & C4 & C4 & C4 \\ C1 & C3 & C5 & C7 & -C7 & -C5 & -C3 & -C1 \\ C2 & C6 & -C6 & -C2 & -C2 & -C6 & C6 & C2 \\ C3 & -C7 & -C1 & -C5 & C5 & C1 & C7 & -C3 \\ C4 & -C4 & -C4 & C4 & C4 & -C4 & -C4 & C4 \\ C5 & -C1 & C7 & C3 & -C3 & -C7 & C1 & -C5 \\ C6 & -C2 & C2 & C6 & -C6 & C2 & -C2 & C6 \\ C7 & -C5 & C3 & -C1 & C1 & -C3 & C5 & -C7 \end{bmatrix} \begin{bmatrix} x0 \\ x1 \\ x2 \\ x3 \\ x4 \\ x5 \\ x6 \\ x7 \end{bmatrix}$$

where $C_j = \cos(j \Pi/16)$

Fig3.1.Matrix representation of 1-D DCT

The cosine matrix that is used in the computation of the DCT is as shown in fig.3.1. It is observed that a lot of symmetry exists in this representation. We see that the terms in even rows exhibit even symmetry and those in odd numbered rows exhibit odd or anti-symmetry. This property of the original matrix is exploited to obtain decomposition of the matrix in 2 matrices as shown in fig.3.2

$$\begin{bmatrix} X(0) \\ X(1) \\ X(2) \\ X(3) \\ X(4) \\ X(5) \\ X(6) \\ X(7) \end{bmatrix} = \begin{bmatrix} C_4 & C_4 & C_4 & C_4 & 0 & 0 & 0 & 0 \\ C_2 & C_6 & -C_6 & -C_2 & 0 & 0 & 0 & 0 \\ C_4 & -C_4 & -C_4 & C_4 & 0 & 0 & 0 & 0 \\ C_6 & -C_2 & C_2 & -C_6 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & C_1 & C_3 & C_5 & C_7 \\ 0 & 0 & 0 & 0 & C_3 & -C_7 & -C_1 & -C_5 \\ 0 & 0 & 0 & 0 & C_5 & -C_1 & C_7 & C_3 \\ 0 & 0 & 0 & 0 & C_7 & -C_5 & C_3 & -C_1 \end{bmatrix} \begin{bmatrix} 1 & 0 & 0 & 0 & 0 & 0 & 0 & 1 \\ 0 & 1 & 0 & 0 & 0 & 0 & 1 & 0 \\ 0 & 0 & 1 & 0 & 0 & 1 & 0 & 0 \\ 0 & 0 & 0 & 1 & 1 & 0 & 0 & 0 \\ 1 & 0 & 0 & 0 & 0 & 0 & 0 & -1 \\ 0 & 1 & 0 & 0 & 0 & 0 & -1 & 0 \\ 0 & 0 & 1 & 0 & 0 & -1 & 0 & 0 \\ 0 & 0 & 0 & 1 & -1 & 0 & 0 & 0 \end{bmatrix} \begin{bmatrix} x(0) \\ x(1) \\ x(2) \\ x(3) \\ x(4) \\ x(5) \\ x(6) \\ x(7) \end{bmatrix}$$

Fig.3.2. One level Even/Odd decomposition of the original DCT matrix

The product of the last two matrices on the RHS would result in a row vector as shown in fig.3.3.

$$\begin{bmatrix} X(0) \\ X(2) \\ X(4) \\ X(6) \end{bmatrix} = \begin{bmatrix} C4 & C4 & C4 & C4 \\ C2 & C6 & -C6 & C2 \\ C4 & -C4 & -C4 & C4 \\ C6 & -C2 & C2 & -C6 \end{bmatrix} \begin{bmatrix} x(0) + x(7) \\ x(1) + x(6) \\ x(2) + x(5) \\ x(3) + x(4) \end{bmatrix}$$

$$\begin{bmatrix} X(1) \\ X(3) \\ X(5) \\ X(7) \end{bmatrix} = \begin{bmatrix} C1 & C3 & C5 & C7 \\ C3 & -C7 & -C1 & -C5 \\ C5 & -C1 & C7 & C3 \\ C7 & -C5 & C3 & -C1 \end{bmatrix} \begin{bmatrix} x(3) - x(4) \\ x(2) - x(5) \\ x(1) - x(6) \\ x(0) - x(7) \end{bmatrix}$$

Fig.3.3 Resultant matrices after multiplying the last two matrices on the RHS

It is now evident from fig3.3 as compared to fig.3.1 that the number of multiplications has been reduced from 64 to 32 i.e. by a factor of two. This is accomplished by only performing on extra operation on the input data i.e. one bit addition or subtraction.

Now Distributed Arithmetic (DA) explained in the previous chapter is used to compute the co-efficient values. The cosine values used in the calculation are constant, so the only variable in the calculation is the inputs. Since the matrix size has been reduced, only four input values are required for the calculation of the odd and even co-efficients. There are only sixteen combinations (0000 to 1111) of the input and depending on these input values the partial products are stored in a Look-Up Table (LUT). The block diagram of a ROM-Accumulator(RAC) unit for the implementation of sum of products using Distributed Arithmetic is in fig 3.4.

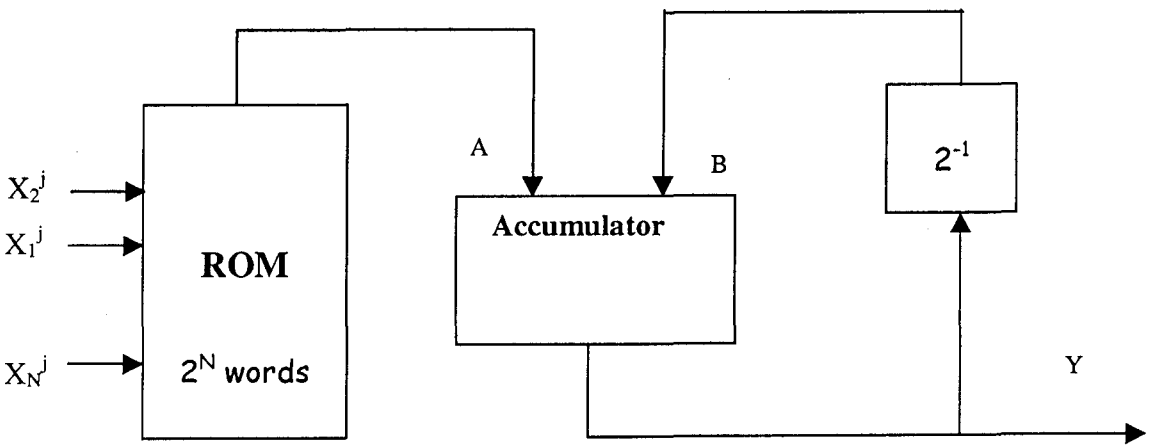


Fig.3.4 ROM-Accumulator unit for the implementation of sum of products using Distributed Arithmetic

Using the ROM-ACCUMULATOR module and the Decomposition approach the implementation of the 1-D DCT is in fig.3.5..

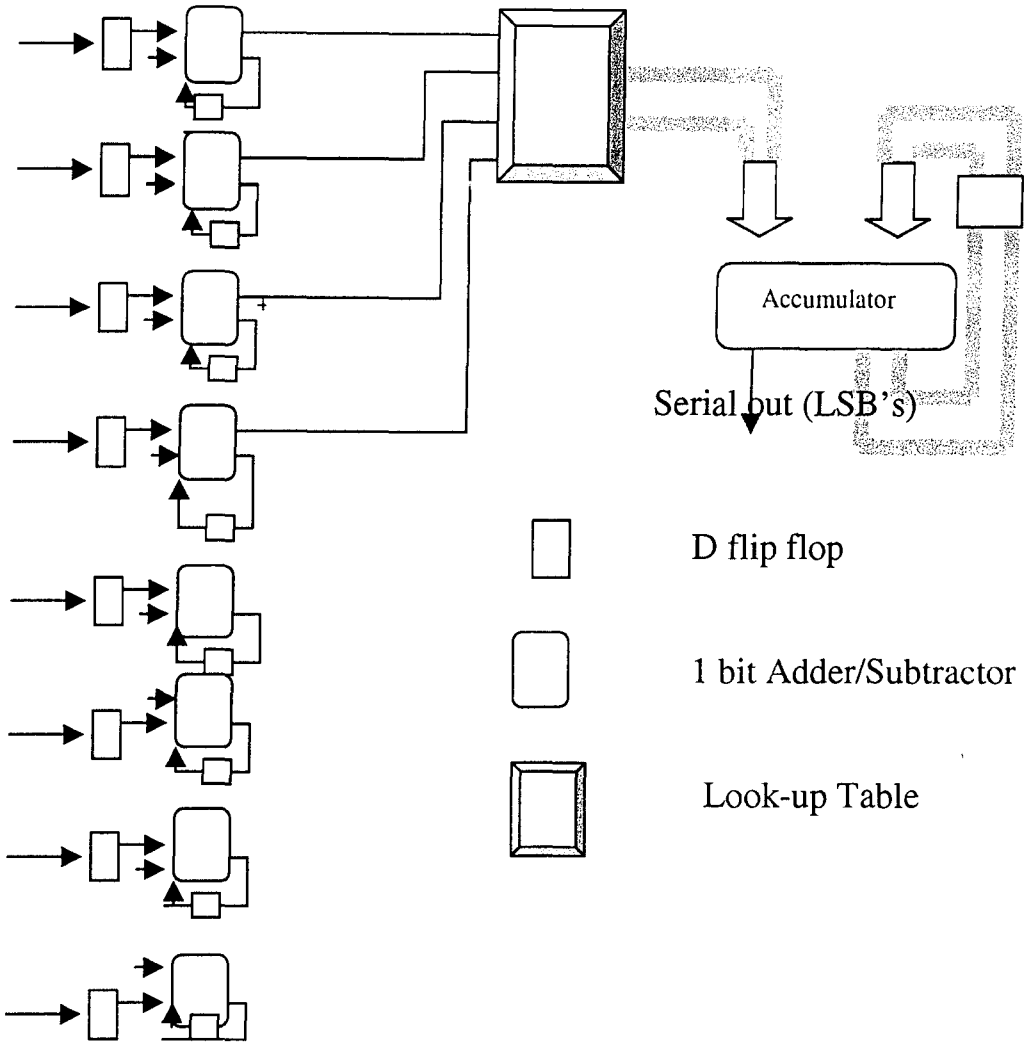


Fig.3.5 Block diagram of 1-D DCT implemented using the ROM-Accumulator module and the Decomposition approach.

3.3 Highlights of the algorithm chosen

- **Serial architecture**

The module is Serial in Serial out. This facilitates the progressive transmission of the co-efficients i.e. the LSB of the output can be transmitted even before the entire data has been clocked into the module.

- **Entire 1-D DCT block consists of repetitive blocks**

It can be clearly seen that the module can be divided into smaller blocks, which are repetitive. Each of these repetitive blocks are used for the calculation of one co-efficient value. The only difference among these blocks is the entries in the LUT.

- **Highly Pipelined Architecture**

The architecture has been divided into stages, so that the concept of pipelining can be used. Each stage has a buffer to store the output value at that stage. Using this concept, we can key in new data into the first stage as the old data is still being processed in the successive stages. This feature eliminates the need for a faster clock.

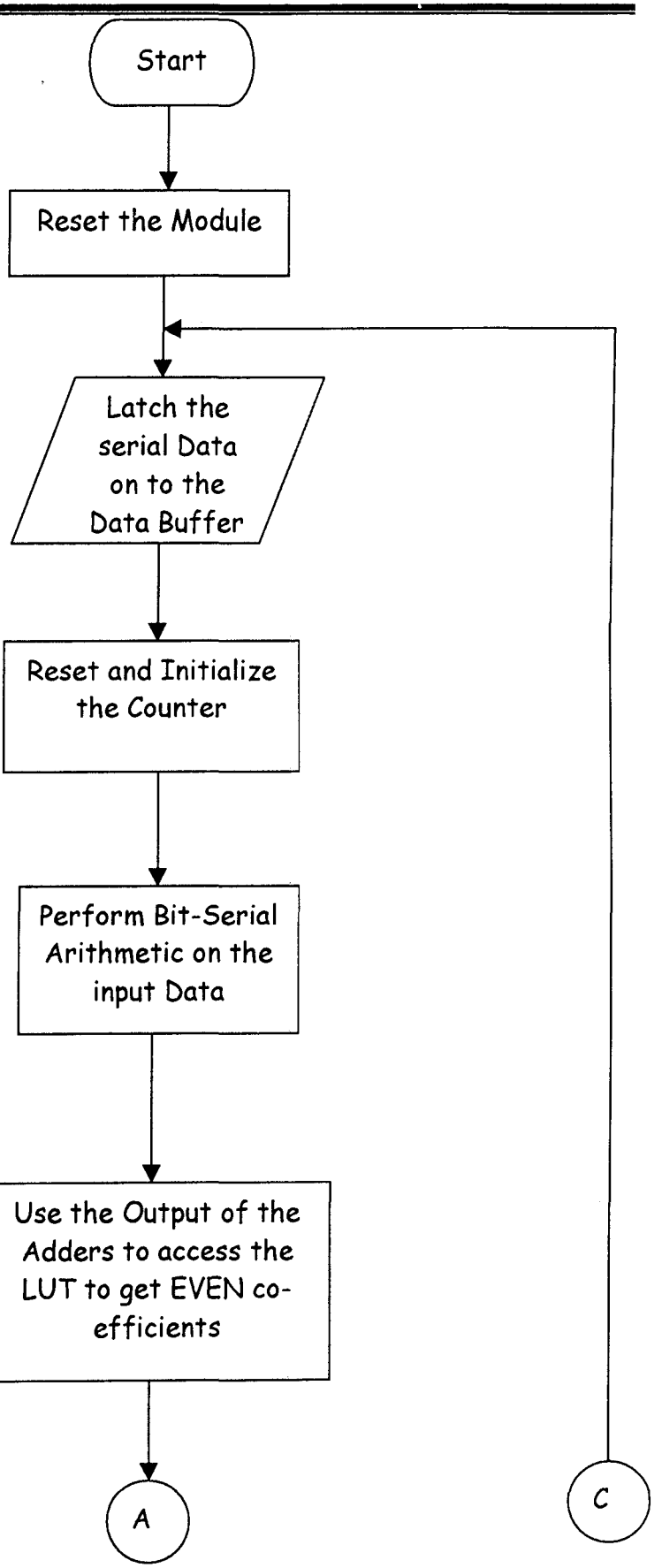
- **The algorithm uses Distributed Arithmetic.**
- **Simple components:**

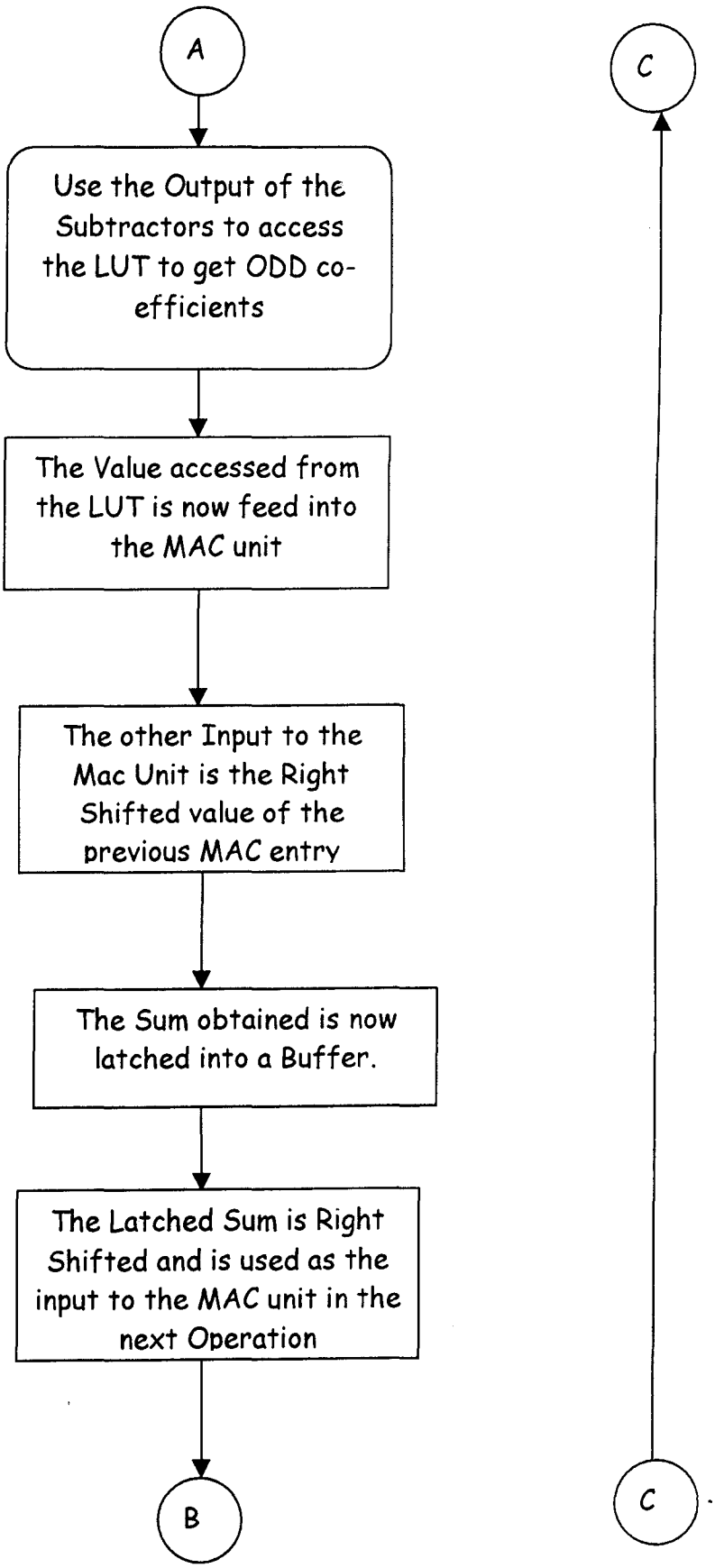
The use of simple components such as D flip flops,adder, subtractor,accumulator reduce the burden on the programmer and the code becomes simple enough for a learner.

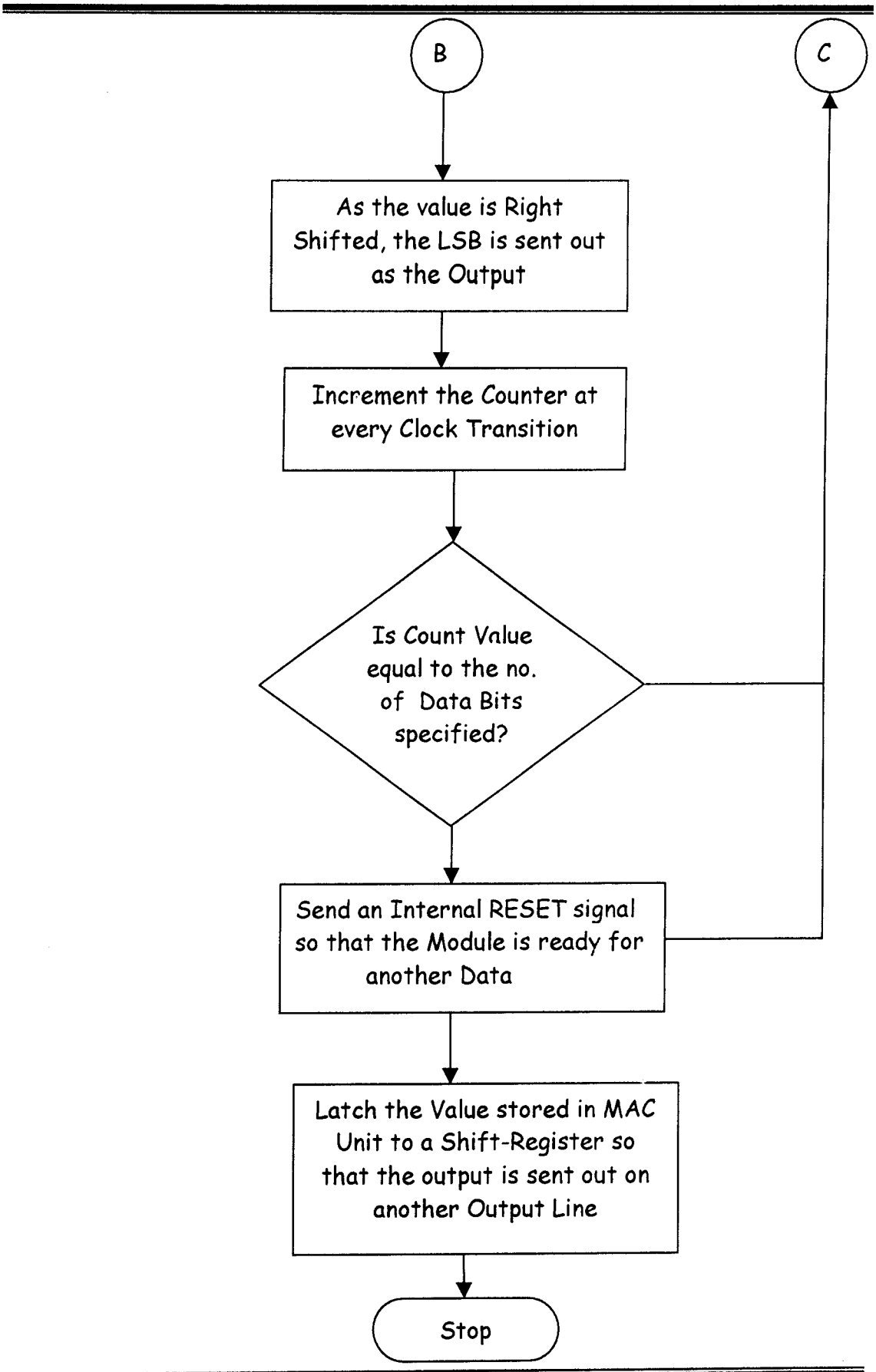
- Use of **distributed arithmetic has eliminated the butterfly structure that consumes lot of hardware due to routing in FPGA's.**

3.4 FLOWCHART

The flowchart for the algorithm that has been implemented in this project is shown in fig 3.6


Start
Reset the Module
Latch the serial Data on to the Data Buffer
Reset and Initialize the Counter
Perform Bit-Serial Arithmetic on the input Data
Use the Output of the Adders to access the LUT to get EVEN co-efficients
A
C


A
Use the Output of the Subtractors to access the LUT to get ODD co-efficients
The Value accessed from the LUT is now feed into the MAC unit
The other Input to the Mac Unit is the Right Shifted value of the previous MAC entry
The Sum obtained is now latched into a Buffer.
The Latched Sum is Right Shifted and is used as the input to the MAC unit in the next Operation
B
C
C


B
C
As the value is Right Shifted, the LSB is sent out as the Output
Increment the Counter at every Clock Transition
Is Count Value equal to the no. of Data Bits specified?
Send an Internal RESET signal so that the Module is ready for another Data
Latch the Value stored in MAC Unit to a Shift-Register so that the output is sent out on another Output Line
Stop

CHAPTER IV
VHDL and PROGRAMMABLE LOGIC

Chapter 4

VHDL and Programmable Logic

4.1 Introduction

VHDL arouse out of the United States government's Very high Speed Integrated Circuits (VHSIC) program. In the course of this program, it became clear that there was a need for a standard language for describing the structure & function of integrated circuits (ICs). Hence the VHSIC Hardware Description Language (VHDL) was developed. It was subsequently developed further under Institute of Electrical & Electronics Engineers (IEEE) and adopted in the form of the IEEE standard 1076.

VHDL is a hardware description language that can be used to model a digital system at many levels of abstraction ranging from algorithmic level to gate level. Different levels of abstractions are used in VHDL to reduce the complexity and development time. The complexity of digital system being modeled could vary from that of a simple gate to a complete digital electronic system, or anything in between. VHDL language can be regarded as an integrated amalgamation of the following:

Sequential language + Concurrent language + Net list language +
Timing specification + Waveform generation language → VHDL

Therefore, the language has constructs that enable one to express the concurrent or sequential behavior of digital systems with or without timing. The language also defines very clear simulation semantics for each language construct. Therefore models written in this language can be verified using a VHDL simulator. VHDL is used to describe a model for digital hardware device which specifies the functionality or structure.

4.2 Why VHDL?

With VHDL we can quickly describe and synthesize the circuit of five, ten or twenty thousands of gates. Equivalently design described with schematics or Boolean equation at the register transfer level can require several engineer months of work. In addition VHDL provides capabilities descried below:

a. Power and flexibility

VHDL has powerful language constructs with which to write succinct code description of complex control logic. It also has multiple levels of design description for controlling design implementation. It supports design libraries and creation of reusable components. It provides for design hierarchies to create modular design and simulation.

b. Device independent design

One design description can be used to target many device architectures. We do not have to become intimately familiar with device architectures in order
to optimize our design for resource utilization or performance. VHDL also permits multiple styles of design descriptions.

c. Portability

Simulating a several thousand-gate design description before synthesizing can save considerable time: a design flaw (bug) discovered at this stage can be corrected before the design implementation stage. Because VHDL is a standard, our design description can be taken from one simulator to another, one synthesizer to another. This means that VHDL design description can be used in multiple projects. Figure 4.1 illustrates that the source code for a design can be used with any synthesis tool and that design can be implemented in any device that is supported by synthesis tool.

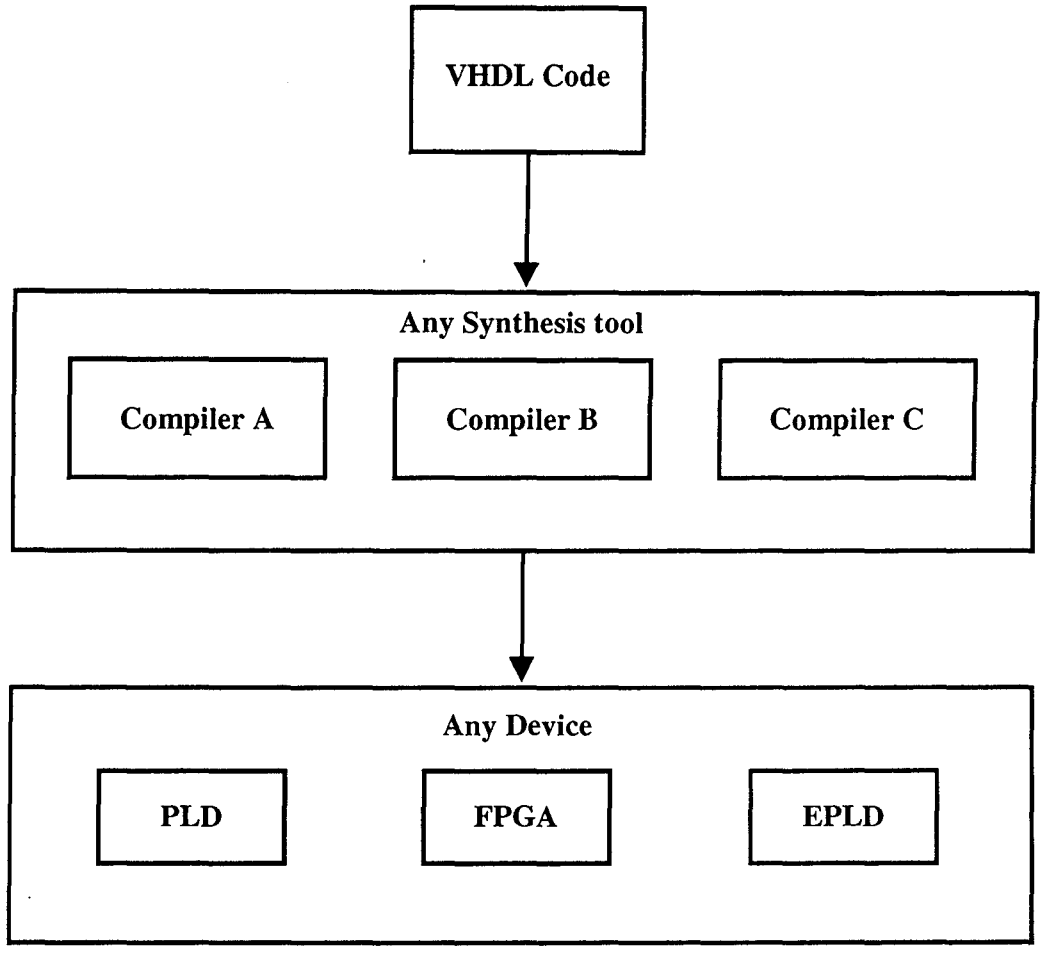


Figure 4.1 Portability of VHDL Code.

d. Bench marking capability

Device independent design and portability allow us to benchmark a design using different device architectures and different synthesis tools. We can take a complete design description and synthesize it, creating logic for architecture of our choice. We can then evaluated the results and choose the device best fit over design requirement.

f. **Quick time-to-market and low cost**

VHDL and programmable logic pair will together to facilitate a speedy design process. VHDL permits design to be described quickly; programmable logic elements eliminate Non Recurring Expenses (NRE) and facilitate quick design iterations. Synthesis makes it all possible. VHDL and programmable logic combines as a powerful vehicle to bring the products to market in record time.

4.3 VHDL Design Process

The VHDL design process can be broken into six steps as given below

1. Define the design requirement
2. Describe the design in VHDL (formulate and code the design)
3. Simulate the source code
4. Synthesize, optimize and fit (place and route) the design
5. Simulate the post layout (fit) design model
6. Program the device

4.4 MAX + PLUS-II ---- The Synthesis Tool

MAX+PLUS – II is the tool used to transform the code written in VHDL to fit the design into the appropriate device. MAX+PLUS – II software consists of eleven application programs and MAX+PLUS – II manager. Compiler is one of the applications of MAX+PLUS – II for targeting the design to the required device. MAX+PLUS – II compiler consists of a series of modules and utility that check a design for errors, synthesize the logic, fit the design in one or more Altera device, generate output files for simulation, timing analysis and device programming.

4.4.1 Compilation process: -

The compiler first extracts information that defines the hierarchical connection between the design's different design files and checks the design for basic design errors. If the design is too large to fit into the device, the compiler can automatically partition it into multiple devices from the same design family, while minimizing the number of connection between the devices. A report file (.rpt) then shows how the design will be implemented in one or more devices. The MAX+PLUS – II compiler process a design with the following modules and utilities:

a. Compiler netlist extractor: -

The compiler netlist extractor converts each design file in the design into one or more binary Compiler Netlist Files (CNF).

b. Database builder: -

The database builder uses Hierarchy Interconnect File (HIF) to link CNF that describe the design.

c. Logic synthesizer: -

The logic synthesizer module applies a number of algorithms that reduce resource usage and remove redundant logic to ensure that the logical cell structure is used as efficiently as possible for architecture of the target family. This compiler module also applies logic synthesis techniques to implement user-specified timing and other implementation requirements.

d. Practitioner: -

If a design does not fit into a single device, the practitioner divides the database updated by the logic synthesizer into multiple devices from the same family attempting to split the design into smallest possible number of device.

e. Fitter: -

Using the database updated by the practitioner, the fitting matches the requirements of the design with known resources of one or more devices. It assigns each logic function to the best cell location and selects appropriate interconnection path and pin assignment.

4.5 PROGRAMMABLE LOGIC

Programmable logic denotes large and very large integrated circuits containing arrays of generalized logic blocks with user configurable interconnections. The user configures the device to define the function of each logic block and the interconnections between the logic blocks.

Programmable logic is divided into two broad categories.

1. Programmable logic devices (PLD's) .
2. Field programmable gate arrays (FPGA's).

The PLD's are often subdivided into Complex PLD's and Simpler PLD's.

4.5.1 PROGRAMMABLE LOGIC DEVICES

This class of circuits are widely used in LSI and VLSI design to implement two-level, sum of products, Boolean functions. The PLD's include programmable read only memory (PROM), programmable array logic (PAL) and programmable logic array(PLA).The basic difference between these PLD's are whether the AND and OR arrays are fixed or programmable. The AND-OR function is often implemented with NOR-NOR or NAND-NAND logic. PLD's have smaller densities.

4.5.2 COMPLEX PROGRAMMABLE LOGIC DEVICES (CPLD's)

CPLD's extend the capacity of PLD's to a higher level of integration to improve the system performance. They also use less board space, improve reliability and reduce cost. CPLD's consist of multiple logic blocks, the logic blocks communicate with one another via programmable interconnect. This architectural arrangement makes more efficient use of available silicon die area leading to better performance and reduced cost.

4.5.3 FIELD PROGRAMMABLE GATE ARRAYS(FPGA's):

A Field Programmable Gate Array is an array of logic that communicates with one another and with I/O via wires within the routing channels. In a FPGA, existing wire resources horizontal and vertical columns are connected through programmable elements. The architecture of FPGA is determined by the programmable switch technology used to configure it. Presently, there are two technologies of choice in developing FPGA's –SRAM and ANTIFUSE, each of which can satisfy a subset of market needs. SRAM allows the device to be reprogrammed any

number of times. Normally configurable data is located into SRAM type FPGA after power-on through either dedicated EPROM or a parallel port from host CPU. In case of ANTIFUSE technology, the device can be programmed only once. Although ANTIFUSE technology devices can be programmed only once, it offers higher density and speed compared to the SRAM counterpart.

The advantages using FPGA are :

1. Parts can be easily reprogrammed.
2. High production volume results in lower cost.
3. They can be dynamically reconfigured within the system.

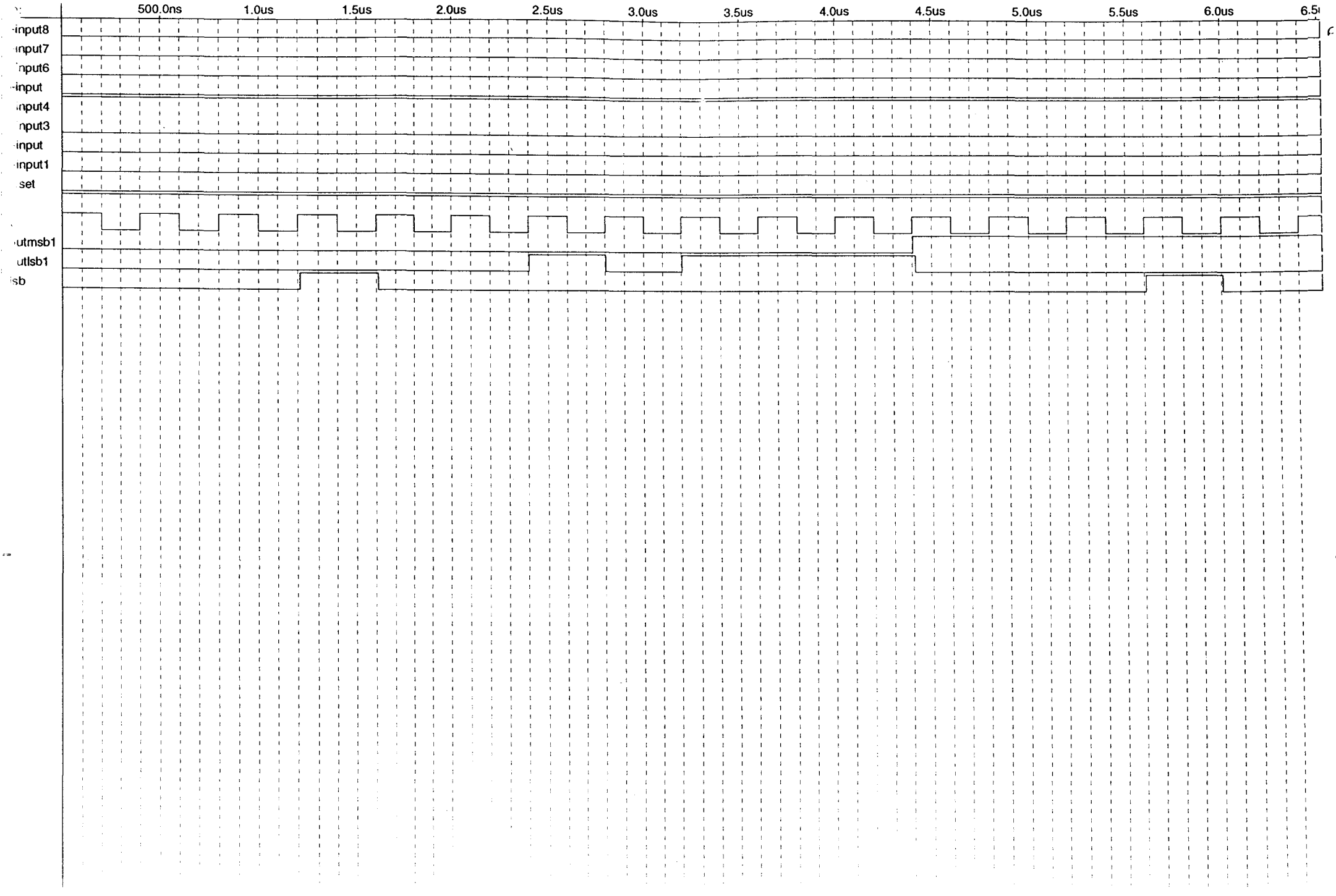
CHAPTER V
RESULTS
and
CONCLUSION

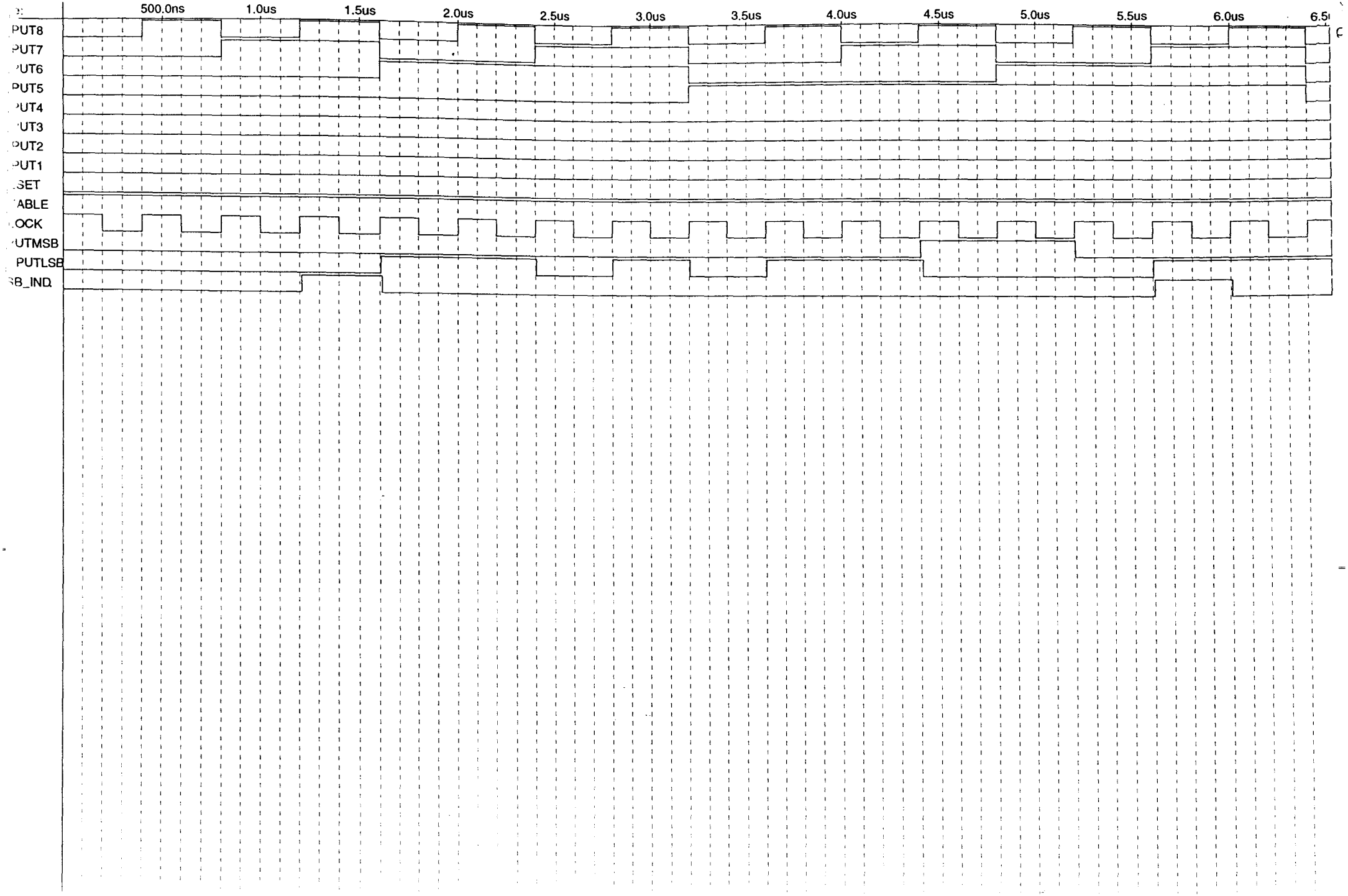
CONCLUSION

The goal of the project was to design the module for the calculation of DCT co-efficients at a rate faster than that of the scanning rate of an NTSC standard Television. This was satisfied at a clock rate of 15 MHz. The processing time of the module was found to be 10 clock cycles. The design was tested by simulation & waveforms were verified. The simulation results satisfy the design requirements to the best of our knowledge.

Scope for Further Improvement

The design could be changed to get the complete output i.e. the co-efficient value on a single output line rather than two as is being done presently.


500.0ns
1.0us
1.5us
2.0us
2.5us
3.0us
3.5us
4.0us
4.5us
5.0us
5.5us
6.0us
input8
input7
input6
input
input4
input3
input
input1
set
utmsb1
utlsb1
sb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PUT5
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UT3
PUT2
PUT1
SET
ABLE
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UTMSB
PUTLSB
B_IND

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APPENDIX

MAX 7000

Programmable Logic Device Family

November 2001, ver. 6.3 | Data Sheet

Features...

- High-performance, EEPROM-based programmable logic devices (PLDs) based on second-generation MAX® architecture
- 5.0-V in-system programmability (ISP) through the built-in IEEE Std. 1149.1 Joint Test Action Group (JTAG) interface available in MAX 7000S devices
  - ISP circuitry compatible with IEEE Std. 1532
- Includes 5.0-V MAX 7000 devices and 5.0-V ISP-based MAX 7000S devices
- Built-in JTAG boundary-scan test (BST) circuitry in MAX 7000S devices with 128 or more macrocells
- Complete EPLD family with logic densities ranging from 600 to 5,000 usable gates (see Tables 1 and 2)
- 5-ns pin-to-pin logic delays with up to 175.4-MHz counter frequencies (including interconnect)
- PCI-compliant devices available

For information on in-system programmable 3.3-V MAX 7000A or 2.5-V MAX 7000B devices, see the *MAX 7000A Programmable Logic Device Family Data Sheet* or the *MAX 7000B Programmable Logic Device Family Data Sheet.*

Table 1. MAX 7000 Device Features

Feature	EPM7032	EPM7064	EPM7096	EPM7128E	EPM7160E	EPM7192E	EPM7256E
Usable gates	600	1,250	1,800	2,500	3,200	3,750	5,000
Macrocells	32	64	96	128	160	192	256
Logic array blocks	2	4	6	8	10	12	16
Maximum user I/O pins	36	68	76	100	104	124	164
t_{PD} (ns)	6	6	7.5	7.5	10	12	12
t_{SU} (ns)	5	5	6	6	7	7	7
t_{FSU} (ns)	2.5	2.5	3	3	3	3	3
t_{CO1} (ns)	4	4	4.5	4.5	5	6	6
f_{CNT} (MHz)	151.5	151.5	125.0	125.0	100.0	90.9	90.9

Table 2. MAX 7000S Device Features

Feature	EPM7032S	EPM7064S	EPM7128S	EPM7160S	EPM7192S	EPM7256S
Usable gates	600	1,250	2,500	3,200	3,750	5,000
Macrocells	32	64	128	160	192	256
Logic array blocks	2	4	8	10	12	16
Maximum user I/O pins	36	68	100	104	124	164
t_{PD} (ns)	5	5	6	6	7.5	7.5
t_{SU} (ns)	2.9	2.9	3.4	3.4	4.1	3.9
t_{FSU} (ns)	2.5	2.5	2.5	2.5	3	3
t_{CO1} (ns)	3.2	3.2	4	3.9	4.7	4.7
f_{CNT} (MHz)	175.4	175.4	147.1	149.3	125.0	128.2

...and More Features

- Open-drain output option in MAX 7000S devices
- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable power-saving mode for a reduction of over 50% in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- 44 to 208 pins available in plastic J-lead chip carrier (PLCC), ceramic pin-grid array (PGA), plastic quad flat pack (PQFP), power quad flat pack (RQFP), and 1.0-mm thin quad flat pack (TQFP) packages
- Programmable security bit for protection of proprietary designs
- 3.3-V or 5.0-V operation
  - MultiVolt™ I/O interface operation, allowing devices to interface with 3.3-V or 5.0-V devices (MultiVolt I/O operation is not available in 44-pin packages)
  - Pin compatible with low-voltage MAX 7000A and MAX 7000B devices
- Enhanced features available in MAX 7000E and MAX 7000S devices
  - Six pin- or logic-driven output enable signals
  - Two global clock signals with optional inversion
  - Enhanced interconnect resources for improved routability
  - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
  - Programmable output slew-rate control
- Software design support and automatic place-and-route provided by Altera's development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
  - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
  - The BitBlaster™ serial download cable, ByteBlasterMV™ parallel port download cable, and MasterBlaster™ serial/universal serial bus (USB) download cable program MAX 7000S devices

General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) ***PCI Local Bus Specification, Revision*** 2.2. See Table 3 for available speed grades.

Table 3. MAX 7000 Speed Grades

Device	Speed Grade									
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		✓	✓		✓		✓	✓	✓	
EPM7032S	✓	✓	✓		✓					
EPM7064		✓	✓		✓		✓	✓		
EPM7064S	✓	✓	✓		✓					
EPM7096			✓		✓		✓	✓		
EPM7128E			✓	✓	✓		✓	✓		✓
EPM7128S		✓	✓		✓			✓		
EPM7160E				✓	✓		✓	✓		✓
EPM7160S		✓	✓		✓			✓		
EPM7192E						✓	✓	✓		✓
EPM7192S			✓		✓			✓		
EPM7256E						✓	✓	✓		✓
EPM7256S			✓		✓			✓		

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Table 4. MAX 7000 Device Features

Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			✓
JTAG BST circuitry			✓ *(1)*
Open-drain output option			✓
Fast input registers		✓	✓
Six global output enables		✓	✓
Two global clocks		✓	✓
Slew-rate control		✓	✓
MultiVolt interface *(2)*	✓	✓	✓
Programmable register	✓	✓	✓
Parallel expanders	✓	✓	✓
Shared expanders	✓	✓	✓
Power-saving mode	✓	✓	✓
Security bit	✓	✓	✓
PCI-compliant devices available	✓	✓	✓

Notes:
(1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.
(2) The MultiVolt I/O interface is not available in 44-pin packages.

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. The MAX 7000 architecture easily integrates multiple devices ranging from PALs, GALs, and 22V10s to MACH and pLSI devices. MAX 7000 devices are available in a wide range of packages, including PLCC, PGA, PQFP, RQFP, and TQFP packages. See Table 5.

Table 5. MAX 7000 Maximum User I/O Pins *Note (1)*

Device	44-Pin PLCC	44-Pin PQFP	44-Pin TQFP	68-Pin PLCC	84-Pin PLCC	100-Pin PQFP	100-Pin TQFP	160-Pin PQFP	160-Pin PGA	192-Pin PGA	208-Pin PQFP	208-Pin RQFP
EPM7032	36	36	36									
EPM7032S	36		36									
EPM7064	36		36	52	68	68						
EPM7064S	36		36		68		68					
EPM7096				52	64	76						
EPM7128E					68	84		100				
EPM7128S					68	84	84 *(2)*	100				
EPM7160E					64	84		104				
EPM7160S					64		84 *(2)*	104				
EPM7192E								124	124			
EPM7192S								124				
EPM7256E								132 *(2)*		164		164
EPM7256S											164 *(2)*	164

Notes:

(1) When the JTAG interface in MAX 7000S devices is used for either boundary-scan testing or for ISP, four I/O pins become JTAG pins.

(2) Perform a complete thermal analysis before committing a design to this device package. For more information, see the *Operating Requirements for Altera Devices Data Sheet*.

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

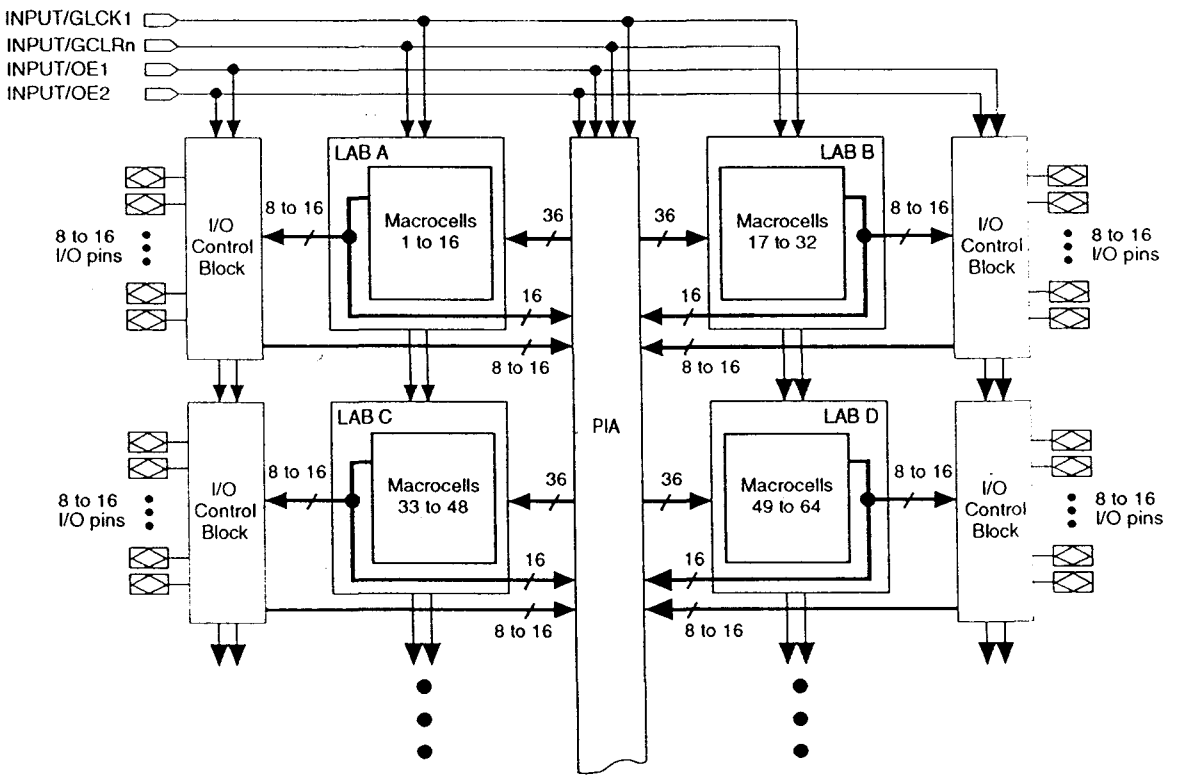
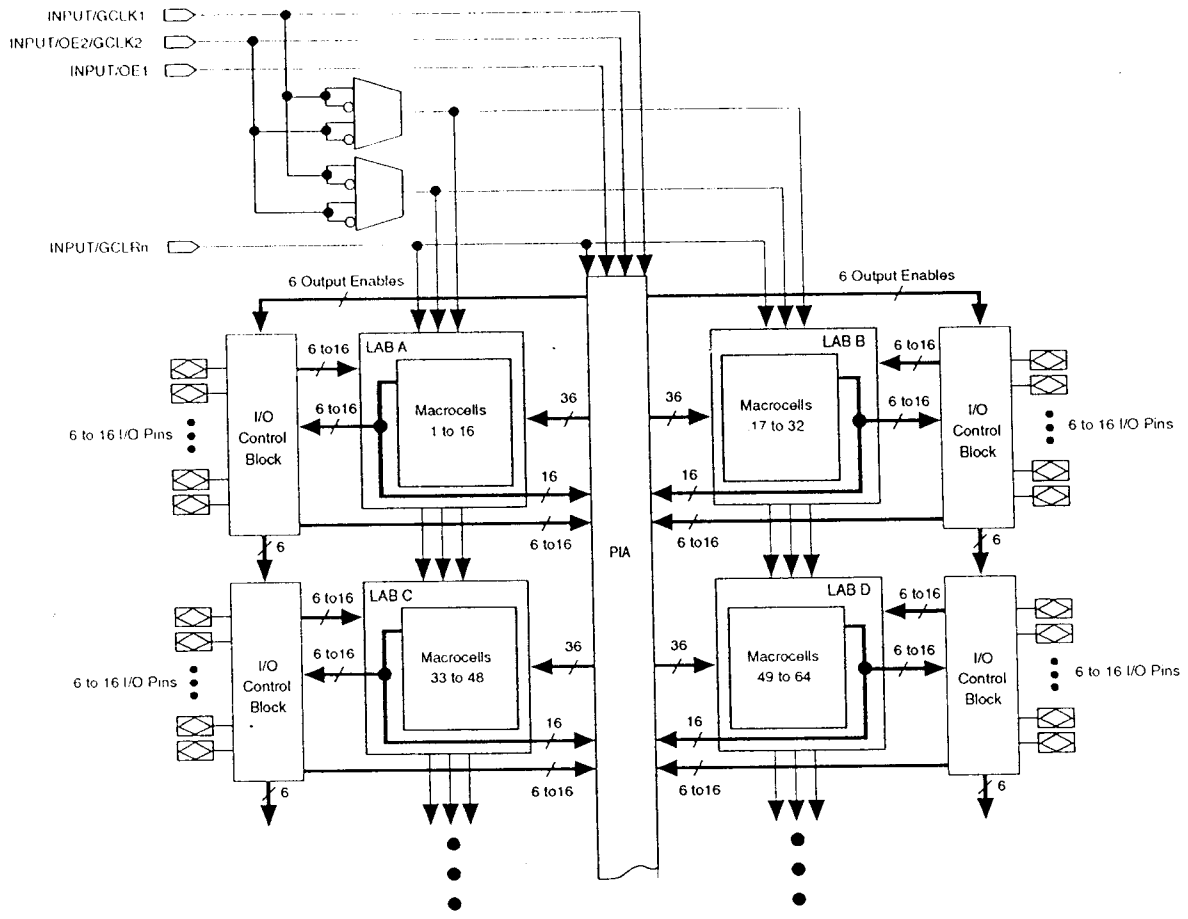


Figure 2 shows the architecture of MAX 7000E and MAX 7000S devices.

Figure 2. MAX 7000E & MAX 7000S Device Block Diagram



Logic Array Blocks

The MAX 7000 device architecture is based on the linking of high-performance, flexible, logic array modules called logic array blocks (LABs). LABs consist of 16-macrocell arrays, as shown in Figures 1 and 2. Multiple LABs are linked together via the programmable interconnect array (PIA), a global bus that is fed by all dedicated inputs, I/O pins, and macrocells.

Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell

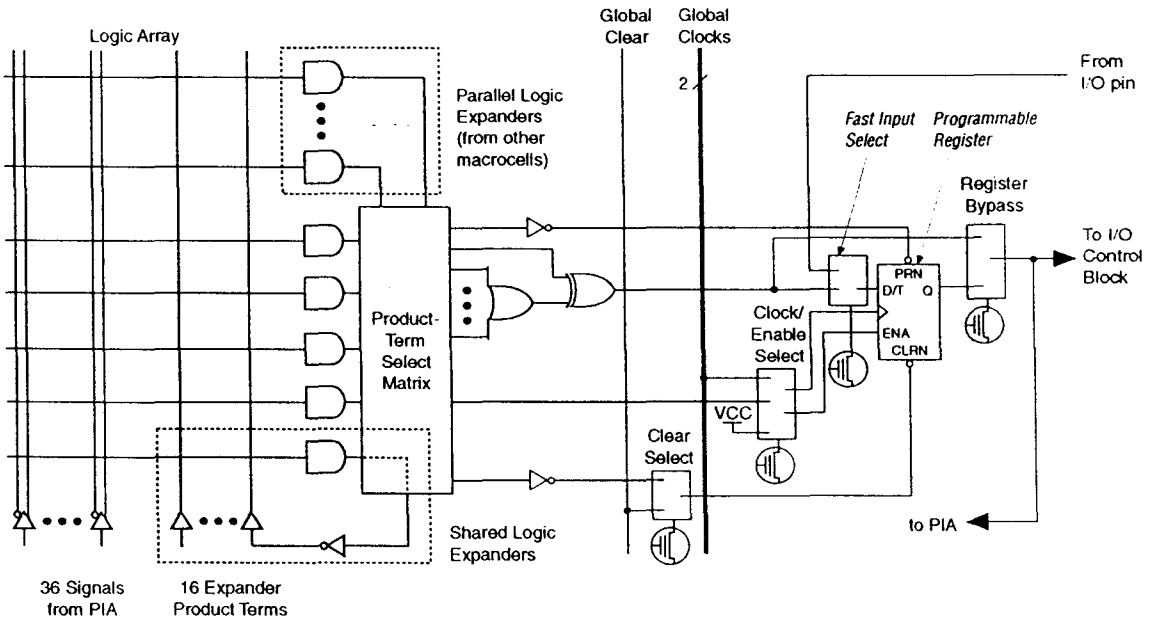
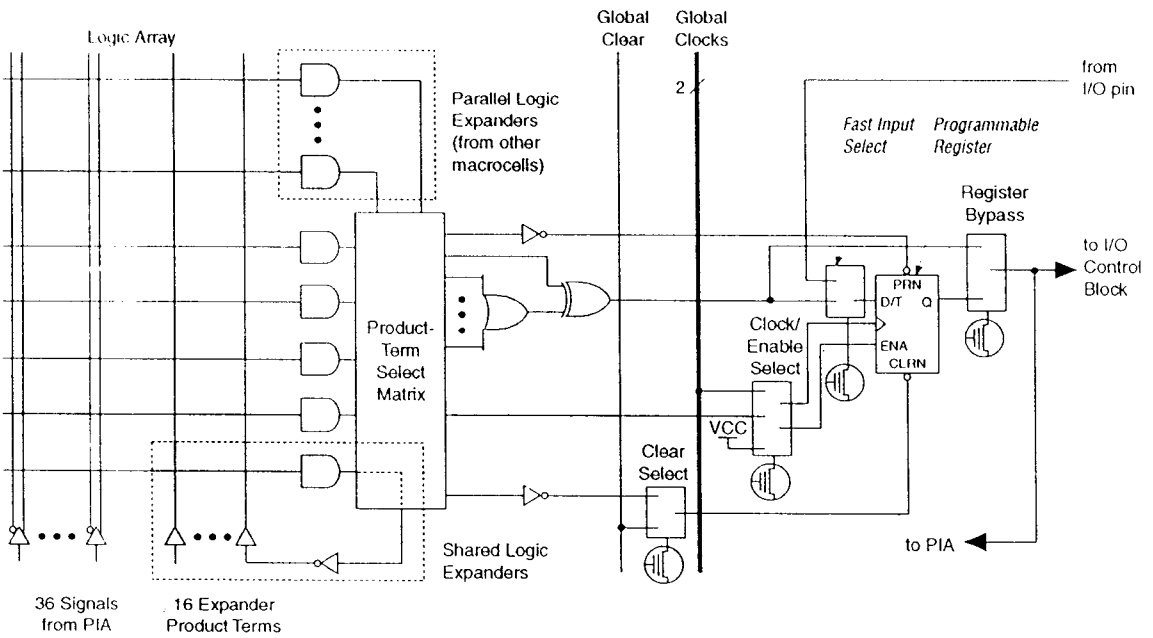


Figure 4 shows a MAX 7000E and MAX 7000S device macrocell.

Figure 4. MAX 7000E & MAX 7000S Device Macrocell



Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-to-output performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, GCLK1, as shown in Figure 1. In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in Figure 2, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

Expander Product Terms

Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms ("expanders") that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

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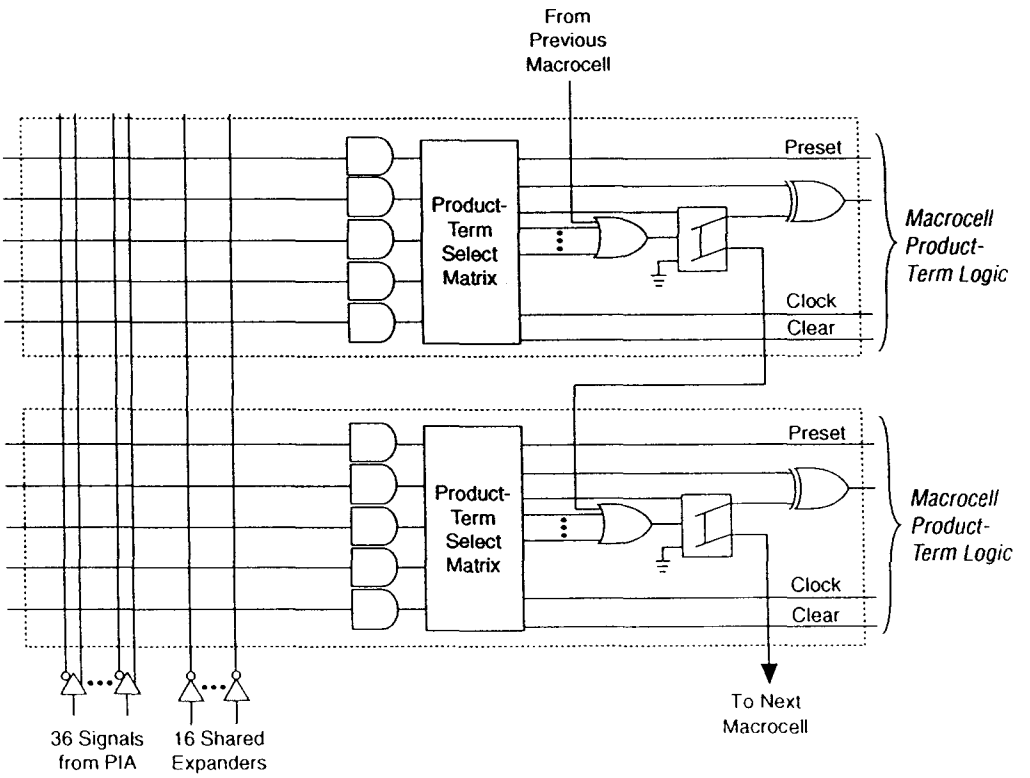
The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

Figure 6. Parallel Expanders

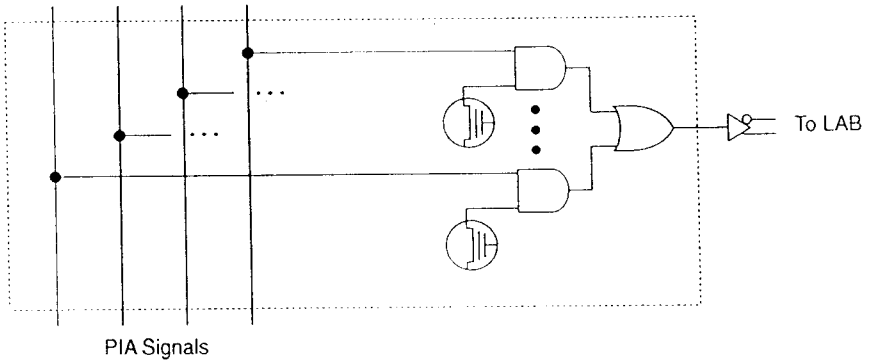
Unused product terms in a macrocell can be allocated to a neighboring macrocell.



Programmable Interconnect Array

Logic is routed between LABs via the programmable interconnect array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input **AND** gate, which selects a PIA signal to drive into the LAB.

Figure 7. PIA Routing



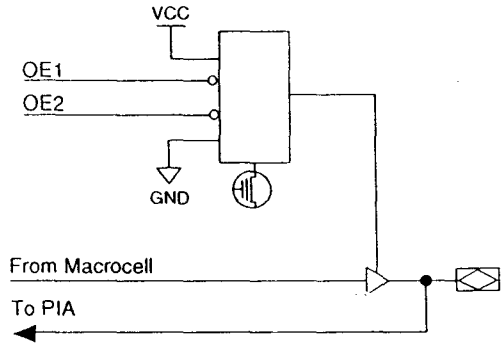
While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals and makes timing performance easy to predict.

I/O Control Blocks

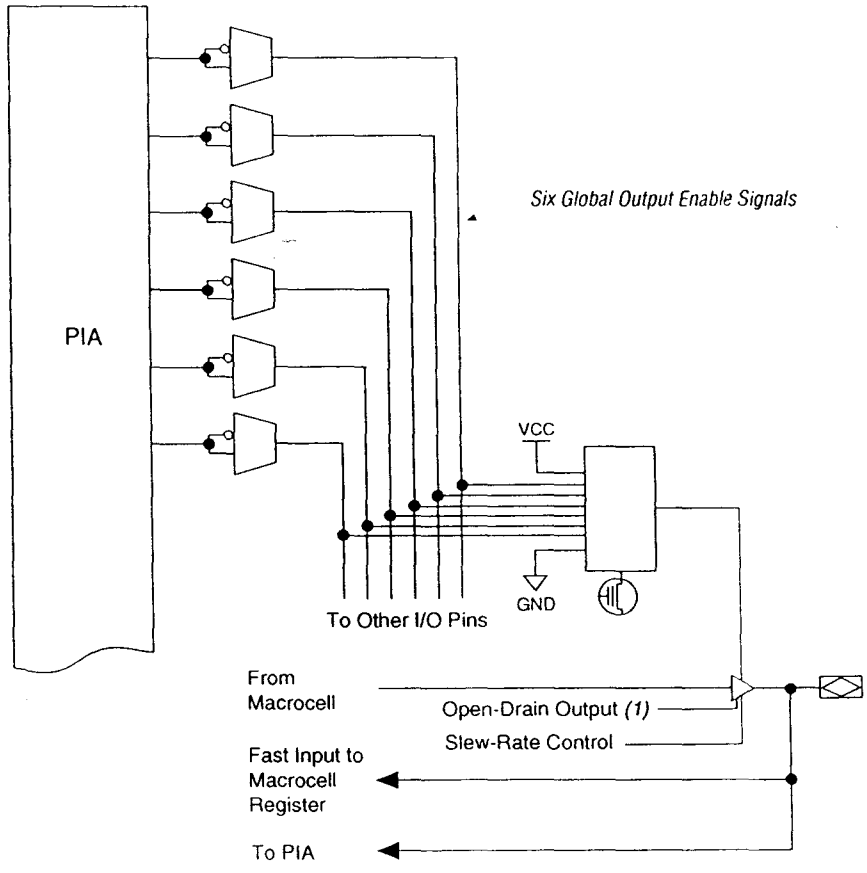
The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V_{CC}. Figure 8 shows the I/O control block for the MAX 7000 family. The I/O control block of EPM7032, EPM7064, and EPM7096 devices has two global output enable signals that are driven by two dedicated active-low output enable pins (OE1 and OE2). The I/O control block of MAX 7000E and MAX 7000S devices has six global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices



MAX 7000E & MAX 7000S Devices



Note:
(1) The open-drain output option is available only in MAX 7000S devices.

When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to V_{CC}, the output is enabled.

The MAX 7000 architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

In-System Programmability (ISP)

MAX 7000S devices are in-system programmable via an industry-standard 4-pin Joint Test Action Group (JTAG) interface (IEEE Std. 1149.1-1990). ISP allows quick, efficient iterations during design development and debugging cycles. The MAX 7000S architecture internally generates the high programming voltage required to program EEPROM cells, allowing in-system programming with only a single 5.0 V power supply. During in-system programming, the I/O pins are tri-stated and pulled-up to eliminate board conflicts. The pull-up value is nominally 50 kΩ.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a printed circuit board with standard in-circuit test equipment before they are programmed. MAX 7000S devices can be programmed by downloading the information via in-circuit testers (ICT), embedded processors, or the Altera MasterBlaster, ByteBlasterMV, ByteBlaster, BitBlaster download cables. (The ByteBlaster cable is obsolete and is replaced by the ByteBlasterMV cable, which can program and configure 2.5-V, 3.3-V, and 5.0-V devices.) Programming the devices after they are placed on the board eliminates lead damage on high-pin-count packages (e.g., QFP packages) due to device handling and allows devices to be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. Because some in-circuit testers cannot support an adaptive algorithm, Altera offers devices tested with a constant algorithm. Devices tested to the constant algorithm are marked with an "F" suffix in the ordering code.

The Jam™ Standard Test and Programming Language (STAPL) can be used to program MAX 7000S devices with in-circuit testers, PCs, or embedded processor.

For more information on using the Jam language, see *Application Note 88 (Using the Jam Language for ISP & ICR via an Embedded Processor)*.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo Bit™ option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, and t_{SEXP}, t_{ACL}, and t_{CPPW} parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V V_{CCINT} level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When V_{CCIO} is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1}.

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When V_{CCIO} is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When V_{CCIO} is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.

For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.

For more information, see the *Programming Hardware Manufacturers*.

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. Table 6 describes the JTAG instructions supported by the MAX 7000 family. The pin-out tables (see the Altera web site (**http://www.altera.com**) or the *Altera Digital Library* for pin-out information) show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 6. MAX 7000 JTAG Instructions

JTAG Instruction	Devices	Description
SAMPLE/PRELOAD	EPM7128S EPM7160S EPM7192S EPM7256S	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	EPM7128S EPM7160S EPM7192S EPM7256S	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ISP Instructions	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	These instructions are used when programming MAX 7000S devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, BitBlaster download cable, or using a Jam File (**.jam**), Jam Byte-Code file (**.jbc**), or Serial Vector Format file (**.svf**) via an embedded processor or test equipment.

The instruction register length of MAX 7000S devices is 10 bits. Tables 7 and 8 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

Table 7. MAX 7000S Boundary-Scan Register Length

Device	Boundary-Scan Register Length
EPM7032S	1 (1)
EPM7064S	1 (1)
EPM7128S	288
EPM7160S	312
EPM7192S	360
EPM7256S	480

Note:
(1) This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

Table 8. 32-Bit MAX 7000 Device IDCODE *Note (1)*

Device	IDCODE (32 Bits)			
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)
EPM7032S	0000	0111 0000 0011 0010	00001101110	1
EPM7064S	0000	0111 0000 0110 0100	00001101110	1
EPM7128S	0000	0111 0001 0010 1000	00001101110	1
EPM7160S	0000	0111 0001 0110 0000	00001101110	1
EPM7192S	0000	0111 0001 1001 0010	00001101110	1
EPM7256S	0000	0111 0010 0101 0110	00001101110	1

Notes:
(1) The most significant bit (MSB) is on the left.
(2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

Figure 9 shows the timing requirements for the JTAG signals.

Figure 9. MAX 7000 JTAG Waveforms

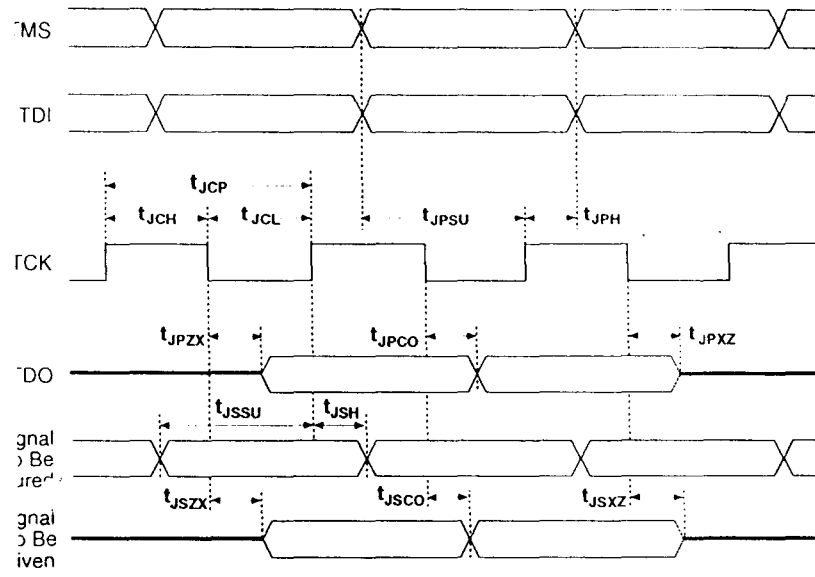


Table 9 shows the JTAG timing parameters and values for MAX 7000S devices.

Table 9. JTAG Timing Parameters & Values for MAX 7000S Devices

Symbol	Parameter	Min	Max	Unit
t_{JCP}	TCK clock period	100		ns
t_{JCH}	TCK clock high time	50		ns
t_{JCL}	TCK clock low time	50		ns
t_{JPSU}	JTAG port setup time	20		ns
t_{JPH}	JTAG port hold time	45		ns
t_{JPCO}	JTAG port clock to output		25	ns
t_{JPZX}	JTAG port high impedance to valid output		25	ns
t_{JPXZ}	JTAG port valid output to high impedance		25	ns
t_{JSSU}	Capture register setup time	20		ns
t_{JSH}	Capture register hold time	45		ns
t_{JSCO}	Update register clock to output		25	ns
t_{JSZX}	Update register high impedance to valid output		25	ns
t_{JSXZ}	Update register valid output to high impedance		25	ns

For more information, see *Application Note 39 (IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices)*.

Design Security

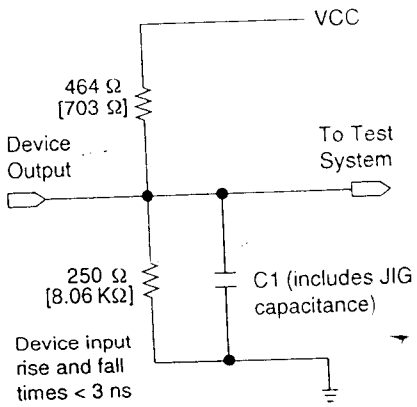
All MAX 7000 devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a proprietary design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

Generic Testing

Each MAX 7000 device is functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 10. Test patterns can be used and then erased during early stages of the production flow.

Figure 10. MAX 7000 AC Test Conditions

Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result. Numbers in brackets are for 2.5-V devices and outputs. Numbers without brackets are for 3.3-V devices and outputs.



QFP Carrier & Development Socket

MAX 7000 and MAX 7000E devices in QFP packages with 100 or more pins are shipped in special plastic carriers to protect the QFP leads. The carrier is used with a prototype development socket and special programming hardware available from Altera. This carrier technology makes it possible to program, test, erase, and reprogram a device without exposing the leads to mechanical stress.

For detailed information and carrier dimensions, refer to the *QFP Carrier & Development Socket Data Sheet*.

MAX 7000S devices are not shipped in carriers.

Operating Conditions

Tables 10 through 15 provide information about absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for 5.0-V MAX 7000 devices.

Table 10. MAX 7000 5.0-V Device Absolute Maximum Ratings *Note (1)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply voltage	With respect to ground *(2)*	–2.0	7.0	V
V_I	DC input voltage		–2.0	7.0	V
I_{OUT}	DC output current, per pin		–25	25	mA
T_{STG}	Storage temperature	No bias	–65	150	° C
T_{AMB}	Ambient temperature	Under bias	–65	135	° C
T_J	Junction temperature	Ceramic packages, under bias		150	° C
		PQFP and RQFP packages, under bias		135	° C

Table 11. MAX 7000 5.0-V Device Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	*(3)*, *(4)*	4.75 (4.50)	5.25 (5.50)	V
V_{CCIO}	Supply voltage for output drivers, 5.0-V operation	*(3)*, *(4)*	4.75 (4.50)	5.25 (5.50)	V
	Supply voltage for output drivers, 3.3-V operation	*(3)*, *(4)*, *(5)*	3.00 (3.00)	3.60 (3.60)	V
V_{CCISP}	Supply voltage during ISP	*(6)*	4.75	5.25	V
V_I	Input voltage		–0.5 *(7)*	V_{CCINT} + 0.5	V
V_O	Output voltage		0	V_{CCIO}	V
T_A	Ambient temperature	For commercial use	0	70	° C
		For industrial use	–40	85	° C
T_J	Junction temperature	For commercial use	0	90	° C
		For industrial use	–40	105	° C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

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T_{AMB}	Ambient temperature	Under bias	–65	135	° C
T_J	Junction temperature	Ceramic packages, under bias		150	° C
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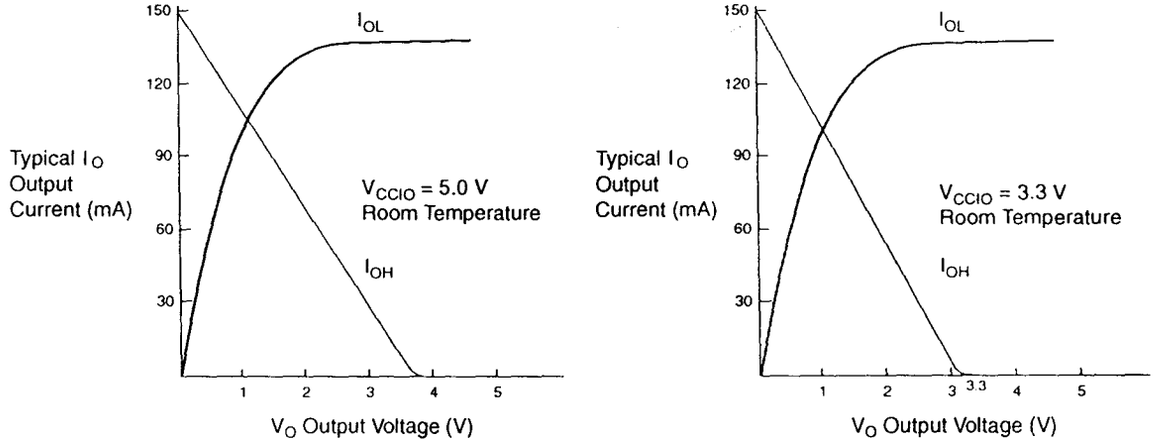
	Supply voltage for output drivers, 3.3-V operation	*(3)*, *(4)*, *(5)*	3.00 (3.00)	3.60 (3.60)	V
V_{CCISP}	Supply voltage during ISP	*(6)*	4.75	5.25	V
V_I	Input voltage		–0.5 *(7)*	V_{CCINT} + 0.5	V
V_O	Output voltage		0	V_{CCIO}	V
T_A	Ambient temperature	For commercial use	0	70	° C
		For industrial use	–40	85	° C
T_J	Junction temperature	For commercial use	0	90	° C
		For industrial use	–40	105	° C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

Notes to tables:

(1) See the *Operating Requirements for Altera Devices Data Sheet*.
(2) Minimum DC input voltage on I/O pins is –0.5 V and on 4 dedicated input pins is –0.3 V. During transitions, the inputs may undershoot to –2.0 V or overshoot to 7.0 V for input currents less than 100 mA and periods shorter than 20 ns.
(3) Numbers in parentheses are for industrial-temperature-range devices.
(4) V_{CC} must rise monotonically.
(5) 3.3-V I/O operation is not available for 44-pin packages.
(6) The V_{CCISP} parameter applies only to MAX 7000S devices.
(7) During in-system programming, the minimum DC input voltage is –0.3 V.
(8) These values are specified under the MAX 7000 recommended operating conditions in Table 11 on page 23.
(9) The parameter is measured with 50% of the outputs each sourcing the specified current. The I_{OH} parameter refers to high-level TTL or CMOS output current.
(10) The parameter is measured with 50% of the outputs each sinking the specified current. The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current.
(11) When the JTAG interface is enabled in MAX 7000S devices, the input leakage current on the JTAG pins is typically –60 µA.
(12) Capacitance is measured at 25° C and is sample-tested only. The OE1 pin has a maximum capacitance of 20 pF.

Figure 11 shows the typical output drive characteristics of MAX 7000 devices.

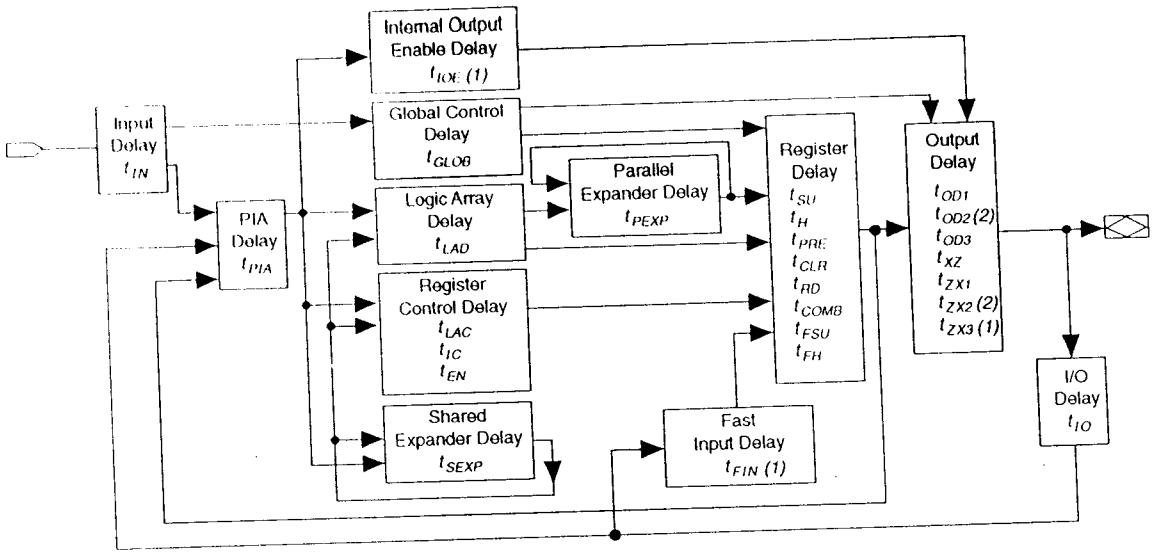
Figure 11. Output Drive Characteristics of 5.0-V MAX 7000 Devices



Timing Model

MAX 7000 device timing can be analyzed with the Altera software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 12. MAX 7000 devices have fixed internal delays that enable the designer to determine the worst-case timing of any design. The Altera software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for a device-wide performance evaluation.

Figure 12. MAX 7000 Timing Model



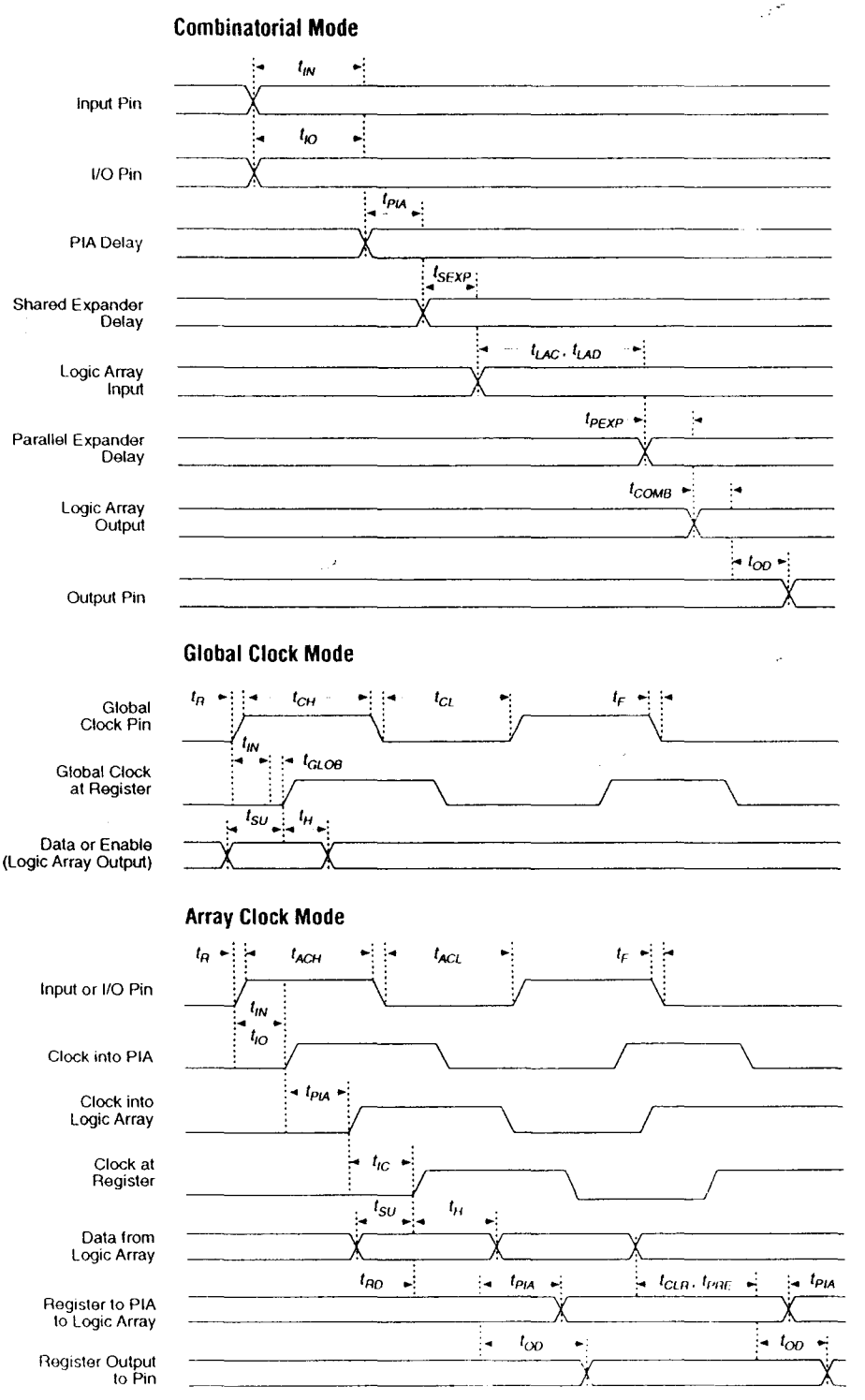
Notes:
(1) Only available in MAX 7000E and MAX 7000S devices.
(2) Not available in 44-pin devices.

The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 13 shows the internal timing relationship of internal and external delay parameters.

For more infomration, see *Application Note 94 (Understanding MAX 7000 Timing)*.

Figure 13. Switching Waveforms

t_R & t_F < 3 ns. Inputs are driven at 3 V for a logic high and 0 V for a logic low. All timing characteristics are measured at 1.5 V.



Tables 16 through 23 show the MAX 7000 and MAX 7000E AC operating conditions.

Table 16. MAX 7000 & MAX 7000E External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	-6 Speed Grade		-7 Speed Grade		Unit
			Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t_{SU}	Global clock setup time		5.0		6.0		ns
t_{H}	Global clock hold time		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input	*(2)*	2.5		3.0		ns
t_{FH}	Global clock hold time of fast input	*(2)*	0.5		0.5		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns
t_{CH}	Global clock high time		2.5		3.0		ns
t_{CL}	Global clock low time		2.5		3.0		ns
t_{ASU}	Array clock setup time		2.5		3.0		ns
t_{AH}	Array clock hold time		2.0		2.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns
t_{ACH}	Array clock high time		3.0		3.0		ns
t_{ACL}	Array clock low time		3.0		3.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(3)*	3.0		3.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(4)*	1.0		1.0		ns
t_{CNT}	Minimum global clock period			6.6		8.0	ns
f_{CNT}	Maximum internal global clock frequency	*(5)*	151.5		125.0		MHz
t_{ACNT}	Minimum array clock period			6.6		8.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(5)*	151.5		125.0		MHz
f_{MAX}	Maximum clock frequency	*(6)*	200		166.7		MHz

Table 17. MAX 7000 & MAX 7000E Internal Timing Parameters *Notes (1)*

Symbol	Parameter	Conditions	Speed Grade -6		Speed Grade -7		Unit
			Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.4		0.5	ns
t_{IO}	I/O input pad and buffer delay			0.4		0.5	ns
t_{FIN}	Fast input delay	*(2)*		0.8		1.0	ns
t_{SEXP}	Shared expander delay			3.5		4.0	ns
t_{PEXP}	Parallel expander delay			0.8		0.8	ns
t_{LAD}	Logic array delay			2.0		3.0	ns
t_{LAC}	Logic control array delay			2.0		3.0	ns
t_{IOE}	Internal output enable delay	*(2)*				2.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off, V_{CCIO} = 5.0 V	C1 = 35 pF		2.0		2.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off, V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		2.5		2.5	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on, V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		7.0		7.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off, V_{CCIO} = 5.0 V	C1 = 35 pF		4.0		4.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off, V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		4.5		4.5	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0	ns
t_{SU}	Register setup time		3.0		3.0		ns
t_{H}	Register hold time		1.5		2.0		ns
t_{FSU}	Register setup time of fast input	*(2)*	2.5		3.0		ns
t_{FH}	Register hold time of fast input	*(2)*	0.5		0.5		ns
t_{RD}	Register delay			0.8		1.0	ns
t_{COMB}	Combinatorial delay			0.8		1.0	ns
t_{IC}	Array clock delay			2.5		3.0	ns
t_{EN}	Register enable time			2.0		3.0	ns
t_{GLOB}	Global control delay			0.8		1.0	ns
t_{PRE}	Register preset time			2.0		2.0	ns
t_{CLR}	Register clear time			2.0		2.0	ns
t_{PIA}	PIA delay			0.8		1.0	ns
t_{LPA}	Low-power adder	*(8)*		10.0		10.0	ns

Table 18. MAX 7000 & MAX 7000E External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-10P)		MAX 7000 (-10) MAX 7000E (-10)		
			Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		10.0		10.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		10.0		10.0	ns
t_{SU}	Global clock setup time		7.0		8.0		ns
t_{H}	Global clock hold time		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input	*(2)*	3.0		3.0		ns
t_{FH}	Global clock hold time of fast input	*(2)*	0.5		0.5		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		5.0		5	ns
t_{CH}	Global clock high time		4.0		4.0		ns
t_{CL}	Global clock low time		4.0		4.0		ns
t_{ASU}	Array clock setup time		2.0		3.0		ns
t_{AH}	Array clock hold time		3.0		3.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		10.0		10.0	ns
t_{ACH}	Array clock high time		4.0		4.0		ns
t_{ACL}	Array clock low time		4.0		4.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(3)*	4.0		4.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(4)*	1.0		1.0		ns
t_{CNT}	Minimum global clock period			10.0		10.0	ns
f_{CNT}	Maximum internal global clock frequency	*(5)*	100.0		100.0		MHz
t_{ACNT}	Minimum array clock period			10.0		10.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(5)*	100.0		100.0		MHz
f_{MAX}	Maximum clock frequency	*(6)*	125.0		125.0		MHz

Table 19. MAX 7000 & MAX 7000E Internal Timing Parameters Note (1)

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-10P)		MAX 7000 (-10) MAX 7000E (-10)		
			Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.5		1.0	ns
t_{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t_{FIN}	Fast input delay	(2)		1.0		1.0	ns
t_{SEXP}	Shared expander delay			5.0		5.0	ns
t_{PEXP}	Parallel expander delay			0.8		0.8	ns
t_{LAD}	Logic array delay			5.0		5.0	ns
t_{LAC}	Logic control array delay			5.0		5.0	ns
t_{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		2.5	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.5		6.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF (7)		5.5		5.5	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t_{SU}	Register setup time		2.0		3.0		ns
t_{H}	Register hold time		3.0		3.0		ns
t_{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns
t_{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t_{RD}	Register delay			2.0		1.0	ns
t_{COMB}	Combinatorial delay			2.0		1.0	ns
t_{IC}	Array clock delay			5.0		5.0	ns
t_{EN}	Register enable time			5.0		5.0	ns
t_{GLOB}	Global control delay			1.0		1.0	ns
t_{PRE}	Register preset time			3.0		3.0	ns
t_{CLR}	Register clear time			3.0		3.0	ns
t_{PIA}	PIA delay			1.0		1.0	ns
t_{LPA}	Low-power adder	(8)		11.0		11.0	ns

Table 20. MAX 7000 & MAX 7000E External Timing Parameters Note (1)

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-12P)		MAX 7000 (-12) MAX 7000E (-12)		
			Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		12.0		12.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		12.0		12.0	ns
t_{SU}	Global clock setup time		7.0		10.0		ns
t_{H}	Global clock hold time		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns
t_{FH}	Global clock hold time of fast input	(2)	0.0		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		6.0		6.0	ns
t_{CH}	Global clock high time		4.0		4.0		ns
t_{CL}	Global clock low time		4.0		4.0		ns
t_{ASU}	Array clock setup time		3.0		4.0		ns
t_{AH}	Array clock hold time		4.0		4.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		12.0		12.0	ns
t_{ACH}	Array clock high time		5.0		5.0		ns
t_{ACL}	Array clock low time		5.0		5.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	(3)	5.0		5.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t_{CNT}	Minimum global clock period			11.0		11.0	ns
f_{CNT}	Maximum internal global clock frequency	(5)	90.9		90.9		MHz
t_{ACNT}	Minimum array clock period			11.0		11.0	ns
f_{ACNT}	Maximum internal array clock frequency	(5)	90.9		90.9		MHz
f_{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz

Table 21. MAX 7000 & MAX 7000E Internal Timing Parameters Note (1)

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-12P)		MAX 7000 (-12) MAX 7000E (-12)		
			Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			1.0		2.0	ns
t_{IO}	I/O input pad and buffer delay			1.0		2.0	ns
t_{FIN}	Fast input delay	(2)		1.0		1.0	ns
t_{SEXP}	Shared expander delay			7.0		7.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.0	ns
t_{LAD}	Logic array delay			7.0		5.0	ns
t_{LAC}	Logic control array delay			5.0		5.0	ns
t_{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		1.0		3.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		4.0	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.0		7.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF (7)		7.0		7.0	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns
t_{SU}	Register setup time		1.0		4.0		ns
t_{H}	Register hold time		6.0		4.0		ns
t_{FSU}	Register setup time of fast input	(2)	4.0		2.0		ns
t_{FH}	Register hold time of fast input	(2)	0.0		2.0		ns
t_{RD}	Register delay			2.0		1.0	ns
t_{COMB}	Combinatorial delay			2.0		1.0	ns
t_{IC}	Array clock delay			5.0		5.0	ns
t_{EN}	Register enable time			7.0		5.0	ns
t_{GLOB}	Global control delay			2.0		0.0	ns
t_{PRE}	Register preset time			4.0		3.0	ns
t_{CLR}	Register clear time			4.0		3.0	ns
t_{PIA}	PIA delay			1.0		1.0	ns
t_{LPA}	Low-power adder	(8)		12.0		12.0	ns

Table 22. MAX 7000 & MAX 7000E External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t_{SU}	Global clock setup time		11.0		11.0		12.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input	*(2)*	3.0		–		5.0		ns
t_{FH}	Global clock hold time of fast input	*(2)*	0.0		–		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t_{CH}	Global clock high time		5.0		6.0		6.0		ns
t_{CL}	Global clock low time		5.0		6.0		6.0		ns
t_{ASU}	Array clock setup time		4.0		4.0		5.0		ns
t_{AH}	Array clock hold time		4.0		4.0		5.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t_{ACH}	Array clock high time		6.0		6.5		8.0		ns
t_{ACL}	Array clock low time		6.0		6.5		8.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(3)*	6.0		6.5		8.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(4)*	1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			13.0		13.0		16.0	ns
f_{CNT}	Maximum internal global clock frequency	*(5)*	76.9		76.9		62.5		MHz
t_{ACNT}	Minimum array clock period			13.0		13.0		16.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(5)*	76.9		76.9		62.5		MHz
f_{MAX}	Maximum clock frequency	*(6)*	100		83.3		83.3		MHz

Table 23. MAX 7000 & MAX 7000E Internal Timing Parameters *Notes (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			2.0		2.0		3.0	ns
t_{IO}	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t_{FIN}	Fast input delay	*(2)*		2.0		–		4.0	ns
t_{SEXP}	Shared expander delay			8.0		10.0		9.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.0		2.0	ns
t_{LAD}	Logic array delay			6.0		6.0		8.0	ns
t_{LAC}	Logic control array delay			6.0		6.0		8.0	ns
t_{IOE}	Internal output enable delay	*(2)*		3.0		–		4.0	ns
t_{OD1}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		4.0		4.0		5.0	ns
t_{OD2}	Output buffer and pad delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		5.0		–		6.0	ns
t_{OD3}	Output buffer and pad delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		8.0		–		9.0	ns
t_{ZX1}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0		10.0	ns
t_{ZX2}	Output buffer enable delay Slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF *(7)*		7.0		–		11.0	ns
t_{ZX3}	Output buffer enable delay Slow slew rate = on V_{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF *(2)*		10.0		–		14.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0		10.0	ns
t_{SU}	Register setup time		4.0		4.0		4.0		ns
t_{H}	Register hold time		4.0		4.0		5.0		ns
t_{FSU}	Register setup time of fast input	*(2)*	2.0		–		4.0		ns
t_{FH}	Register hold time of fast input	*(2)*	2.0		–		3.0		ns
t_{RD}	Register delay			1.0		1.0		1.0	ns
t_{COMB}	Combinatorial delay			1.0		1.0		1.0	ns
t_{IC}	Array clock delay			6.0		6.0		8.0	ns
t_{EN}	Register enable time			6.0		6.0		8.0	ns
t_{GLOB}	Global control delay			1.0		1.0		3.0	ns
t_{PRE}	Register preset time			4.0		4.0		4.0	ns
t_{CLR}	Register clear time			4.0		4.0		4.0	ns
t_{PIA}	PIA delay			2.0		2.0		3.0	ns
t_{LPA}	Low-power adder	*(8)*		13.0		15.0		15.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 11. See Figure 13 for more information on switching waveforms.
(2) This parameter applies to MAX 7000E devices only.
(3) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
(4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
(5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
(6) The f_{MAX} values represent the highest frequency for pipelined data.
(7) Operating conditions: V_{CCIO} = 3.3 V ± 10% for commercial and industrial use.
(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, t_{ACL}, and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 24 and 25 show the EPM7032S AC operating conditions.

Table 24. EPM7032S External Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t_{SU}	Global clock setup time		2.9		4.0		5.0		7.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t_{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t_{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t_{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t_{ASU}	Array clock setup time		0.7		0.9		1.1		2.0		ns
t_{AH}	Array clock hold time		1.8		2.1		2.7		3.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t_{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t_{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(2)*	2.5		2.5		3.0		4.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(3)*	1.0		1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f_{CNT}	Maximum internal global clock frequency	*(4)*	175.4		142.9		116.3		100.0		MHz
t_{ACNT}	Minimum array clock period			5.7		7.0		8.6		10.0	ns

Table 24. EPM7032S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
f_{ACNT}	Maximum internal array clock frequency	*(4)*	175.4		142.9		116.3		100.0		MHz
f_{MAX}	Maximum clock frequency	*(5)*	250.0		200.0		166.7		125.0		MHz

Table 25. EPM7032S Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t_{IO}	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t_{FIN}	Fast input delay			2.2		2.1		2.5		1.0	ns
t_{SEXP}	Shared expander delay			3.1		3.8		4.6		5.0	ns
t_{PEXP}	Parallel expander delay			0.9		1.1		1.4		0.8	ns
t_{LAD}	Logic array delay			2.6		3.3		4.0		5.0	ns
t_{LAC}	Logic control array delay			2.5		3.3		4.0		5.0	ns
t_{IOE}	Internal output enable delay			0.7		0.8		1.0		2.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF *(6)*		0.7		0.8		0.9		2.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF *(6)*		4.5		4.5		4.5		5.5	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t_{SU}	Register setup time		0.8		1.0		1.3		2.0		ns
t_{H}	Register hold time		1.7		2.0		2.5		3.0		ns
t_{FSU}	Register setup time of fast input		1.9		1.8		1.7		3.0		ns
t_{FH}	Register hold time of fast input		0.6		0.7		0.8		0.5		ns
t_{RD}	Register delay			1.2		1.6		1.9		2.0	ns
t_{COMB}	Combinatorial delay			0.9		1.1		1.4		2.0	ns
t_{IC}	Array clock delay			2.7		3.4		4.2		5.0	ns
t_{EN}	Register enable time			2.6		3.3		4.0		5.0	ns
t_{GLOB}	Global control delay			1.6		1.4		1.7		1.0	ns
t_{PRE}	Register preset time			2.0		2.4		3.0		3.0	ns

Table 25. EPM7032S Internal Timing Parameters Note (1)

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{CLR}	Register clear time			2.0		2.4		3.0		3.0	ns
t_{PIA}	PIA delay	(7)		1.1		1.1		1.4		1.0	ns
t_{LPA}	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 11. See Figure 13 for more information on switching waveforms.

(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.

(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(5) The f_{MAX} values represent the highest frequency for pipelined data.

(6) Operating conditions: $V_{CCIO} = 3.3\ V \pm 10\%$ for commercial and industrial use.

(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, t_{ACL}, and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 26 and 27 show the EPM7064S AC operating conditions.

Table 26. EPM7064S External Timing Parameters (Part 1 of 2) Note (1)

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t_{SU}	Global clock setup time		2.9		3.6		6.0		7.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns
t_{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns
t_{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t_{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t_{ASU}	Array clock setup time		0.7		0.9		3.0		2.0		ns

Table 26. EPM7064S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{AH}	Array clock hold time		1.8		2.1		2.0		3.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
t_{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t_{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(2)*	2.5		2.5		3.0		4.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(3)*	1.0		1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			5.7		7.1		8.0		10.0	ns
f_{CNT}	Maximum internal global clock frequency	*(4)*	175.4		140.8		125.0		100.0		MHz
t_{ACNT}	Minimum array clock period			5.7		7.1		8.0		10.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(4)*	175.4		140.8		125.0		100.0		MHz
f_{MAX}	Maximum clock frequency	*(5)*	250.0		200.0		166.7		125.0		MHz

Table 27. EPM7064S Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t_{IO}	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t_{FIN}	Fast input delay			2.2		2.6		1.0		1.0	ns
t_{SEXP}	Shared expander delay			3.1		3.8		4.0		5.0	ns
t_{PEXP}	Parallel expander delay			0.9		1.1		0.8		0.8	ns
t_{LAD}	Logic array delay			2.6		3.2		3.0		5.0	ns
t_{LAC}	Logic control array delay			2.5		3.2		3.0		5.0	ns
t_{IOE}	Internal output enable delay			0.7		0.8		2.0		2.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF *(6)*		0.7		0.8		2.5		2.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF *(6)*		4.5		4.5		4.5		5.5	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t_{SU}	Register setup time		0.8		1.0		3.0		2.0		ns

Table 27. EPM7064S Internal Timing Parameters (Part 2 of 2) Note (1)

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{H}	Register hold time		1.7		2.0		2.0		3.0		ns
t_{FSU}	Register setup time of fast input		1.9		1.8		3.0		3.0		ns
t_{FH}	Register hold time of fast input		0.6		0.7		0.5		0.5		ns
t_{RD}	Register delay			1.2		1.6		1.0		2.0	ns
t_{COMB}	Combinatorial delay			0.9		1.0		1.0		2.0	ns
t_{IC}	Array clock delay			2.7		3.3		3.0		5.0	ns
t_{EN}	Register enable time			2.6		3.2		3.0		5.0	ns
t_{GLOB}	Global control delay			1.6		1.9		1.0		1.0	ns
t_{PRE}	Register preset time			2.0		2.4		2.0		3.0	ns
t_{CLR}	Register clear time			2.0		2.4		2.0		3.0	ns
t_{PIA}	PIA delay	(7)		1.1		1.3		1.0		1.0	ns
t_{LPA}	Low-power adder	(8)		12.0		11.0		10.0		11.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 11. See Figure 13 for more information on switching waveforms.

(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.

(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(5) The f_{MAX} values represent the highest frequency for pipelined data.

(6) Operating conditions: V_{CCIO} = 3.3 V ± 10% for commercial and industrial use.

(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, t_{ACL}, and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 28 and 29 show the EPM7128S AC operating conditions.

Table 28. EPM7128S External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t_{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t_{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t_{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t_{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t_{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t_{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t_{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t_{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(2)*	3.0		3.0		4.0		6.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(3)*	1.0		1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
f_{CNT}	Maximum internal global clock frequency	*(4)*	147.1		125.0		100.0		76.9		MHz
t_{ACNT}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(4)*	147.1		125.0		100.0		76.9		MHz
f_{MAX}	Maximum clock frequency	*(5)*	166.7		166.7		125.0		100.0		MHz

Table 29. EPM7128S Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.5		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.2		0.5		0.5		2.0	ns
t_{FIN}	Fast input delay			2.6		1.0		1.0		2.0	ns
t_{SEXP}	Shared expander delay			3.7		4.0		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.1		0.8		0.8		1.0	ns
t_{LAD}	Logic array delay			3.0		3.0		5.0		6.0	ns
t_{LAC}	Logic control array delay			3.0		3.0		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.7		2.0		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		2.0		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF *(6)*		0.9		2.5		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		7.0		5.5		8.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF *(6)*		4.5		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.0		3.0		2.0		4.0		ns
t_{H}	Register hold time		1.7		2.0		5.0		4.0		ns
t_{FSU}	Register setup time of fast input		1.9		3.0		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.6		0.5		0.5		1.0		ns
t_{RD}	Register delay			1.4		1.0		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.0		1.0		2.0		1.0	ns
t_{IC}	Array clock delay			3.1		3.0		5.0		6.0	ns
t_{EN}	Register enable time			3.0		3.0		5.0		6.0	ns
t_{GLOB}	Global control delay			2.0		1.0		1.0		1.0	ns
t_{PRE}	Register preset time			2.4		2.0		3.0		4.0	ns
t_{CLR}	Register clear time			2.4		2.0		3.0		4.0	ns
t_{PIA}	PIA delay	*(7)*		1.4		1.0		1.0		2.0	ns
t_{LPA}	Low-power adder	*(8)*		11.0		10.0		11.0		13.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 11. See Figure 13 for more information on switching waveforms.

(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.

(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(5) The f_{MAX} values represent the highest frequency for pipelined data.

(6) Operating conditions: V_{CCIO} = 3.3 V ± 10% for commercial and industrial use.

(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, t_{ACL}, and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 30 and 31 show the EPM7160S AC operating conditions.

Table 30. EPM7160S External Timing Parameters (Part 1 of 2) Note (1)

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t_{SU}	Global clock setup time		3.4		4.2		7.0		11.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t_{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		3.9		4.8		5		8	ns
t_{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t_{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t_{ASU}	Array clock setup time		0.9		1.1		2.0		4.0		ns
t_{AH}	Array clock hold time		1.7		2.1		3.0		4.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		6.4		7.9		10.0		15.0	ns
t_{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t_{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		3.0		4.0		6.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			6.7		8.2		10.0		13.0	ns
f_{CNT}	Maximum internal global clock frequency	(4)	149.3		122.0		100.0		76.9		MHz

Table 30. EPM7160S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(4)*	149.3		122.0		100.0		76.9		MHz
f_{MAX}	Maximum clock frequency	*(5)*	166.7		166.7		125.0		100.0		MHz

Table 31. EPM7160S Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t_{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns
t_{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns
t_{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns
t_{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF *(6)*		0.9		1.0		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF *(6)*		4.5		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.0		1.2		2.0		4.0		ns
t_{H}	Register hold time		1.6		2.0		3.0		4.0		ns
t_{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
t_{RD}	Register delay			1.3		1.6		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns
t_{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns
t_{EN}	Register enable time			2.8		3.4		5.0		6.0	ns
t_{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns

Table 31. EPM7160S Internal Timing Parameters (Part 2 of 2) Note (1)

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns
t_{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t_{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns
t_{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 11. See Figure 3 for more information on switching waveforms.

(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.

(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(5) The f_{MAX} values represent the highest frequency for pipelined data.

(6) Operating conditions: V_{CCIO} = 3.3 V ± 10% for commercial and industrial use.

(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, t_{ACL}, and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 32 and 33 show the EPM7192S AC operating conditions.

Table 32. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t_{SU}	Global clock setup time		4.1		7.0		11.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns
t_{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t_{CH}	Global clock high time		3.0		4.0		5.0		ns

Table 32. EPM7192S External Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{CL}	Global clock low time		3.0		4.0		5.0		ns
t_{ASU}	Array clock setup time		1.0		2.0		4.0		ns
t_{AH}	Array clock hold time		1.8		3.0		4.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns
t_{ACH}	Array clock high time		3.0		4.0		6.0		ns
t_{ACL}	Array clock low time		3.0		4.0		6.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(2)*	3.0		4.0		6.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(3)*	1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			8.0		10.0		13.0	ns
f_{CNT}	Maximum internal global clock frequency	*(4)*	125.0		100.0		76.9		MHz
t_{ACNT}	Minimum array clock period			8.0		10.0		13.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(4)*	125.0		100.0		76.9		MHz
f_{MAX}	Maximum clock frequency	*(5)*	166.7		125.0		100.0		MHz

Table 33. EPM7192S Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t_{FIN}	Fast input delay			3.2		1.0		2.0	ns
t_{SEXP}	Shared expander delay			4.2		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.2		0.8		1.0	ns
t_{LAD}	Logic array delay			3.1		5.0		6.0	ns
t_{LAC}	Logic control array delay			3.1		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.9		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF *(6)*		1.0		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		7.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF *(6)*		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns

Table 33. EPM7192S Internal Timing Parameters (Part 2 of 2) Note (1)

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.1		2.0		4.0		ns
t_{H}	Register hold time		1.7		3.0		4.0		ns
t_{FSU}	Register setup time of fast input		2.3		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.7		0.5		1.0		ns
t_{RD}	Register delay			1.4		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.2		2.0		1.0	ns
t_{IC}	Array clock delay			3.2		5.0		6.0	ns
t_{EN}	Register enable time			3.1		5.0		6.0	ns
t_{GLOB}	Global control delay			2.5		1.0		1.0	ns
t_{PRE}	Register preset time			2.7		3.0		4.0	ns
t_{CLR}	Register clear time			2.7		3.0		4.0	ns
t_{PIA}	PIA delay	(7)		2.4		1.0		2.0	ns
t_{LPA}	Low-power adder	(8)		10.0		11.0		13.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 11. See Figure 13 for more information on switching waveforms.

(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.

(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(5) The f_{MAX} values represent the highest frequency for pipelined data.

(6) Operating conditions: V_{CCIO} = 3.3 V ± 10% for commercial and industrial use.

(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, t_{ACL}, and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 34 and 35 show the EPM7256S AC operating conditions.

Table 34. EPM7256S External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t_{SU}	Global clock setup time		3.9		7.0		11.0		ns
t_{H}	Global clock hold time		0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns
t_{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t_{CH}	Global clock high time		3.0		4.0		5.0		ns
t_{CL}	Global clock low time		3.0		4.0		5.0		ns
t_{ASU}	Array clock setup time		0.8		2.0		4.0		ns
t_{AH}	Array clock hold time		1.9		3.0		4.0		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns
t_{ACH}	Array clock high time		3.0		4.0		6.0		ns
t_{ACL}	Array clock low time		3.0		4.0		6.0		ns
t_{CPPW}	Minimum pulse width for clear and preset	*(2)*	3.0		4.0		6.0		ns
t_{ODH}	Output data hold time after clock	C1 = 35 pF *(3)*	1.0		1.0		1.0		ns
t_{CNT}	Minimum global clock period			7.8		10.0		13.0	ns
f_{CNT}	Maximum internal global clock frequency	*(4)*	128.2		100.0		76.9		MHz
t_{ACNT}	Minimum array clock period			7.8		10.0		13.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(4)*	128.2		100.0		76.9		MHz
f_{MAX}	Maximum clock frequency	*(5)*	166.7		125.0		100.0		MHz

Table 35. EPM7256S Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.3		0.5		2.0	ns
t_{IO}	I/O input pad and buffer delay			0.3		0.5		2.0	ns
t_{FIN}	Fast input delay			3.4		1.0		2.0	ns
t_{SEXP}	Shared expander delay			3.9		5.0		8.0	ns
t_{PEXP}	Parallel expander delay			1.1		0.8		1.0	ns
t_{LAD}	Logic array delay			2.6		5.0		6.0	ns
t_{LAC}	Logic control array delay			2.6		5.0		6.0	ns
t_{IOE}	Internal output enable delay			0.8		2.0		3.0	ns
t_{OD1}	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
t_{OD2}	Output buffer and pad delay	C1 = 35 pF *(6)*		1.0		2.0		5.0	ns
t_{OD3}	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
t_{ZX2}	Output buffer enable delay	C1 = 35 pF *(6)*		4.5		5.5		7.0	ns
t_{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
t_{SU}	Register setup time		1.1		2.0		4.0		ns
t_{H}	Register hold time		1.6		3.0		4.0		ns
t_{FSU}	Register setup time of fast input		2.4		3.0		2.0		ns
t_{FH}	Register hold time of fast input		0.6		0.5		1.0		ns
t_{RD}	Register delay			1.1		2.0		1.0	ns
t_{COMB}	Combinatorial delay			1.1		2.0		1.0	ns
t_{IC}	Array clock delay			2.9		5.0		6.0	ns
t_{EN}	Register enable time			2.6		5.0		6.0	ns
t_{GLOB}	Global control delay			2.8		1.0		1.0	ns
t_{PRE}	Register preset time			2.7		3.0		4.0	ns
t_{CLR}	Register clear time			2.7		3.0		4.0	ns
t_{PIA}	PIA delay	*(7)*		3.0		1.0		2.0	ns
t_{LPA}	Low-power adder	*(8)*		10.0		11.0		13.0	ns

Notes to tables:

(1) These values are specified under the recommended operating conditions shown in Table 11. See Figure 13 for more information on switching waveforms.

(2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.

(3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.

(4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(5) The f_{MAX} values represent the highest frequency for pipelined data.

(6) Operating conditions: $V_{CCIO} = 3.3\ V \pm 10\%$ for commercial and industrial use.

(7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{EN}, t_{SEXP}, t_{ACL}, and t_{CPPW} parameters for macrocells running in the low-power mode.

Power Consumption

Supply power (P) versus frequency (f_{MAX} in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The P_{IO} value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note 74 (Evaluating Power for Altera Devices)*.

The I_{CCINT} value, which depends on the switching frequency and the application logic, is calculated with the following equation:

$$I_{CCINT} =$$

$$A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times tog_{LC}$$

The parameters in this equation are shown below:

MC_{TON}	=	Number of macrocells with the Turbo Bit option turned on, as reported in the MAX+PLUS II Report File (.rpt)
MC_{DEV}	=	Number of macrocells in the device
MC_{USED}	=	Total number of macrocells in the design, as reported in the MAX+PLUS II Report File (.rpt)
f_{MAX}	=	Highest clock frequency to the device
tog_{LC}	=	Average ratio of logic cells toggling at each clock (typically 0.125)
A, B, C	=	Constants, shown in Table 36

Table 36. MAX 7000 I_{CC} Equation Constants

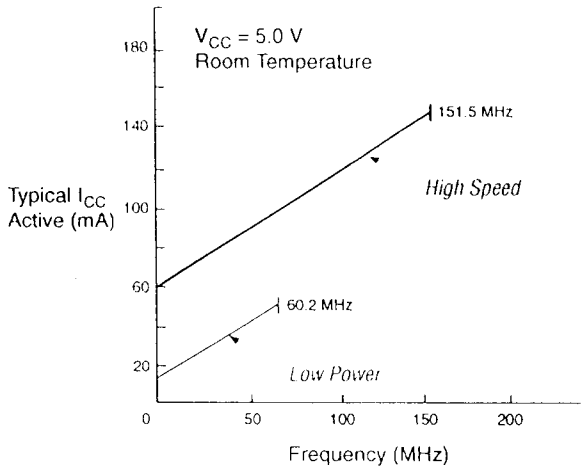
Device	A	B	C
EPM7032	1.87	0.52	0.144
EPM7064	1.63	0.74	0.144
EPM7096	1.63	0.74	0.144
EPM7128E	1.17	0.54	0.096
EPM7160E	1.17	0.54	0.096
EPM7192E	1.17	0.54	0.096
EPM7256E	1.17	0.54	0.096
EPM7032S	0.93	0.40	0.040
EPM7064S	0.93	0.40	0.040
EPM7128S	0.93	0.40	0.040
EPM7160S	0.93	0.40	0.040
EPM7192S	0.93	0.40	0.040
EPM7256S	0.93	0.40	0.040

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} values should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

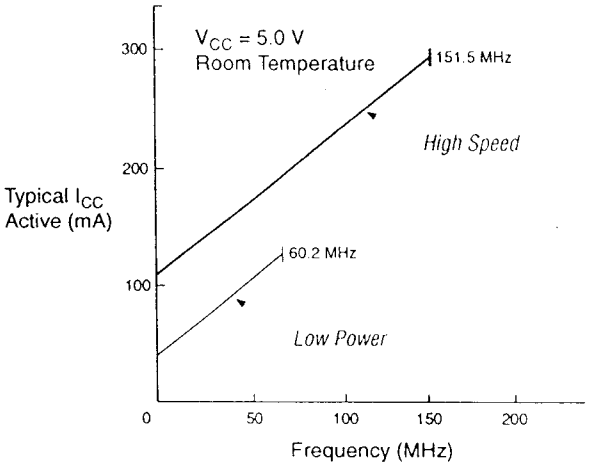
Figure 14 shows typical supply current versus frequency for MAX 7000 devices.

Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 1 of 2)

EPM7032



EPM7064



EPM7096

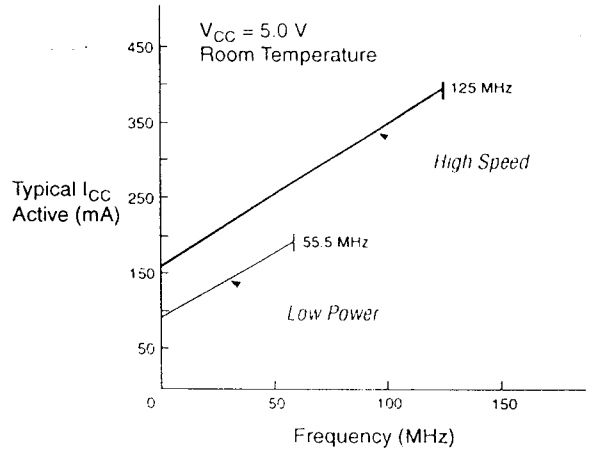
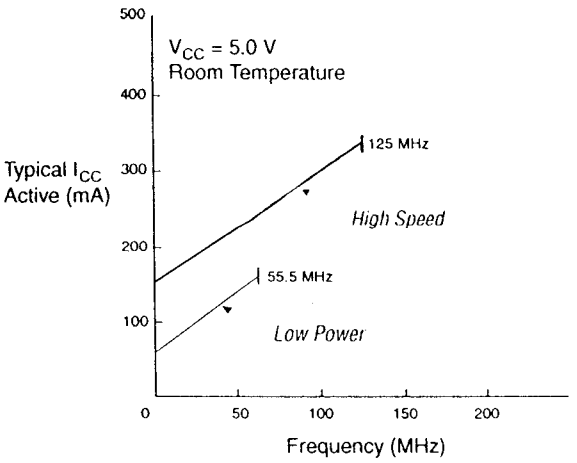
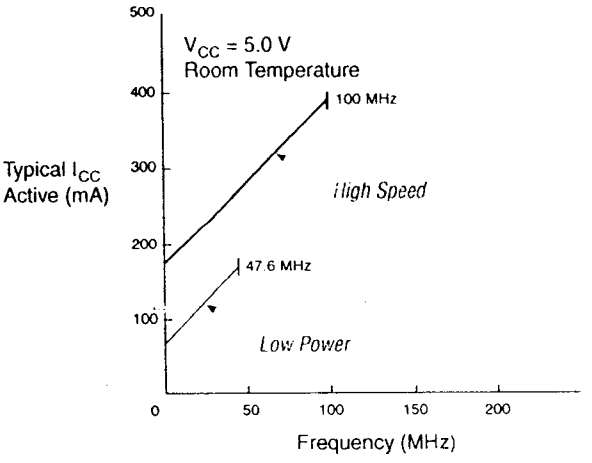


Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 2 of 2)

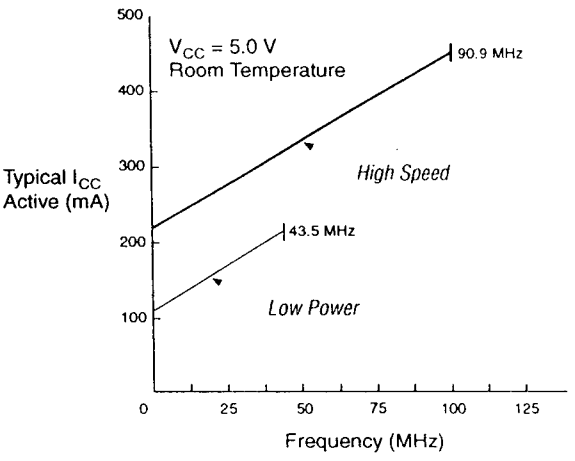
EPM7128E



EPM7160E



EPM7192E



EPM7256E

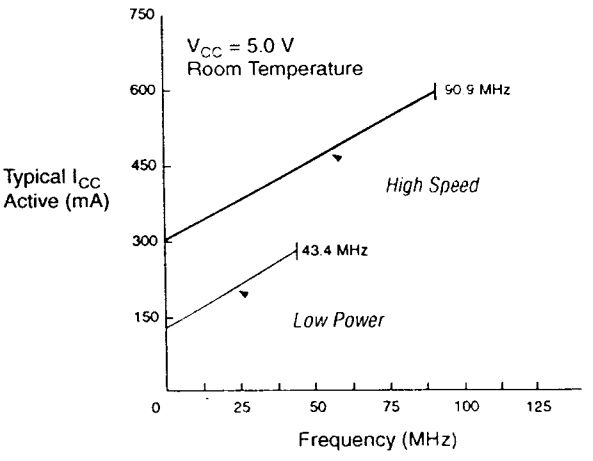
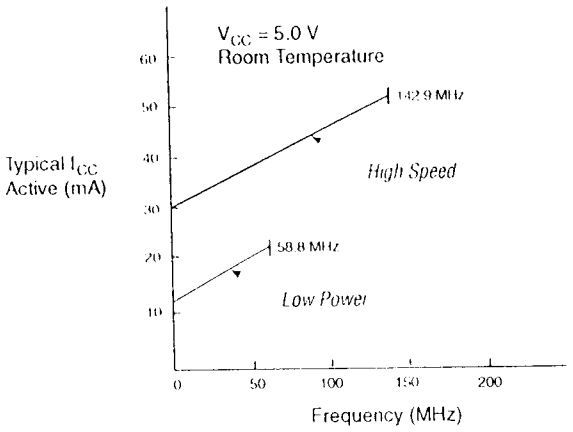


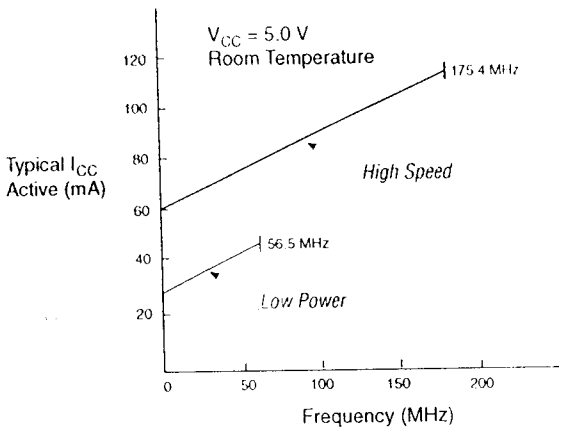
Figure 15 shows typical supply current versus frequency for MAX 7000S devices.

Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 1 of 2)

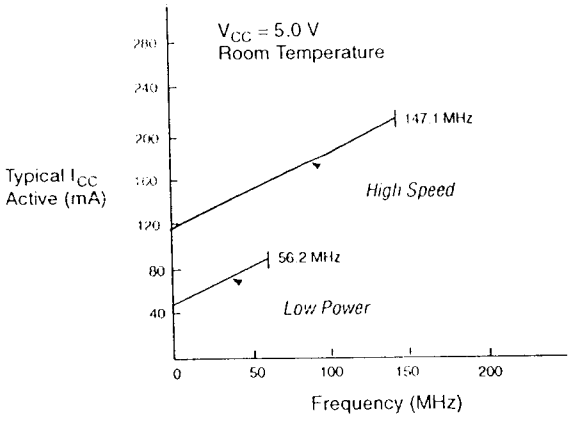
EPM7032S



EPM7064S



EPM7128S



EPM7160S

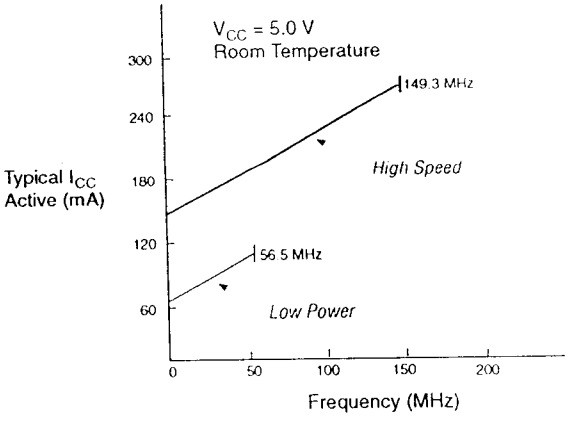
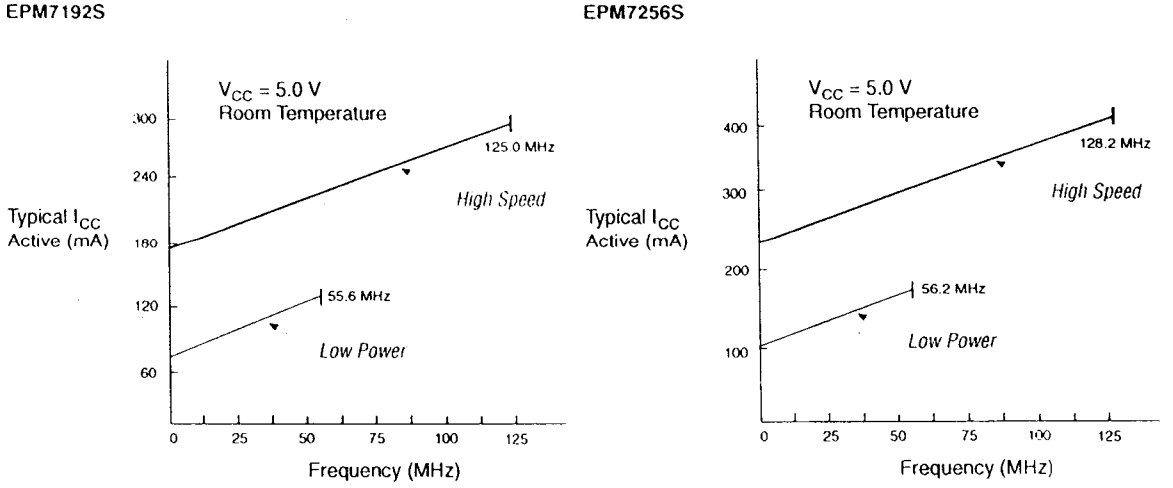


Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 2 of 2)



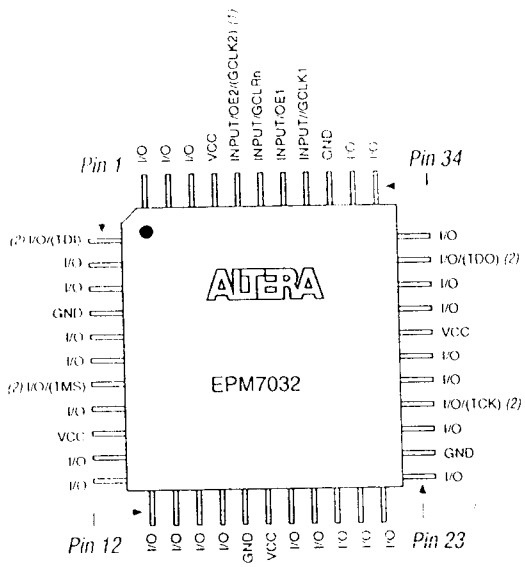
Device Pin-Outs

See the Altera web site (**http://www.altera.com**) or the *Altera Digital Library* for pin-out information.

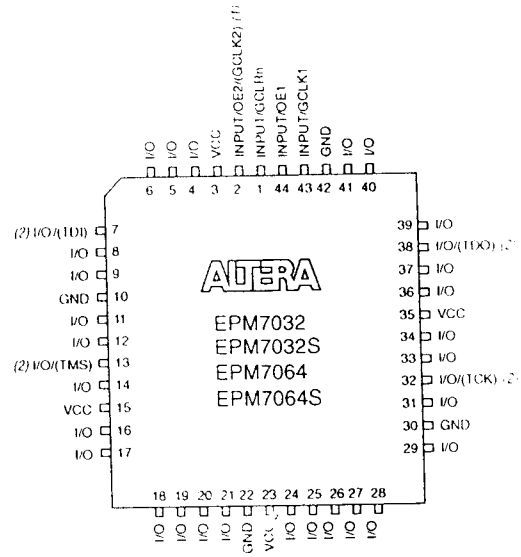
Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

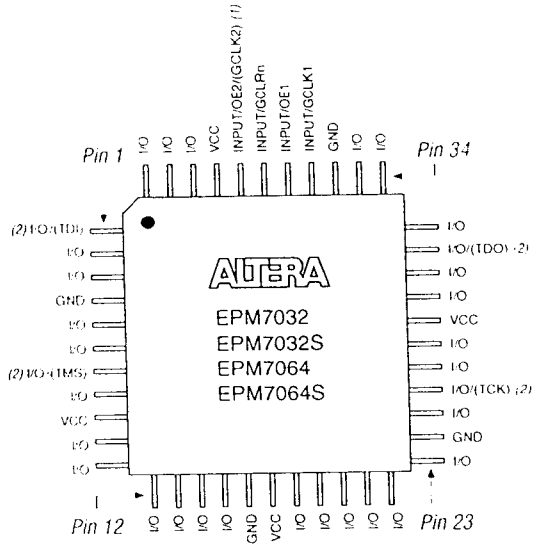
Package outlines not drawn to scale.



44-Pin PQFP



44-Pin PLCC



44-Pin TQFP

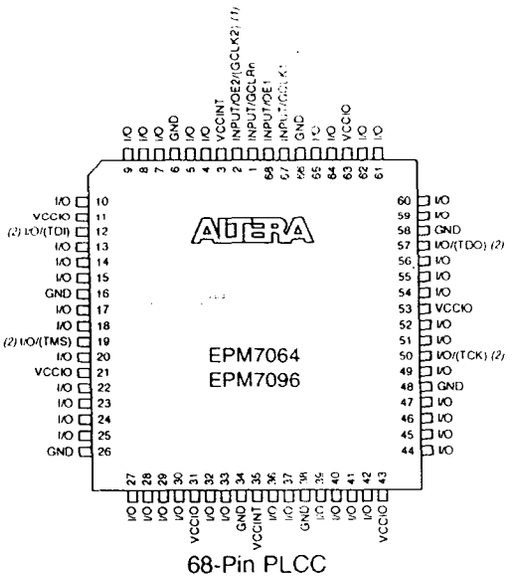
Notes:

(1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.

(2) JTAG ports are available in MAX 7000S devices only.

Figure 17. 68-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



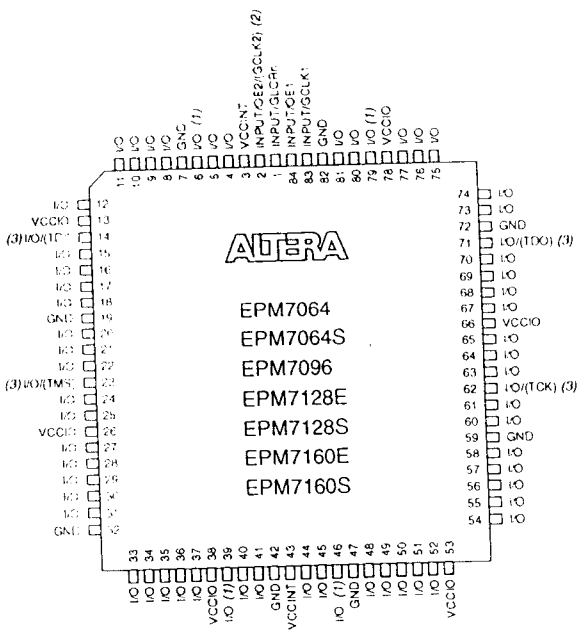
Notes:

(1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.

(2) JTAG ports are available in MAX 7000S devices only.

Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

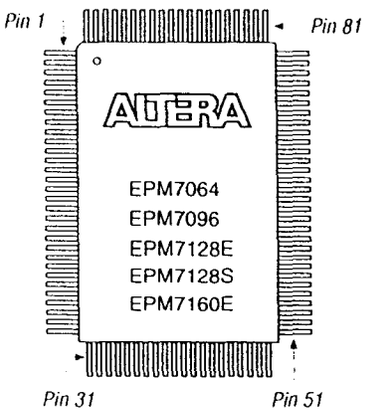


84-Pin PLCC

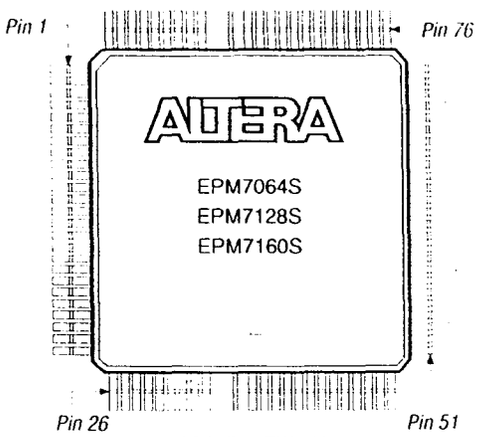
Notes:
(1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
(2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
(3) JTAG ports are available in MAX 7000S devices only.

Figure 19. 100-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



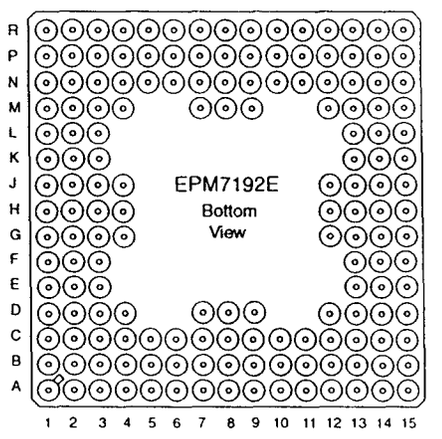
100-Pin PQFP



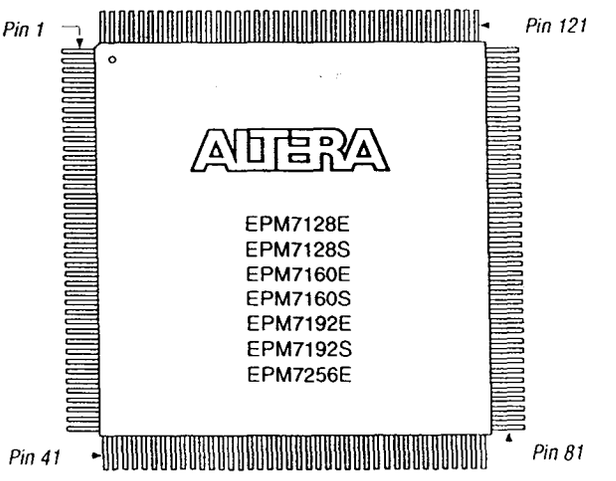
100-Pin TQFP

Figure 20. 160-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



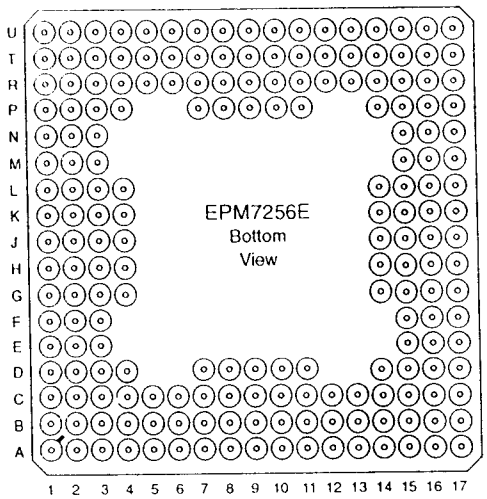
160-Pin PGA



160-Pin PQFP

Figure 21. 192-Pin Package Pin-Out Diagram

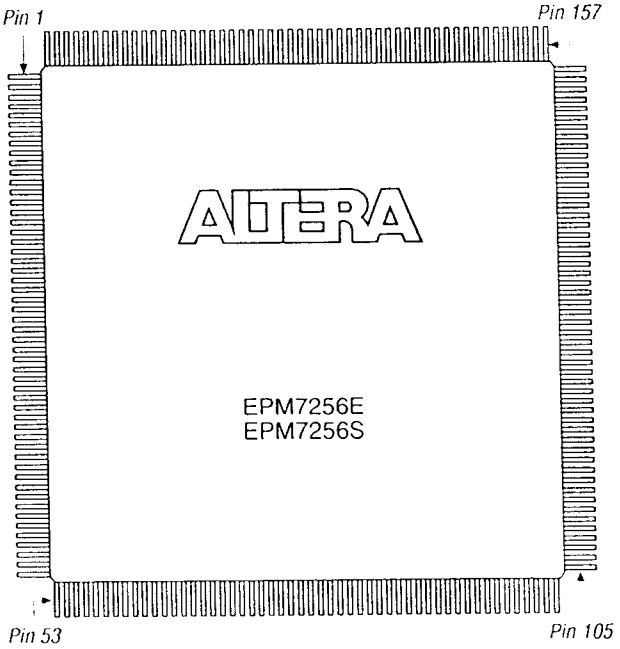
Package outline not drawn to scale.



192-Pin PGA

Figure 22. 208-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



208-Pin PQFP/RQFP

Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.3 supersedes information published in previous versions. The following changes were made in the *MAX 3000A Programmable Logic Device Family Data Sheet* version 6.3: Updated the "Open Drain Output Option (MAX 7000S Devices Only)" section on page 18.

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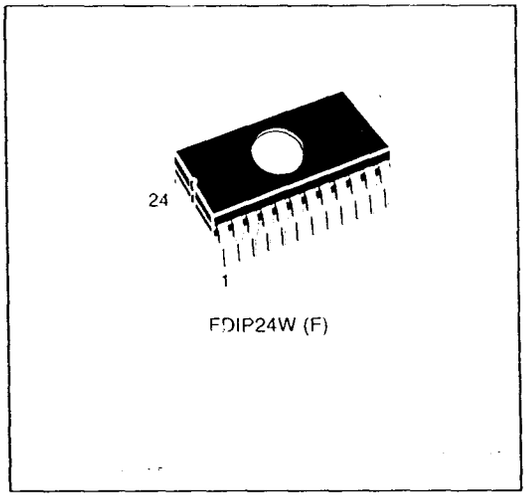
Printed on Recycled Paper.

M2732A

NMOS 32 Kbit (4Kb x 8) UV EPROM

NOT FOR NEW DESIGN

- FAST ACCESS TIME: 200ns
- EXTENDED TEMPERATURE RANGE
- SINGLE 5V SUPPLY VOLTAGE
- LOW STANDBY CURRENT: 35mA max
- INPUTS and OUTPUTS TTL COMPATIBLE DURING READ and PROGRAM
- COMPLETELY STATIC



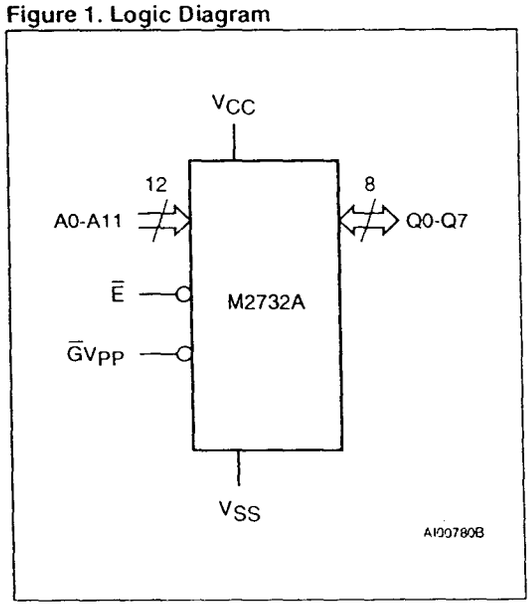
FDIP24W (F)

DESCRIPTION

The M2732A is a 32,768 bit UV erasable and electrically programmable memory EPROM. It is organized as 4,096 words by 8 bits. The M2732A with its single 5V power supply and with an access time of 200 ns, is ideal suited for applications where fast turn around and pattern experimentation are important requirements.

The M2732A is housed in a 24 pin Window Ceramic Frit-Seal Dual-in-Line package. The transparent lid allows the user to expose the chip to ultraviolet light to erase the bit pattern. A new pattern can be then written to the device by following the programming procedure.

Figure 1. Logic Diagram



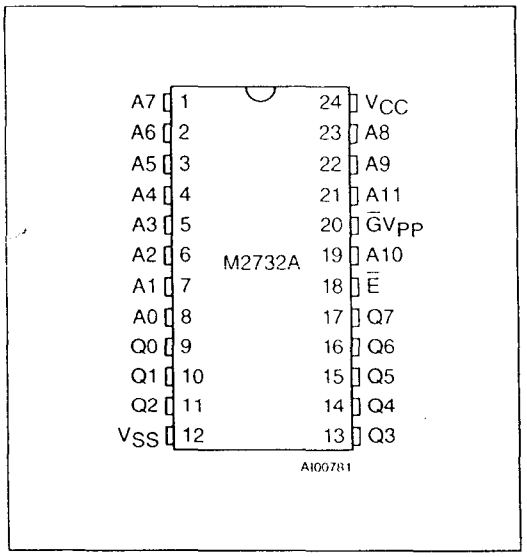
This is information on a product still in production but not recommended for new designs.

Table 2. Absolute Maximum Ratings

Symbol	Parameter		Value	Unit
T_A	Ambient Operating Temperature	grade 1 grade 6	0 to 70 –40 to 85	°C
T_{BIAS}	Temperature Under Bias	grade 1 grade 6	–10 to 80 –50 to 95	°C
T_{STG}	Storage Temperature		–65 to 125	°C
V_{IO}	Input or Output Voltages		–0.6 to 6	V
V_{CC}	Supply Voltage		–0.6 to 6	V
V_{PP}	Program Supply Voltage		–0.6 to 22	V

Note: Except for the rating "Operating Temperature Range", stresses above those listed in the Table "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Figure 2. DIP Pin Connections



DEVICE OPERATION

The six modes of operation for the M2732A are listed in the Operating Modes Table. A single 5V power supply is required in the read mode. All inputs are TTL level except for V_{PP}.

Read Mode

The M2732A has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable ($\overline{E}$) is the power control and should be used for device selection. Output Enable ($\overline{G}$) is the output control and should be used to gate data to the output pins, independent of device selection.

Assuming that the addresses are stable, address access time (t_{AVAQ}) is equal to the delay from $\overline{E}$ to output (t_{ELQV}). Data is available at the outputs after the falling edge of $\overline{G}$, assuming that $\overline{E}$ has been low and the addresses have been stable for at least t_{AVQV}-t_{GLQV}.

Standby Mode

The M2732A has a standby mode which reduces the active power current by 70 %, from 125 mA to 35 mA. The M2732A is placed in the standby mode by applying a TTL high signal to $\overline{E}$ input. When in standby mode, the outputs are in a high impedance state, independent of the $\overline{G}/V_{PP}$ input.

Two Line Output Control

Because M2732A's are usually used in larger memory arrays, this product features a 2 line control function which accommodates the use of multiple memory connection. The two line control function allows:

a. the lowest possible memory power dissipation,

b. complete assurance that output bus contention will not occur.

To most efficiently use these two control lines, it is recommended that $\overline{E}$ be decoded and used as the primary device selecting function, while $\overline{G}$ should be made a common connection to all devices in the array and connected to the $\overline{READ}$ line from the system control bus.

This ensures that all deselected memory devices are in their low power standby mode and that the output pins are only active when data is required from a particular memory device.

Programming

When delivered, and after each erasure, all bits of the M2732A are in the "1" state. Data is introduced by selectively programming "0's" into the desired bit locations. Although only "0's" will be programmed, both "1's" and "0's" can be presented in the data word. The only way to change a "0" to a "1" is by ultraviolet light erasure.

The M2732A is in the programming mode when the $\overline{G}V_{PP}$ input is at 21V. A 0.1µF capacitor must be placed across $\overline{G}V_{PP}$ and ground to suppress spurious voltage transients which may damage the device. The data to be programmed is applied, 8 bits in parallel, to the data output pins. The levels required for the address and data inputs are TTL.

When the address and data are stable, a 50ms, active low, TTL program pulse is applied to the $\overline{E}$ input. A program pulse must be applied at each address location to be programmed. Any location can be programmed at any time - either individually, sequentially, or at random. The program pulse has a maximum width of 55ms. The M2732A must not be programmed with a DC signal applied to the $\overline{E}$ input.

Programming of multiple M2732As in parallel with the same data can be easily accomplished due to the simplicity of the programming requirements. Inputs of the paralleled M2732As may be connected together when they are programmed with the same data. A low level TTL pulse applied to the $\overline{E}$ input programs the paralleled 2732As.

Program Inhibit

Programming of multiple M2732As in parallel with different data is also easily accomplished. Except for $\overline{E}$, all like inputs (including $\overline{G}V_{PP}$) of the parallel M2732As may be common. A TTL level program pulse applied to a M2732A's $\overline{E}$ input with $\overline{G}V_{PP}$ at 21V will program that M2732A. A high level $\overline{E}$ input inhibits the other M2732As from being programmed.

Program Verify

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify is carried out with $\overline{G}V_{PP}$ and $\overline{E}$ at V_{IL}.

ERASURE OPERATION

The erasure characteristics of the M2732A are such that erasure begins when the cells are exposed to light with wavelengths shorter than approximately 4000 Å. It should be noted that sunlight and certain types of fluorescent lamps have wavelengths in the 3000-4000 Å range. Research shows that constant exposure to room level fluorescent lighting could erase a typical M2732A in approximately 3 years, while it would take approximately 1 week to cause erasure when exposed to the direct sunlight. If the M2732A is to be exposed to these types of lighting conditions for extended periods of time, it is suggested that opaque labels be put over the M2732A window to prevent unintentional erasure.

The recommended erasure procedure for the M2732A is exposure to shortwave ultraviolet light which has a wavelength of 2537 Å. The integrated dose (i.e. UV intensity x exposure time) for erasure should be a minimum of 15 W-sec/cm^2. The erasure time with this dosage is approximately 15 to 20 minutes using an ultraviolet lamp with 12000 µW/cm^2 power rating. The M2732A should be placed within 2.5 cm of the lamp tubes during erasure. Some lamps have a filter on their tubes which should be removed before erasure.

Table 3. Operating Modes

Mode	$\overline{E}$	$\overline{G}V_{PP}$	V_{CC}	Q0 - Q7
Read	V_{IL}	V_{IL}	V_{CC}	Data Out
Program	V_{IL} Pulse	V_{PP}	V_{CC}	Data In
Verify	V_{IL}	V_{IL}	V_{CC}	Data Out
Program Inhibit	V_{IH}	V_{PP}	V_{CC}	Hi-Z
Standby	V_{IH}	X	V_{CC}	Hi-Z

Note: X = V_{IH} or V_{IL}.

AC MEASUREMENT CONDITIONS

Input Rise and Fall Times	≤ 20ns
Input Pulse Voltages	0.45V to 2.4V
Input and Output Timing Ref. Voltages	0.8V to 2.0V

Note that Output Hi-Z is defined as the point where data is no longer driven.

Figure 3. AC Testing Input Output Waveforms

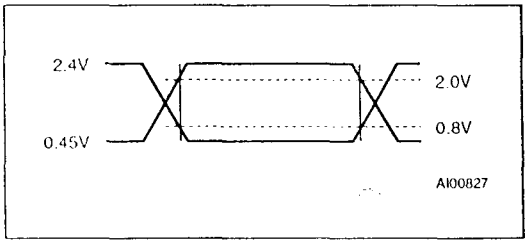


Figure 4. AC Testing Load Circuit

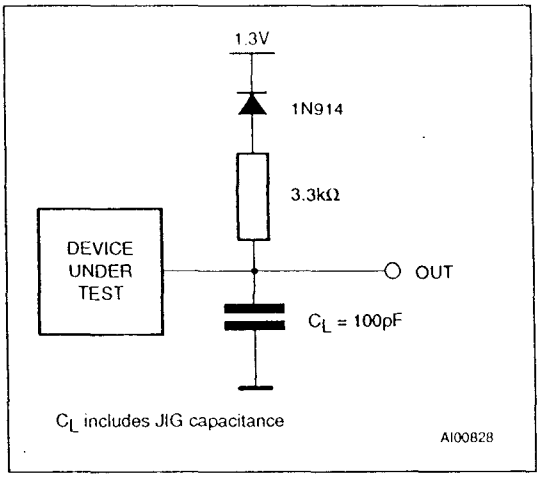


Table 4. Capacitance (1) (T_A = 25 °C, f = 1 MHz)

Symbol	Parameter	Test Condition	Min	Max	Unit
C_{IN}	Input Capacitance (except $\overline{G}V_{PP}$)	V_{IN} = 0V		6	pF
C_{IN1}	Input Capacitance ($\overline{G}V_{PP}$)	V_{IN} = 0V		20	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0V		12	pF

Note: 1. Sampled only, not 100% tested.

Figure 5. Read Mode AC Waveforms

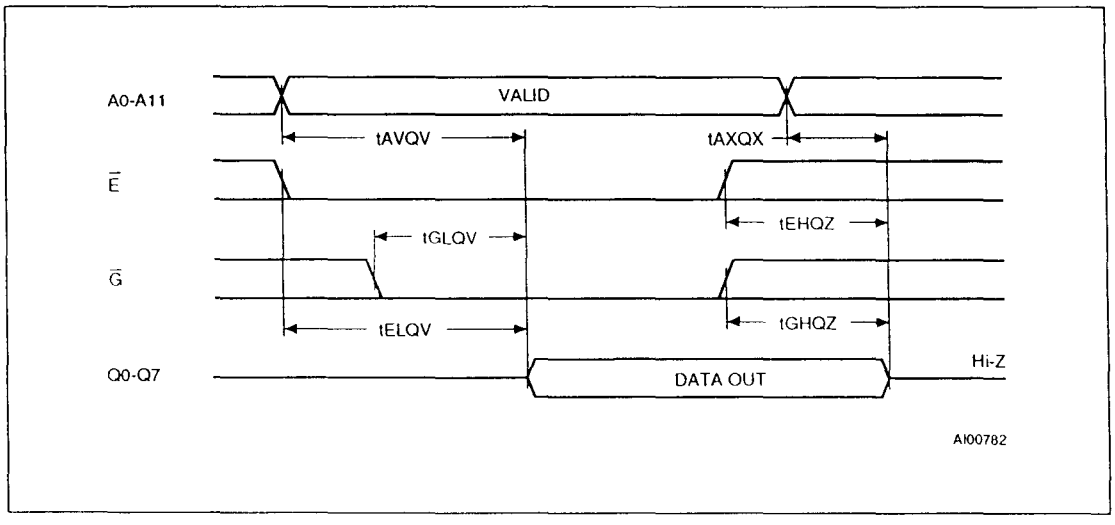


Table 5. Read Mode DC Characteristics (1)
(T_A = 0 to 70 °C or –40 to 85 °C; V_{CC} = 5V ± 5% or 5V ± 10%; V_{PP} = V_{CC})

Symbol	Parameter	Test Condition	Value		Unit
			Min	Max	
I_{LI}	Input Leakage Current	$0 \le V_{IN} \le V_{CC}$		±10	µA
I_{LO}	Output Leakage Current	$V_{OUT} = V_{CC}$		±10	µA
I_{CC}	Supply Current	$\overline{E} = V_{IL}$, $\overline{G} = V_{IL}$		125	mA
I_{CC1}	Supply Current (Standby)	$\overline{E} = V_{IH}$, $\overline{G} = V_{IL}$		35	mA
V_{IL}	Input Low Voltage		–0.1	0.8	V
V_{IH}	Input High Voltage		2	V_{CC} + 1	V
V_{OL}	Output Low Voltage	I_{OL} = 2.1mA		0.45	V
V_{OH}	Output High Voltage	I_{OH} = –400µA	2.4		V

Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.

Table 6. Read Mode AC Characteristics (1)
(T_A = 0 to 70 °C or –40 to 85 °C; V_{CC} = 5V ± 5% or 5V ± 10%; V_{PP} = V_{CC})

Symbol	Alt	Parameter	Test Condition	M2732A								Unit
				-2, -20		blank, -25		-3		-4		
				Min	Max	Min	Max	Min	Max	Min	Max	
t_{AVQV}	t_{ACC}	Address Valid to Output Valid	$\overline{E} = V_{IL}$, $\overline{G} = V_{IL}$		200		250		300		450	ns
t_{ELQV}	t_{CE}	Chip Enable Low to Output Valid	$\overline{G} = V_{IL}$		200		250		300		450	ns
t_{GLQV}	t_{OE}	Output Enable Low to Output Valid	$\overline{E} = V_{IL}$		100		100		150		150	ns
t_{EHQZ} (2)	t_{DF}	Chip Enable High to Output Hi-Z	$\overline{G} = V_{IL}$	0	60	0	60	0	130	0	130	ns
t_{GHQZ} (2)	t_{DF}	Output Enable High to Output Hi-Z	$\overline{E} = V_{IL}$	0	60	0	60	0	130	0	130	ns
t_{AXQX}	t_{OH}	Address Transition to Output Transition	$\overline{E} = V_{IL}$, $\overline{G} = V_{IL}$	0		0		0		0		ns

Notes: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.
2. Sampled only, not 100% tested.

Table 7. **Programming Mode DC Characteristics** (1)
(T_A = 25 °C; V_{CC} = 5V ± 5%; V_{PP} = 21V ± 0.5V)

Symbol	Parameter	Test Condition	Min	Max	Units
I_{LI}	Input Leakage Current	$V_{IL} \le V_{IN} \le V_{IH}$		±10	µA
I_{CC}	Supply Current	$\overline{E} = V_{IL}$, $\overline{G} = V_{IL}$		125	mA
I_{PP}	Program Current	$\overline{E} = V_{IL}$, $\overline{G} = V_{PP}$		30	mA
V_{IL}	Input Low Voltage		–0.1	0.8	V
V_{IH}	Input High Voltage		2	V_{CC} + 1	V
V_{OL}	Output Low Voltage	I_{OL} = 2.1mA		0.45	V
V_{OH}	Output High Voltage	I_{OH} = –400µA	2.4		V

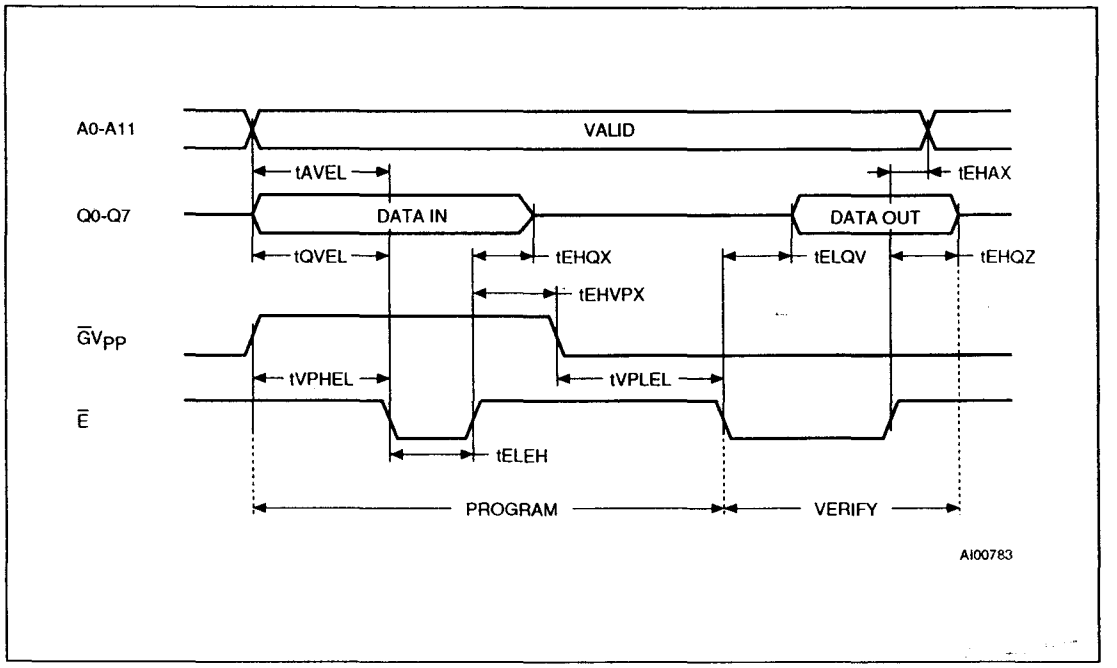
Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.

Table 8. **Programming Mode AC Characteristics** (1)
(T_A = 25 °C; V_{CC} = 5V ± 5%; V_{PP} = 21V ± 0.5V)

Symbol	Alt	Parameter	Test Condition	Min	Max	Units
t_{AVEL}	t_{AS}	Address Valid to Chip Enable Low		2		µs
t_{DVEL}	t_{DS}	Input Valid to Chip Enable Low		2		µs
t_{VPHEL}	t_{OES}	V_{PP} High to Chip Enable Low		2		µs
$t_{VPL1VPL2}$	t_{PRT}	V_{PP} Rise Time		50		ns
t_{ELEH}	t_{PW}	Chip Enable Program Pulse Width		45	55	ms
t_{EHQX}	t_{DH}	Chip Enable High to Input Transition		2		µs
t_{EHVPX}	t_{OEH}	Chip Enable High to V_{PP} Transition		2		µs
t_{VPLEL}	t_{VR}	V_{PP} Low to Chip Enable Low		2		µs
t_{ELQV}	t_{DV}	Chip Enable Low to Output Valid	$\overline{E} = V_{IL}$, $\overline{G} = V_{IL}$		1	µs
t_{EHQZ}	t_{DF}	Chip Enable High to Output Hi-Z		0	130	ns
t_{EHAX}	t_{AH}	Chip Enable High to Address Transition		0		ns

Note: 1. V_{CC} must be applied simultaneously with or before V_{PP} and removed simultaneously or after V_{PP}.

Figure 6. Programming and Verify Modes AC Waveforms



ORDERING INFORMATION SCHEME

Example: M2732A -2 F 1

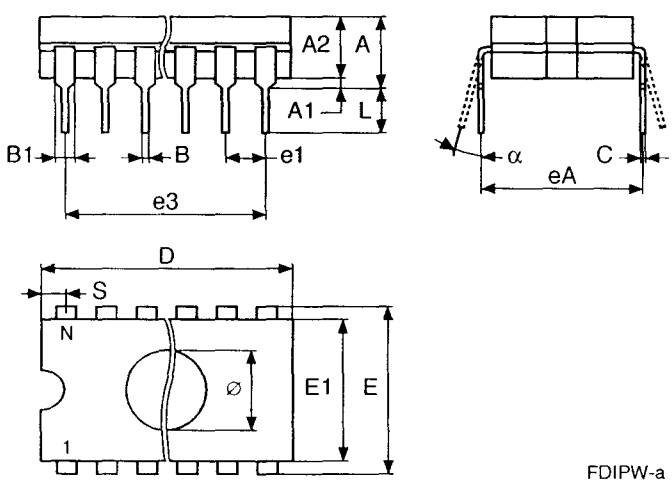
Speed and V_{CC} Tolerance		Package		Temperature Range	
-2	200 ns, 5V ±5%	F	FDIP24W	1	0 to 70 °C
blank	250 ns, 5V ±5%			6	–40 to 85 °C
-3	300 ns, 5V ±5%				
-4	450 ns, 5V ±5%				
-20	200 ns, 5V ±10%				
-25	250 ns, 5V ±10%				

For a list of available options (Speed, V_{CC} Tolerance, Package, etc...) refer to the current Memory Shortform catalogue.

For further information on any aspect of this device, please contact STMicroelectronics Sales Office nearest to you.

FDIP24W - 24 pin Ceramic Frit-seal DIP, with window

Symb	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A			5.71			0.225
A1		0.50	1.78		0.020	0.070
A2		3.90	5.08		0.154	0.200
B		0.40	0.55		0.016	0.022
B1		1.17	1.42		0.046	0.056
C		0.22	0.31		0.009	0.012
D			32.30			1.272
E		15.40	15.80		0.606	0.622
E1		13.05	13.36		0.514	0.526
e1	2.54	–	–	0.100	–	–
e3	27.94	–	–	1.100	–	–
eA		16.17	18.32		0.637	0.721
L		3.18	4.10		0.125	0.161
S		1.52	2.49		0.060	0.098
∅	7.11	–	–	0.280	–	–
α		4°	15°		4°	15°
N	2	4		24		



FDIPW-a

Drawing is not to scale

CD4049UB, CD4050B

TEXAS INSTRUMENTS

Data sheet acquired from Harris Semiconductor
SCHS046A

August 1998 - Revised May 1999

CMOS Hex Buffer/Converters

The CD4049UB and CD4050B devices are inverting and non-inverting hex buffers, respectively, and feature logic-level conversion using only one supply voltage (V_{CC}). The input-signal high level (V_{IH}) can exceed the V_{CC} supply voltage when these devices are used for logic-level conversions. These devices are intended for use as CMOS to DTL/TTL converters and can drive directly two DTL/TTL loads. (V_{CC} = 5V, $V_{OL} \leq 0.4V$, and $I_{OL} \geq 3.3mA$.)

The CD4049UB and CD4050B are designated as replacements for CD4009UB and CD4010B, respectively. Because the CD4049UB and CD4050B require only one power supply, they are preferred over the CD4009UB and CD4010B and should be used in place of the CD4009UB and CD4010B in all inverter, current driver, or logic-level conversion applications. In these applications the CD4049UB and CD4050B are pin compatible with the CD4009UB and CD4010B respectively, and can be substituted for these devices in existing as well as in new designs. Terminal No. 16 is not connected internally on the CD4049UB or CD4050B, therefore, connection to this terminal is of no consequence to circuit operation. For applications not requiring high sink-current or voltage conversion, the CD4069UB Hex Inverter is recommended.

Features

- CD4049UB Inverting
- CD4050B Non-Inverting
- High Sink Current for Driving 2 TTL Loads
- High-To-Low Level Logic Conversion
- 100% Tested for Quiescent Current at 20V
- Maximum Input Current of 1µA at 18V Over Full Package Temperature Range; 100nA at 18V and 25°C
- 5V, 10V and 15V Parametric Ratings

Applications

- CMOS to DTL/TTL Hex Converter
- CMOS Current "Sink" or "Source" Driver
- CMOS High-To-Low Logic Level Converter

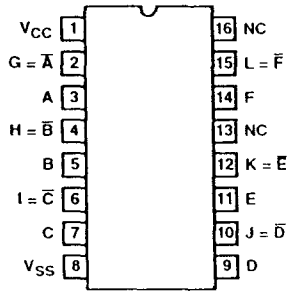
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD4049UBE	-55 to 125	16 Ld PDIP	E16.3
CD4050BE	-55 to 125	16 Ld PDIP	E16.3
CD4049UBF	-55 to 125	16 Ld CERDIP	F16.3
CD4050BF	-55 to 125	16 Ld CERDIP	F16.3
CD4050BM	-55 to 125	16 Ld SOIC	M16.3

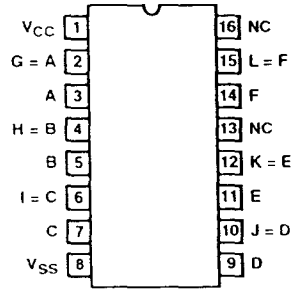
NOTE: Wafer and die for this part number is available which meets all electrical specifications. Please contact your local sales office or customer service for ordering information.

Pinouts

CD4049UB (PDIP, CERDIP)
TOP VIEW



CD4050B (PDIP, CERDIP, SOIC)
TOP VIEW



CAUTION: These devices are sensitive to electrostatic discharge; follow proper IC Handling Procedures.
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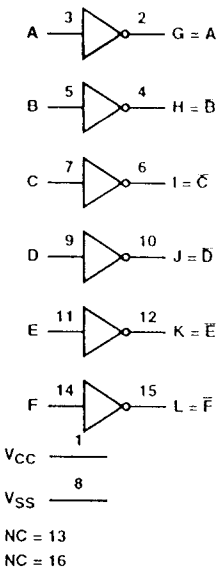
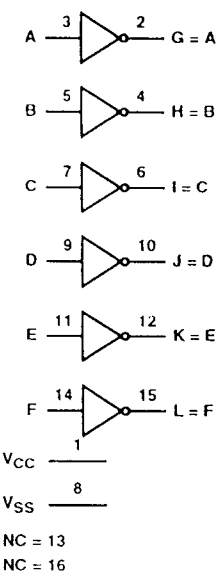
Functional Block Diagrams

CD4049UB



CD4050B



Schematic Diagrams

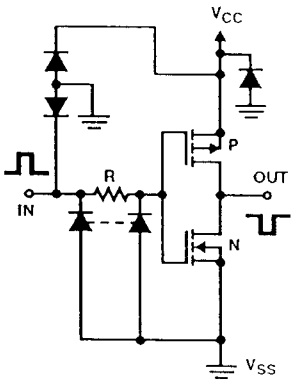


FIGURE 1A. SCHEMATIC DIAGRAM OF CD4049UB, 1 OF 6 IDENTICAL UNITS

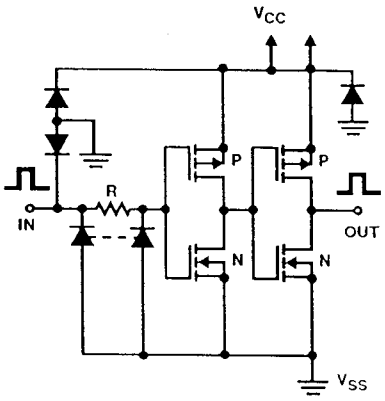


FIGURE 1B. SCHEMATIC DIAGRAM OF CD4050B, 1 OF 6 IDENTICAL UNITS

Absolute Maximum Ratings

Supply Voltage (V+ to V-) . . . . . -0.5V to 20V
DC Input Current, Any One Input . . . . . ±10mA

Operating Conditions

Temperature Range . . . . . -55°C to 125°C

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} (°C/W)	θ_{JC} (°C/W)
PDIP Package	90	N/A
CERDIP Package	130	55
SOIC Package	100	N/A

Maximum Junction Temperature (Plastic Package) . . . . . 150°C
Maximum Storage Temperature Range . . . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . . 265°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

PARAMETER	TEST CONDITIONS			LIMITS AT INDICATED TEMPERATURE (°C)							UNITS
								25			
	V_O (V)	V_{IN} (V)	V_{CC} (V)	-55	-40	85	125	MIN	TYP	MAX	
Quiescent Device Current I_{DD} (Max)	-	0,5	5	1	1	30	30	-	0.02	1	µA
	-	0,10	10	2	2	60	60	-	0.02	2	µA
	-	0,15	15	4	4	120	120	-	0.02	4	µA
	-	0,20	20	20	20	600	600	-	0.04	20	µA
Output Low (Sink) Current I_{OL} (Min)	0.4	0,5	4.5	3.3	3.1	2.1	1.8	2.6	5.2	-	mA
	0.4	0,5	5	4	3.8	2.9	2.4	3.2	6.4	-	mA
	0.5	0,10	10	10	9.6	6.6	5.6	8	16	-	mA
	1.5	0,15	15	26	25	20	18	24	48	-	mA
Output High (Source) Current I_{OH} (Min)	4.6	0,5	5	-0.81	-0.73	-0.58	-0.48	-0.65	-1.2	-	mA
	2.5	0,5	5	-2.6	-2.4	-1.9	-1.55	-2.1	-3.9	-	mA
	9.5	0,10	10	-2.0	-1.8	-1.35	-1.18	-1.65	-3.0	-	mA
	13.5	0,15	15	-5.2	-4.8	-3.5	-3.1	-4.3	-8.0	-	mA
Out Voltage Low Level V_{OL} (Max)	-	0,5	5	0.05	0.05	0.05	0.05	-	0	0.05	V
	-	0,10	10	0.05	0.05	0.05	0.05	-	0	0.05	V
	-	0,15	5	0.05	0.05	0.05	0.05	-	0	0.05	V
Output Voltage High Level V_{OH} (Min)	-	0,5	5	4.95	4.95	4.95	4.95	4.95	5	-	V
	-	0,10	10	9.95	9.95	9.95	9.95	9.95	10	-	V
	-	0,15	15	14.95	14.95	14.95	14.95	14.95	15	-	V
Input Low Voltage, V_{IL} (Max) CD4049UB	4.5	-	5	1	1	1	1	-	-	1	V
	9	-	10	2	2	2	2	-	-	2	V
	13.5	-	15	2.5	2.5	2.5	2.5	-	-	2.5	V
Input Low Voltage, V_{IL} (Max) CD4050B	0.5	-	5	1.5	1.5	1.5	1.5	-	-	1.5	V
	1	-	10	3	3	3	3	-	-	3	V
	1.5	-	15	4	4	4	4	-	-	4	V
Input High Voltage, V_{IH} Min CD4049UB	0.5	-	5	4	4	4	4	4	-	-	V
	1	-	10	8	8	8	8	8	-	-	V
	1.5	-	15	12.5	12.5	12.5	12.5	12.5	-	-	V

DC Electrical Specifications (Continued)

PARAMETER	TEST CONDITIONS V_O (V)	V_{IN} (V)	V_{CC} (V)	LIMITS AT INDICATED TEMPERATURE (°C) -55	-40	85	125	25 MIN	25 TYP	25 MAX	UNITS
Input High Voltage, V_{IH} Min CD4050B	4.5	-	5	3.5	3.5	3.5	3.5	3.5	-	-	V
	9	-	10	7	7	7	7	7	-	-	V
	13.5	-	15	11	11	11	11	11	-	-	V
Input Current, I_{IN} Max	-	0,18	18	±0.1	±0.1	±1	±1	-	$\pm 10^{-5}$	±0.1	µA

AC Electrical Specifications $T_A = 25^oC$, Input t_r, t_f = 20ns, C_L = 50pF, R_L = 200kΩ

PARAMETER	TEST CONDITIONS V_{IN}	V_{CC}	LIMITS (ALL PACKAGES) TYP	MAX	UNITS
Propagation Delay Time Low to High, t_{PLH} CD4049UB	5	5	60	120	ns
	10	10	32	65	ns
	10	5	45	90	ns
	15	15	25	50	ns
	15	5	45	90	ns
Propagation Delay Time Low to High, t_{PLH} CD4050B	5	5	70	140	ns
	10	10	40	80	ns
	10	5	45	90	ns
	15	15	30	60	ns
	15	5	40	80	ns
Propagation Delay Time High to Low, t_{PHL} CD4049UB	5	5	32	65	ns
	10	10	20	40	ns
	10	5	15	30	ns
	15	15	15	30	ns
	15	5	10	20	ns
Propagation Delay Time High to Low, t_{PHL} CD4050B	5	5	55	110	ns
	10	10	22	55	ns
	10	5	50	100	ns
	15	15	15	30	ns
	15	5	50	100	ns
Transition Time, Low to High, t_{TLH}	5	5	80	160	ns
	10	10	40	80	ns
	15	15	30	60	ns
Transition Time, High to Low, t_{THL}	5	5	30	60	ns
	10	10	20	40	ns
	15	15	15	30	ns
Input Capacitance, C_{IN} CD4049UB	-	-	15	22.5	pF
Input Capacitance, C_{IN} CD4050B	-	-	5	7.5	pF

Typical Performance Curves

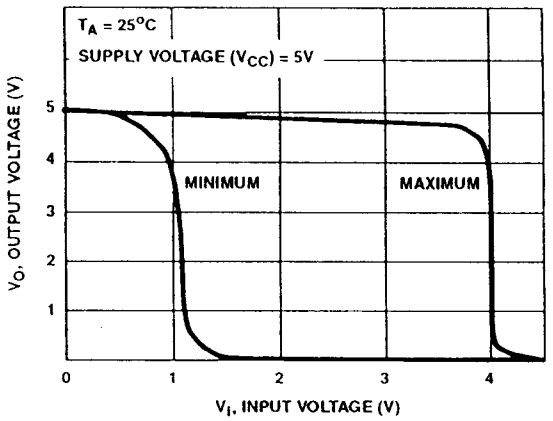


FIGURE 2. MINIMUM AND MAXIMUM VOLTAGE TRANSFER CHARACTERISTICS FOR CD4049UB

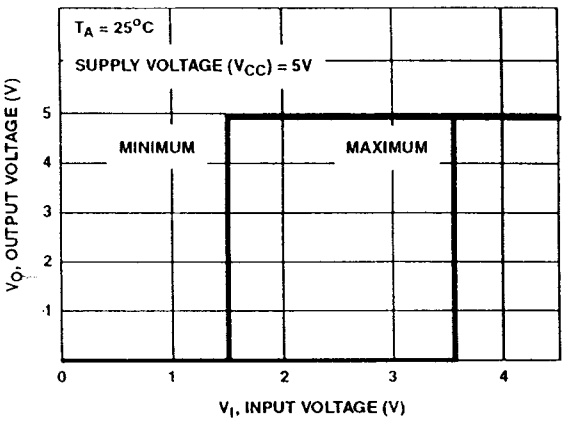


FIGURE 3. MINIMUM AND MAXIMUM VOLTAGE TRANSFER CHARACTERISTICS FOR CD4050B

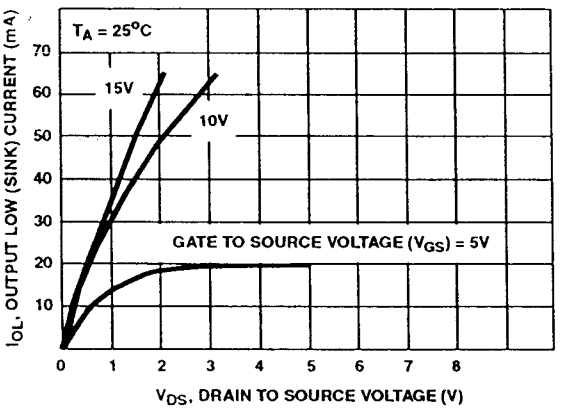


FIGURE 4. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

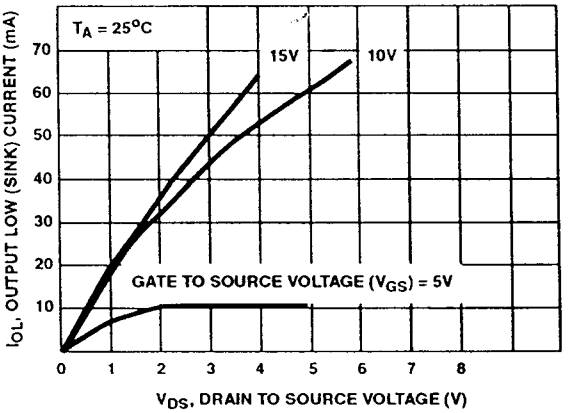


FIGURE 5. MINIMUM OUTPUT LOW (SINK) CURRENT DRAIN CHARACTERISTICS

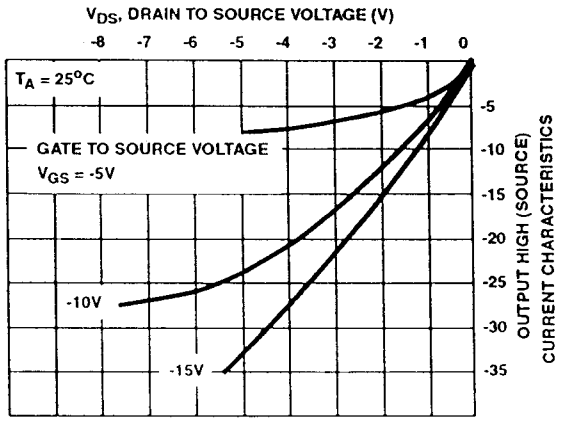


FIGURE 6. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

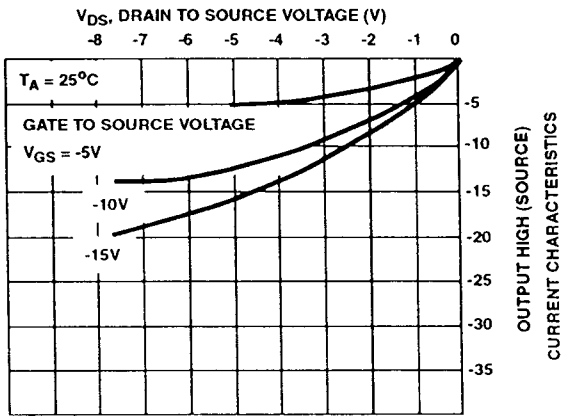


FIGURE 7. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

Typical Performance Curves (Continued)

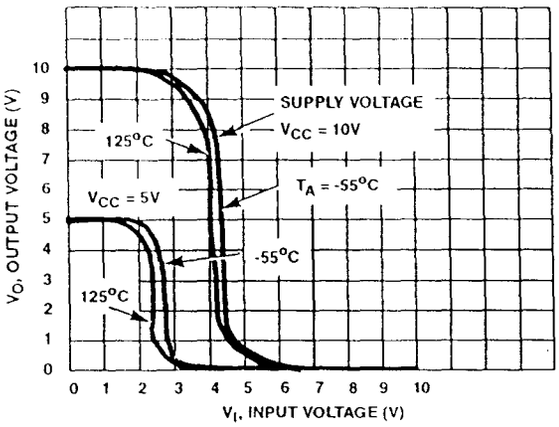


FIGURE 8. TYPICAL VOLTAGE TRANSFER CHARACTERISTICS AS A FUNCTION OF TEMPERATURE FOR CD4049UB

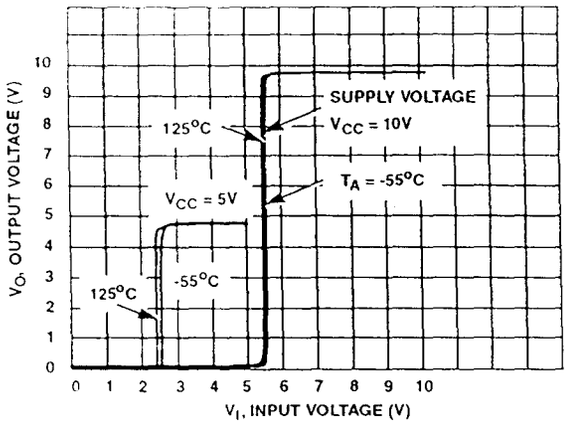


FIGURE 9. TYPICAL VOLTAGE TRANSFER CHARACTERISTICS AS A FUNCTION OF TEMPERATURE FOR CD4050B

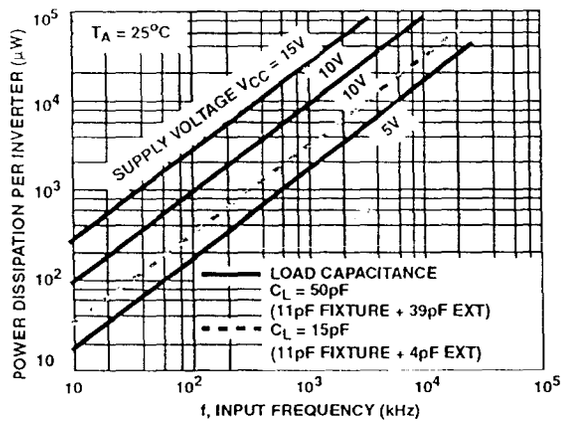


FIGURE 10. TYPICAL POWER DISSIPATION vs FREQUENCY CHARACTERISTICS

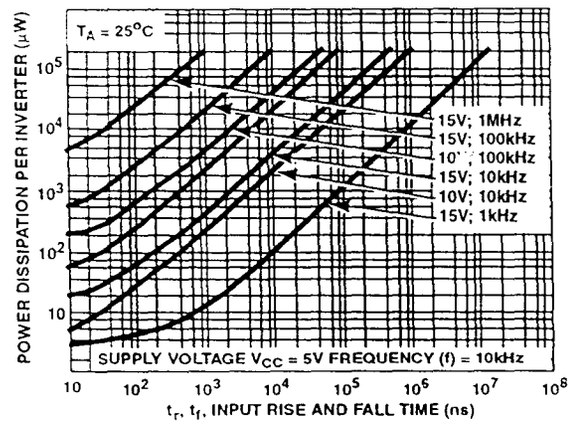


FIGURE 11. TYPICAL POWER DISSIPATION vs INPUT RISE AND FALL TIMES PER INVERTER FOR CD4049UB

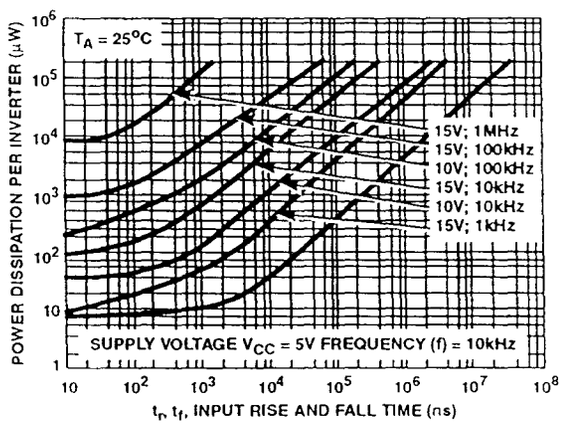


FIGURE 12. TYPICAL POWER DISSIPATION vs INPUT RISE AND FALL TIMES PER INVERTER FOR CD4050B

Test Circuits

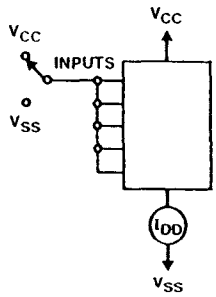
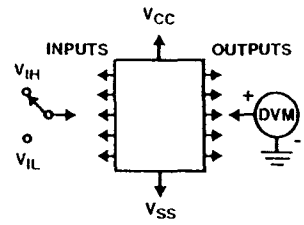
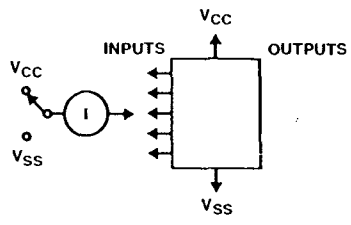


FIGURE 13. QUIESCENT DEVICE CURRENT TEST CIRCUIT



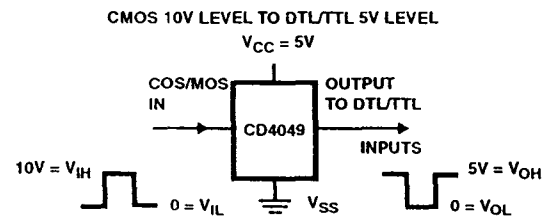
NOTE: Test any one input with other inputs at V_{CC} or V_{SS}.

FIGURE 14. INPUT VOLTAGE TEST CIRCUIT



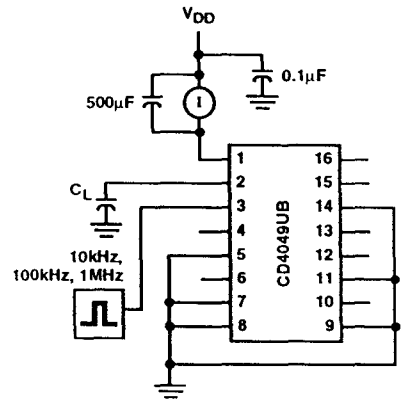
NOTE: Measure inputs sequentially, to both V_{CC} and V_{SS} connect all unused inputs to either V_{CC} or V_{SS}.

FIGURE 15. INPUT CURRENT TEST CIRCUIT



In Terminal - 3, 5, 7, 9, 11, or 14
Out Terminal - 2, 4, 6, 10, 12 or 15
V_{CC} Terminal - 1
V_{SS} Terminal - 8

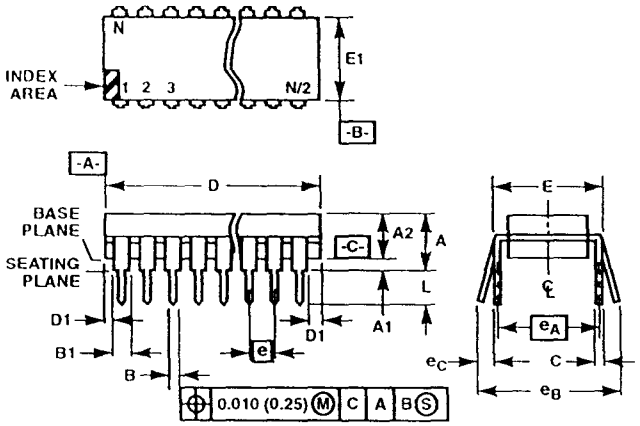
FIGURE 16. LOGIC LEVEL CONVERSION APPLICATION



C_L INCLUDES FIXTURE CAPACITANCE

FIGURE 17. DYNAMIC POWER DISSIPATION TEST CIRCUITS

Dual-In-Line Plastic Packages (PDIP)



NOTES:

1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
4. Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
5. D, D1, and E1 dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
6. E and e_A are measured with the leads constrained to be perpendicular to datum -C-.
7. e_B and e_C are measured at the lead tips with the leads unconstrained. e_C must be zero or greater.
8. B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
9. N is the maximum number of terminal positions.
10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

E16.3 (JEDEC MS-001-BB ISSUE D)
16 LEAD DUAL-IN-LINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8, 10
C	0.008	0.014	0.204	0.355	-
D	0.735	0.775	18.66	19.68	5
D1	0.005	-	0.13	-	5
E	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
e	0.100 BSC		2.54 BSC		-
e_A	0.300 BSC		7.62 BSC		6
e_B	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	16		16		9

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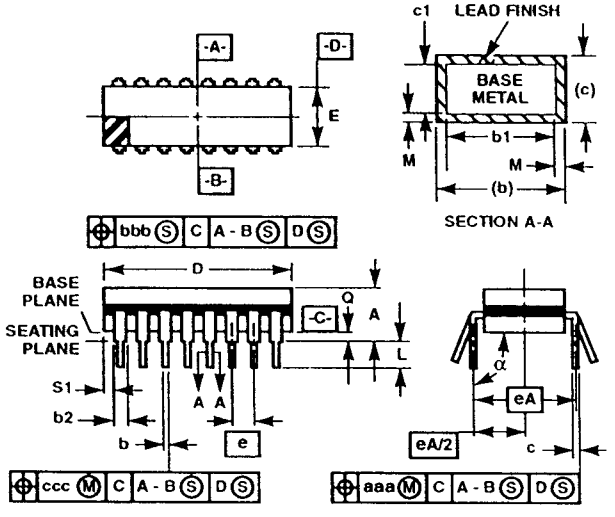
Ceramic Dual-In-Line Frit Seal Packages (CERDIP)



NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
2. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness.
4. Corner leads (1, N, N/2, and N/2+1) may be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b2.
5. This dimension allows for off-center lid, meniscus, and glass overrun.
6. Dimension Q shall be measured from the seating plane to the base plane.
7. Measure dimension S1 at all four corners.
8. N is the maximum number of terminal positions.
9. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
10. Controlling dimension: INCH.

F16.3 MIL-STD-1835 GDIP1-T16 (D-2, CONFIGURATION A)
16 LEAD CERAMIC DUAL-IN-LINE FRIT SEAL PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.200	-	5.08	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
c	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	0.840	-	21.34	5
E	0.220	0.310	5.59	7.87	5
e	0.100 BSC		2.54 BSC		-
eA	0.300 BSC		7.62 BSC		-
eA/2	0.150 BSC		3.81 BSC		-
L	0.125	0.200	3.18	5.08	-
Q	0.015	0.060	0.38	1.52	6
S1	0.005	-	0.13	-	7
α	90°	105°	90°	105°	-
aaa	-	0.015	-	0.38	-
bbb	-	0.030	-	0.76	-
ccc	-	0.010	-	0.25	-
M	-	0.0015	-	0.038	2, 3
N	16		16		8

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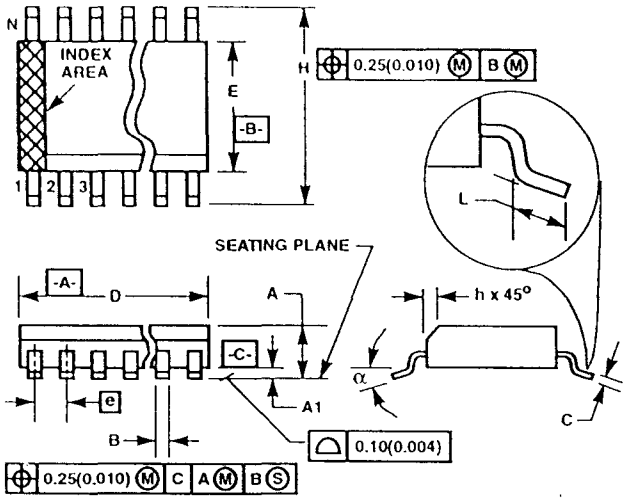
Small Outline Plastic Packages (SOIC)



NOTES:

1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M16.3 (JEDEC MS-013-AA ISSUE C)
16 LEAD WIDE BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0926	0.1043	2.35	2.65	-
A1	0.0040	0.0118	0.10	0.30	-
B	0.013	0.0200	0.33	0.51	9
C	0.0091	0.0125	0.23	0.32	-
D	0.3977	0.4133	10.10	10.50	3
E	0.2914	0.2992	7.40	7.60	4
e	0.050 BSC		1.27 BSC		-
H	0.394	0.419	10.00	10.65	-
h	0.010	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
N	16		16		7
α	0°	8°	0°	8°	-

Rev. 0 12/93

TEXAS INSTRUMENTS

Data sheet acquired from Harris Semiconductor
SCHS076A – Revised March 2002

CD4518B, CD4520B Types

CMOS Dual Up-Counters

High-Voltage Types (20-Volt Rating)

CD4518B Dual BCD Up-Counter
CD4520B Dual Binary Up-Counter

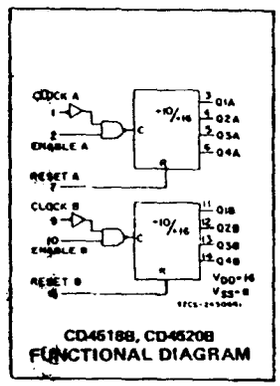
■ CD4518 Dual BCD Up-Counter and CD4520 Dual Binary Up-Counter each consist of two identical, internally synchronous 4-stage counters. The counter stages are D-type flip-flops having interchangeable CLOCK and ENABLE lines for incrementing on either the positive-going or negative-going transition. For single-unit operation the ENABLE input is maintained high and the counter advances on each positive-going transition of the CLOCK. The counters are cleared by high levels on their RESET lines.

The counter can be cascaded in the ripple mode by connecting Q4 to the enable input of the subsequent counter while the CLOCK input of the latter is held low.

The CD4518B and CD4520B types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline package (NSR suffix), and in chip form (H suffix).

Features:

- Medium-speed operation – 6-MHz typical clock frequency at 10 V
- Positive- or negative-edge triggering
- Synchronous internal carry propagation
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature range): 1 V at V_{DD} = 5 V; 2 V at V_{DD} = 10 V; 2.5 V at V_{DD} = 15 V
- 5-V, 10-V, and 15-V parametric ratings
- Standardized, symmetrical output characteristics
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



CD4518B, CD4520B
FUNCTIONAL DIAGRAM

Applications:

- Multistage synchronous counting
- Multistage ripple counting
- Frequency dividers

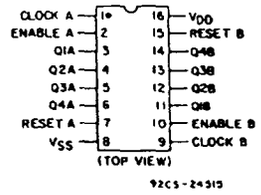
TRUTH TABLE

CLOCK	ENABLE	RESET	ACTION
↑	1	0	Increment Counter
0	↓	0	Increment Counter
↓	X	0	No Change
X	↑	0	No Change
↑	0	0	No Change
1	↓	0	No Change
X	X	1	Q1 thru Q4 = 0

X = Don't Care 1 = High State 0 = Low State

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
(Voltages referenced to V_{SS} Terminal) ..... -0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) ..... -55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) ..... -65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C



CD4518B, CD4520B
TERMINAL ASSIGNMENT

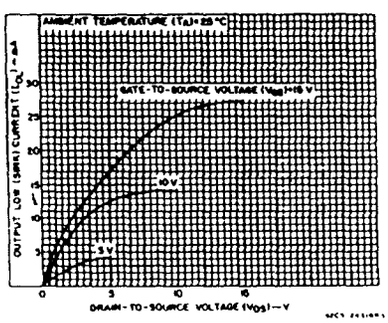


Fig. 1 – Typical output low (sink) current characteristics.

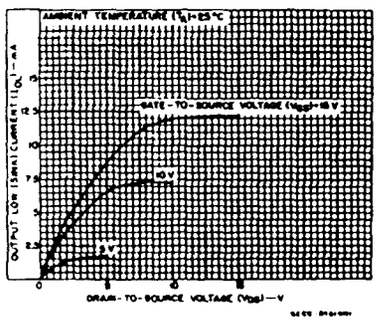


Fig. 2 – Minimum output low (sink) current characteristics.

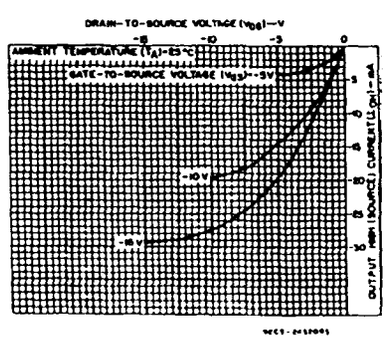


Fig. 3 – Typical output high (source) current characteristics.

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STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
								+25			
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	–	0,5	5	5	5	150	150	–	0.04	5	μA
	–	0,10	10	10	10	300	300	–	0.04	10	
	–	0,15	15	20	20	600	600	–	0.04	20	
	–	0,20	20	100	100	3000	3000	–	0.08	100	
Output Low (Sink) Current I_{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	–	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	–	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	–	
Output High (Source) Current, I_{OH} Min.	4.6	0,5	5	−0.64	−0.61	−0.42	−0.36	−0.51	−1	–	
	2.5	0,5	5	−2	−1.8	−1.3	−1.15	−1.6	−3.2	–	
	9.5	0,10	10	−1.6	−1.5	−1.1	−0.9	−1.3	−2.6	–	
	13.5	0,15	15	−4.2	−4	−2.8	−2.4	−3.4	−6.8	–	
Output Voltage: Low-Level, V_{OL} Max.	–	0,5	5	0.05				–	0	0.05	V
	–	0,10	10	0.05				–	0	0.05	
	–	0,15	15	0.05				–	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	–	0,5	5	4.95				4.95	5	–	
	–	0,10	10	9.95				9.95	10	–	
	–	0,15	15	14.95				14.95	15	–	
Input Low Voltage, V_{IL} Max.	0.5, 4.5	–	5	1.5				—	—	1.5	V
	1, 9	–	10	3				—	—	3	
	1.5,13.5	–	15	4				—	—	4	
Input High Voltage, V_{IH} Min.	0.5, 4.5	–	5	3.5				3.5	—	—	
	1, 9	–	10	7				7	—	—	
	1.5,13.5	–	15	11				11	—	—	
Input Current I_{IN} Max.	–	0,18	18	±0.1	±0.1	±1	±1	–	$\pm 10^{-5}$	±0.1	μA

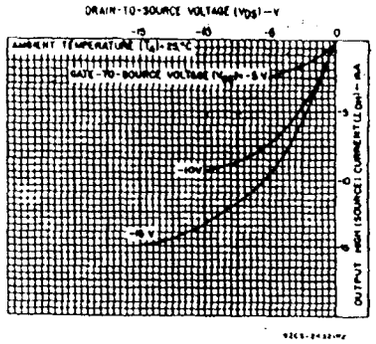


Fig. 4 — Minimum output high (source) current characteristics.

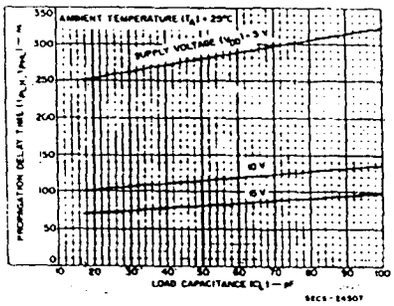


Fig. 5 — Typical propagation delay vs. load capacitance, clock or enable to output.

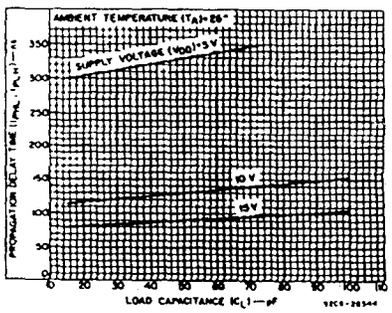


Fig. 6 — Typical propagation delay time vs. load capacitance, reset to output.

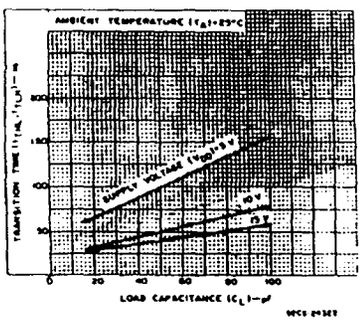


Fig. 7 — Typical transition time vs. load capacitance.

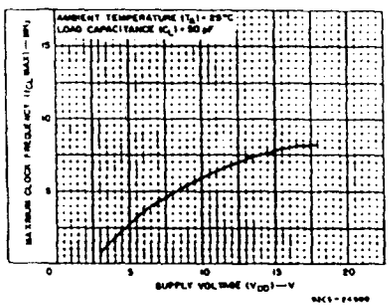


Fig. 8 — Typical maximum-clock-frequency vs. supply voltage.

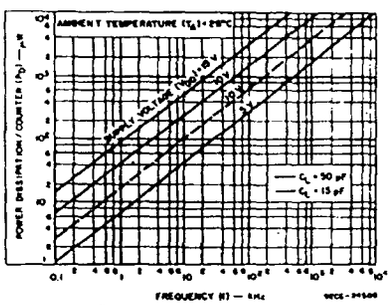


Fig. 9 — Typical power dissipation characteristics.

RECOMMENDED OPERATING CONDITIONS at T_A = 25°C, Except as Noted.
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V_{DD} (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For T_A = Full Package-Temperature Range)		3	18	V
Enable Pulse Width, t_W	5	400	–	ns
	10	200	–	
	15	140	–	
Clock Pulse Width, t_W	5	200	–	ns
	10	100	–	
	15	70	–	
Clock Input Frequency, f_{CL}	5	dc	1.5	MHz
	10		3	
	15		4	
Clock Rise or Fall Time, t_rCL or t_fCL:	5	–	15	μs
	10	–	5	
	15	–	5	
Reset Pulse Width, t_W	5	250	–	ns
	10	110	–	
	15	80	–	

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A=25°C:
Input t_r,t_f=20 ns, C_L=50 pF, R_L=200 KΩ

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS
	V_{DD} V	Min.	Typ.	Max.	
Propagation Delay Time, t_{PHL}, t_{PLH}: Clock or Enable to Output	5	–	280	560	ns
	10	–	115	230	
	15	–	80	160	
Reset to Output	5	–	330	650	
	10	–	130	225	
	15	–	90	170	
Transition Time, t_{THL}, t_{TLH}	5	–	100	200	ns
	10	–	50	100	
	15	–	40	80	
Maximum Clock Input Frequency, f_{CL}	5	1.5	3	–	MHz
	10	3	6	–	
	15	4	8	–	
Minimum Clock Pulse Width, t_W	5		100	200	ns
	10		50	100	
	15		35	70	
Clock Rise or Fall Time, t_r or t_f:	5	–	–	15	μs
	10, 15	–	–	5	
Minimum Reset Pulse Width, t_W	5		125	250	ns
	10		55	110	
	15	–	40	80	
Minimum Enable Pulse Width, t_W	5	–	200	400	ns
	10		100	200	
	15		70	140	
Input Capacitance, C_{IN}	Any Input		5	7.5	pF

TEST CIRCUITS

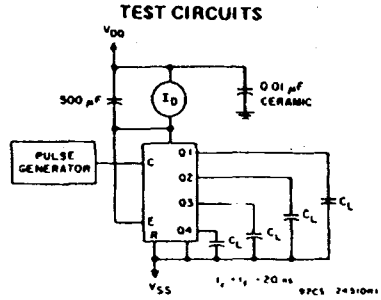


Fig. 10 – Dynamic power dissipation.

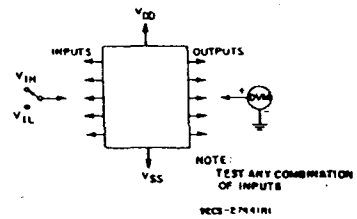


Fig. 11 – Input voltage.

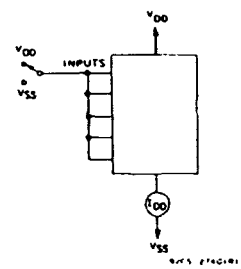


Fig. 12 – Quiescent device current test circuit.

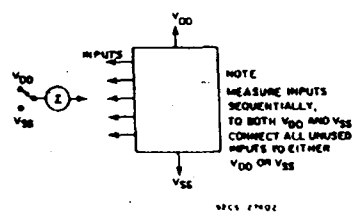


Fig. 13 – Input leakage-current test circuit.

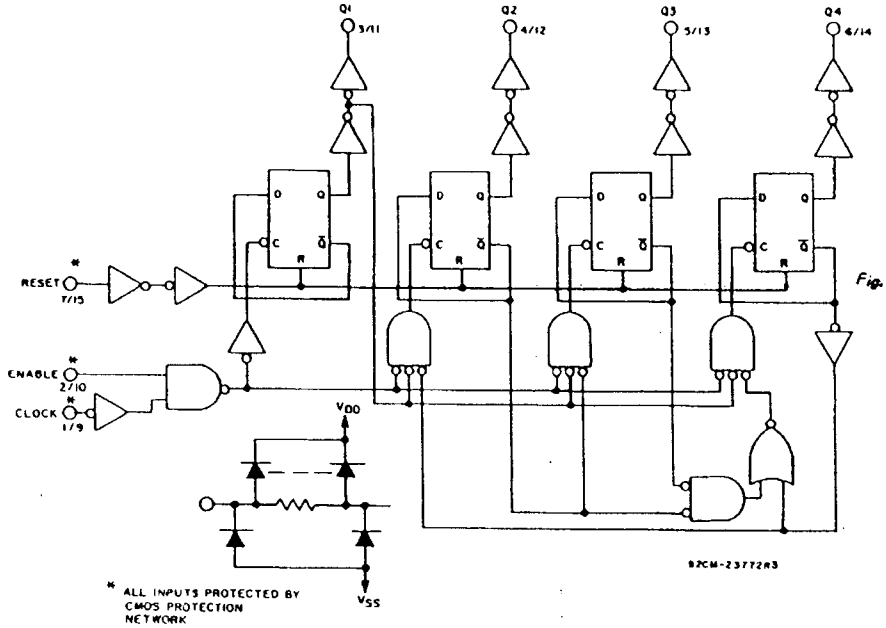


Fig. 14 — Decade counter (CD4518B) logic diagram for one of two identical counters.

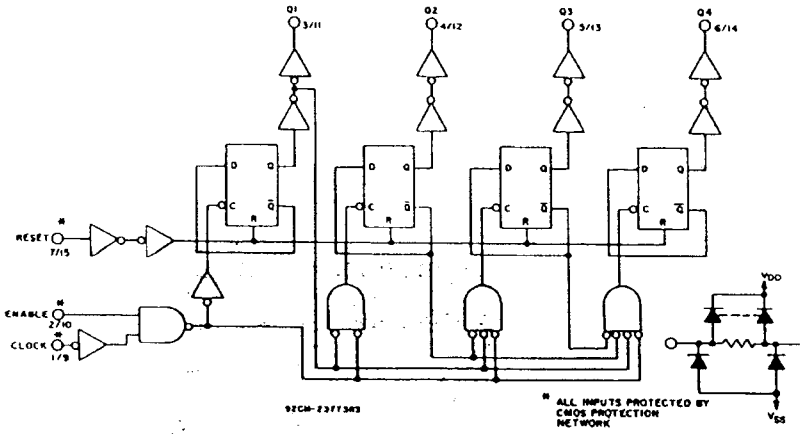


Fig. 15 — Binary counter (CD4520B) logic diagram for one of two identical counters.

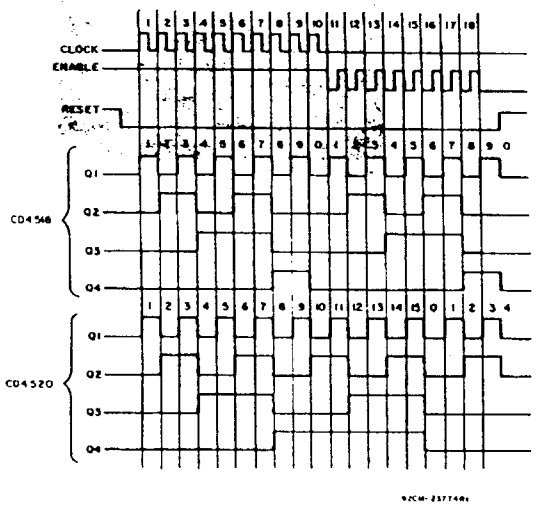


Fig. 16 — Timing diagrams for CD4518B and CD4520B.

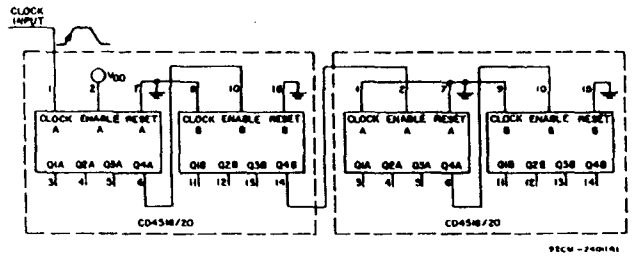
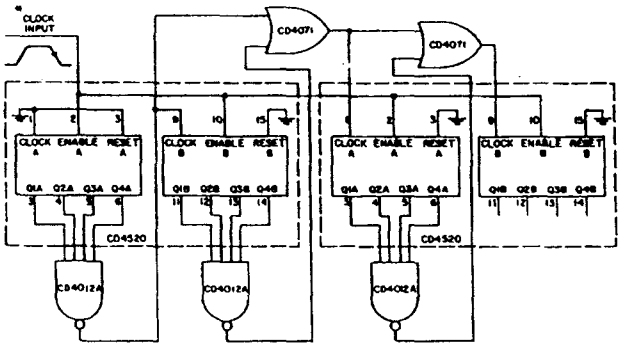
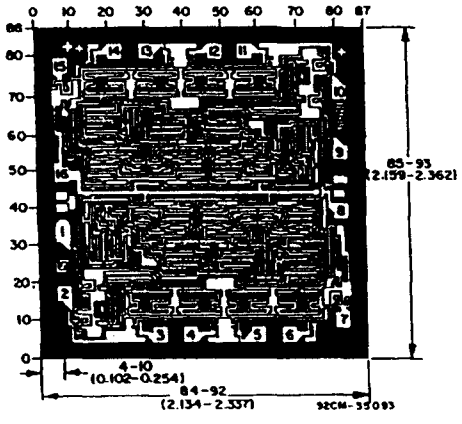


Fig. 17 – Ripple cascading of four counters with positive edge triggering.

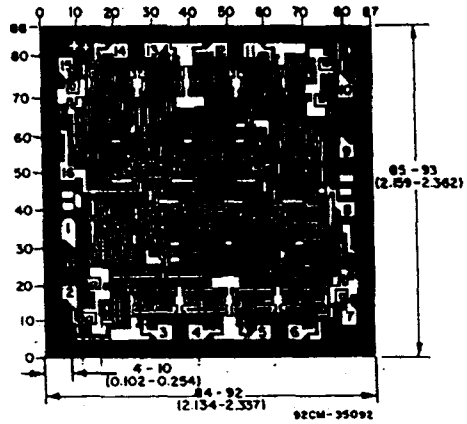


*NOTE:
FOR SYNCHRONOUS CASCADING, THE CLOCK TRANSITION TIME SHOULD BE MADE LESS THAN OR EQUAL TO THE SUM OF THE FIXED PROPAGATION DELAY AT 15 pF AND THE TRANSITION TIME OF THE OUTPUT DRIVER STAGE FOR THE ESTIMATED CAPACITATIVE LOAD.

Fig. 18 – Synchronous cascading of four binary counters with negative edge triggering.



Dimensions and pad layout for CD4518BH chip.



Dimensions and pad layout for CD4520BH chip.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

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